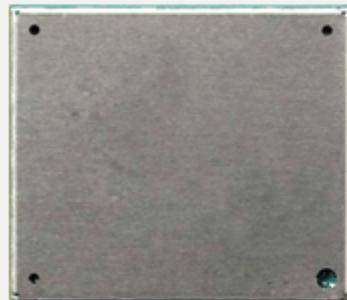


Cinterion[®] PLS8-X/PLS8-V

Hardware Interface Description

Version: 03.017

DocId: PLS8-X_PLS8-V_HD_v03.017



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0 Document History

Preceding document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" v03.016

New document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" Version **v03.017**

| Chapter | What is new |
|---------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3.4 | Revised description of power saving configuration and added Section 3.4.1 , Section 3.4.2 and Section 3.4.1 again. |
| 3.6.1 | Revised section to include remark about data connections. |
| 6.5 | Added comment for CCIN. |
| 7.2.3.1 | Revised Table 29 listing reflow temperature ratings. |
| 7.2.3.2 | Added remark on ramp-down rate. |
| 10.1 | Added note for module label information. |

Preceding document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" v02.510

New document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" Version v03.016

| Chapter | What is new |
|---------------------|---------------------------------------------------------------------------------------------------------------------------------------------------|
| Throughout document | Added information on dead reckoning synchronization line. |
| 1.4 | Removed ECE-R 10 directive from Table 1 . Updated NAPRD version in Table 2 . |
| 2.1 | Added USAT as supported feature. |
| 3.3.4 | Revised section including Figure 7 . |
| 3.4 | Revised description of power save mode and removed previous sections 3.4.1, 3.4.2, and 3.4.2. |
| 3.9 | Shortened section, because PLS8-X and PLS8-V are data only modules, and the module's digital audio interface therefore only supports local tones. |
| 3.13.1 | Revised section to mention VCC μ C in PWR_IND circuit. |
| 3.13.3 | Revised description of remote host wakeup functionality. Updated other sections accordingly. |
| 3.13.6 | New section 700MHz Antenna Switch Control . |
| 5.2 | Revised ratings for VGNSS in Figure 27 . |
| 6.2.1 | Revised temperature allocation model given in Table 18 . |
| 6.5 | Host wakeup functionality added for GPIOs in Table 22 . |
| 7.2.3.1 | Revised ramp down rate given in Table 29 . |
| 9.2 | Revised maximum antenna gain limits - added Table 30 . |

Preceding document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" v02.502

New document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" Version 02.510

| Chapter | What is new |
|---------------------|------------------------------------------------------------------------------|
| Throughout document | Added real time clock (RTC) information. Added VDDL line information. |
| 2.3 | Revised Figure 2 to differentiate between PLS8-X and PLS8-V. |

| | |
|---------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3.5 | New section RTC Backup . |
| 6.5 | Added characteristics for VDDL P line (RTC backup) in Table 22 . |
| 6.6 | Revised current consumption ratings for IDLE mode in Table 24 . Added current consumption rating for GPRS data transfer (4Tx/1Rx @ total mismatch). Revised average GSM/UMTS/LTE current consumption ratings while GNSS is ON. |
| 7.2.3.1 | Revised description for average ramp up and ramp down rates in Table 29 . |

New document: "Cinterion® PLS8-X/PLS8-V Hardware Interface Description" Version 02.502

| Chapter | What is new |
|---------|-------------------------|
| -- | Initial document setup. |

1 Introduction

The document¹ describes the hardware of the two Cinterion® modules variants PLS8-V and PLS8-X, designed to connect to a cellular device application and the air interface. It helps you quickly retrieve interface specifications, electrical and mechanical details and information on the requirements to be considered for integrating further components.

The product variants differ in their radio access technology support:

- PLS8-X is available for operation in LTE, UMTS and GSM radio networks - for supported frequency bands please refer to [Section 2.1](#). Connected to this, the module has two separate firmware images on board that can be activated based on the used (U)SIM card. Employing the module's two (U)SIM interfaces, it is thus possible to switch between firmware images on the fly - making PLS8-X a multi carrier/provider module.
- PLS8-V in contrast is available for operation in LTE radio networks only - for supported frequency bands please refer to [Section 2.1](#). It has only a single firmware image on board that can be activated by (U)SIM card - making it a single carrier/provider module.

If not otherwise mentioned, this document applies to both product variants. Where necessary a note is made to differentiate between the variants.

1.1 Supported Products

This document applies to the following Gemalto M2M products:

- Cinterion® PLS8-V module
- Cinterion® PLS8-X module

1.2 Related Documents

- [1] AT Command Set for your Gemalto M2M product
 [2] Release Notes for your Gemalto M2M product
 [3] Application Note 48: SMT Module Integration
 [4] Universal Serial Bus Specification Revision 2.0, April 27, 2000

1.3 Terms and Abbreviations

| Abbreviation | Description |
|--------------|--------------------------------------------|
| ANSI | American National Standards Institute |
| ARP | Antenna Reference Point |
| CE | Conformité Européene (European Conformity) |
| CS | Coding Scheme |
| CS | Circuit Switched |
| CSD | Circuit Switched Data |
| DCS | Digital Cellular System |

¹ The document is effective only if listed in the appropriate Release Notes as part of the technical documentation delivered with your Gemalto M2M product.

1.3 Terms and Abbreviations

| Abbreviation | Description |
|--------------|-------------------------------------------------|
| DL | Download |
| dnu | Do not use |
| DRX | Discontinuous Reception |
| DSB | Development Support Board |
| DTX | Discontinuous Transmission |
| EDGE | Enhanced Data rates for GSM Evolution |
| EGSM | Extended GSM |
| EMC | Electromagnetic Compatibility |
| ESD | Electrostatic Discharge |
| ETS | European Telecommunication Standard |
| ETSI | European Telecommunications Standards Institute |
| FCC | Federal Communications Commission (U.S.) |
| FDD | Frequency Division Duplex |
| GPRS | General Packet Radio Service |
| GSM | Global Standard for Mobile Communications |
| HiZ | High Impedance |
| HSDPA | High Speed Downlink Packet Access |
| I/O | Input/Output |
| IMEI | International Mobile Equipment Identity |
| ISO | International Standards Organization |
| ITU | International Telecommunications Union |
| kbps | kbits per second |
| LCI | Low Current Indicator |
| LED | Light Emitting Diode |
| LGA | Land Grid Array |
| LTE | Long term evolution |
| MBB | Moisture barrier bag |
| Mbps | Mbits per second |
| MCS | Modulation and Coding Scheme |
| MIMO | Multiple Input Multiple Output |
| MLCC | Multi Layer Ceramic Capacitor |
| MO | Mobile Originated |
| MS | Mobile Station, also referred to as TE |
| MSL | Moisture Sensitivity Level |
| MT | Mobile Terminated |
| nc | Not connected |

1.3 Terms and Abbreviations

| Abbreviation | Description |
|--------------|-------------------------------------------------------------|
| NTC | Negative Temperature Coefficient |
| PCB | Printed Circuit Board |
| PCL | Power Control Level |
| PCS | Personal Communication System, also referred to as GSM 1900 |
| PD | Pull Down resistor |
| PDU | Protocol Data Unit |
| PS | Packet Switched |
| PSK | Phase Shift Keying |
| PU | Pull Up resistor |
| QAM | Quadrature Amplitude Modulation |
| R&TTE | Radio and Telecommunication Terminal Equipment |
| RF | Radio Frequency |
| rfu | Reserved for future use |
| ROPR | Radio Output Power Reduction |
| RTC | Real Time Clock |
| Rx | Receive Direction |
| SAR | Specific Absorption Rate |
| SELV | Safety Extra Low Voltage |
| SIM | Subscriber Identification Module |
| SMD | Surface Mount Device |
| SMS | Short Message Service |
| SMT | Surface Mount Technology |
| SRAM | Static Random Access Memory |
| SRB | Signalling Radio Bearer |
| TE | Terminal Equipment |
| TPC | Transmit Power Control |
| TS | Technical Specification |
| Tx | Transmit Direction |
| UL | Upload |
| UMTS | Universal Mobile Telecommunications System |
| URC | Unsolicited Result Code |
| USB | Universal Serial Bus |
| UICC | USIM Integrated Circuit Card |
| USIM | UMTS Subscriber Identification Module |
| WB-AMR | Wideband Adaptive Multirate |
| WCDMA | Wideband Code Division Multiple Access |

1.4 Regulatory and Type Approval Information

1.4 Regulatory and Type Approval Information

1.4.1 Directives and Standards

PLS8-X/PLS8-V has been designed to comply with the directives and standards listed below.

It is the responsibility of the application manufacturer to ensure compliance of the final product with all provisions of the applicable directives and standards as well as with the technical specifications provided in the "PLS8-X/PLS8-V Hardware Interface Description".¹

Table 1: Directives

| | | |
|--------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| 2002/95/EC (RoHS 1) 2011/65/EC (RoHS 2) | Directive of the European Parliament and of the Council of 27 January 2003 (and revised on 8 June 2011) on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS) |  |
|--------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|

Table 2: Standards of North American type approval

| | | |
|------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|
| CFR Title 47 | Code of Federal Regulations, Part 22, Part 24 and Part 27; US Equipment Authorization FCC | |
| OET Bulletin 65 (Edition 97-01) | Evaluating Compliance with FCC Guidelines for Human Exposure to Radiofrequency Electromagnetic Fields | |
| UL 60 950-1 | Product Safety Certification (Safety requirements) |  |
| NAPRD.03 V5.24 | Overview of PCS Type certification review board Mobile Equipment Type Certification and IMEI control PCS Type Certification Review board (PTCRB) | |
| RSS130, RSS132, RSS133, RSS139 | Canadian Standard | |

Table 3: Requirements of quality

| | |
|--------------|-----------------------|
| IEC 60068 | Environmental testing |
| DIN EN 60529 | IP codes |

¹ Manufacturers of applications which can be used in the US shall ensure that their applications have a PTCRB approval. For this purpose they can refer to the PTCRB approval of the respective module.

1.4 Regulatory and Type Approval Information

Table 4: Standards of the Ministry of Information Industry of the People’s Republic of China

| | |
|-----------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| SJ/T 11363-2006 | “Requirements for Concentration Limits for Certain Hazardous Substances in Electronic Information Products” (2006-06). |
| SJ/T 11364-2006 | <p>“Marking for Control of Pollution Caused by Electronic Information Products” (2006-06).</p> <p>According to the “Chinese Administration on the Control of Pollution caused by Electronic Information Products” (ACPEIP) the EPUP, i.e., Environmental Protection Use Period, of this product is 20 years as per the symbol shown here, unless otherwise marked. The EPUP is valid only as long as the product is operated within the operating limits described in the Hardware Interface Description.</p> <p>Please see Table 5 for an overview of toxic or hazardous substances or elements that might be contained in product parts in concentrations above the limits defined by SJ/T 11363-2006.</p> |



Table 5: Toxic or hazardous substances or elements with defined concentration limits

| 部件名称 Name of the part | 有毒有害物质或元素 Hazardous substances | | | | | |
|-------------------------------------------|--------------------------------|-----------|-----------|-----------------|---------------|-----------------|
| | 铅 (Pb) | 汞 (Hg) | 镉 (Cd) | 六价铬 (Cr(VI)) | 多溴联苯 (PBB) | 多溴二苯醚 (PBDE) |
| 金属部件 (Metal Parts) | ○ | ○ | ○ | ○ | ○ | ○ |
| 电路模块 (Circuit Modules) | X | ○ | ○ | ○ | ○ | ○ |
| 电缆及电缆组件 (Cables and Cable Assemblies) | ○ | ○ | ○ | ○ | ○ | ○ |
| 塑料和聚合物部件 (Plastic and Polymeric parts) | ○ | ○ | ○ | ○ | ○ | ○ |

O:
表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下。
Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X:
表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。
Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part *might exceed* the limit requirement in SJ/T11363-2006.

1.4.2 SAR requirements specific to portable mobiles

Mobile phones, PDAs or other portable transmitters and receivers incorporating a GSM module must be in accordance with the guidelines for human exposure to radio frequency energy. This requires the Specific Absorption Rate (SAR) of portable PLS8-X/PLS8-V based applications to be evaluated and approved for compliance with national and/or international regulations.

Since the SAR value varies significantly with the individual product design manufacturers are advised to submit their product for approval if designed for portable use. For US markets the relevant directives are mentioned below. It is the responsibility of the manufacturer of the final product to verify whether or not further standards, recommendations or directives are in force outside these areas.

Products intended for sale on US markets

ES 59005/ANSI C95.1 Considerations for evaluation of human exposure to electromagnetic fields (EMFs) from mobile telecommunication equipment (MTE) in the frequency range 30MHz - 6GHz

IMPORTANT:

Manufacturers of portable applications based on PLS8-X/PLS8-V modules are required to have their final product certified and apply for their own FCC Grant and Industry Canada Certificate related to the specific portable mobile.

1.4 Regulatory and Type Approval Information

1.4.3 SELV Requirements

The power supply connected to the PLS8-X/PLS8-V module shall be in compliance with the SELV requirements defined in EN 60950-1.

1.4.4 Safety Precautions

The following safety precautions must be observed during all phases of the operation, usage, service or repair of any cellular terminal or mobile incorporating PLS8-X/PLS8-V. Manufacturers of the cellular terminal are advised to convey the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. Failure to comply with these precautions violates safety standards of design, manufacture and intended use of the product. Gemalto M2M assumes no liability for customer's failure to comply with these precautions.

| | |
|-------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|  | <p>When in a hospital or other health care facility, observe the restrictions on the use of mobiles. Switch the cellular terminal or mobile off, if instructed to do so by the guidelines posted in sensitive areas. Medical equipment may be sensitive to RF energy.</p> <p>The operation of cardiac pacemakers, other implanted medical equipment and hearing aids can be affected by interference from cellular terminals or mobiles placed close to the device. If in doubt about potential danger, contact the physician or the manufacturer of the device to verify that the equipment is properly shielded. Pacemaker patients are advised to keep their hand-held mobile away from the pacemaker, while it is on.</p> |
|  | <p>Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it cannot be switched on inadvertently. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communications systems. Failure to observe these instructions may lead to the suspension or denial of cellular services to the offender, legal action, or both.</p> |
|  | <p>Do not operate the cellular terminal or mobile in the presence of flammable gases or fumes. Switch off the cellular terminal when you are near petrol stations, fuel depots, chemical plants or where blasting operations are in progress. Operation of any electrical equipment in potentially explosive atmospheres can constitute a safety hazard.</p> |
|  | <p>Your cellular terminal or mobile receives and transmits radio frequency energy while switched on. Remember that interference can occur if it is used close to TV sets, radios, computers or inadequately shielded equipment. Follow any special regulations and always switch off the cellular terminal or mobile wherever forbidden, or when you suspect that it may cause interference or danger.</p> |
|  | <p>IMPORTANT! Cellular terminals or mobiles operate using radio signals and cellular networks. Because of this, connection cannot be guaranteed at all times under all conditions. Therefore, you should never rely solely upon any wireless device for essential communications, for example emergency calls.</p> <p>Remember, in order to make or receive calls, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength.</p> <p>Some networks do not allow for emergency calls if certain network services or phone features are in use (e.g. lock functions, fixed dialing etc.). You may need to deactivate those features before you can make an emergency call.</p> <p>Some networks require that a valid SIM card be properly inserted in the cellular terminal or mobile.</p> |

2 Product Concept

2.1 Key Features at a Glance

| Feature | Implementation |
|-------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| General | |
| Frequency bands | PLS8-X: GSM/GPRS/EDGE: Quad band, 850/900/1800/1900MHz UMTS/HSPA+: Triple band, 850 (BdV) / AWS (BdIV) / 1900MHz (BdII) LTE: Five band, 700 (Bd13) / 700 (Bd17) / 850 (Bd5) / AWS (Bd4) / 1900MHz (Bd2) PLS8-V: LTE: Triple band, 700 (Bd13) / AWS (Bd4) / 1900MHz (Bd2) |
| GSM class | Small MS |
| Output power (according to Release 99) | Class 4 (+33dBm ±2dB) for EGSM850 Class 4 (+33dBm ±2dB) for EGSM900 Class 1 (+30dBm ±2dB) for GSM1800 Class 1 (+30dBm ±2dB) for GSM1900 Class E2 (+27dBm ± 3dB) for GSM 850 8-PSK Class E2 (+27dBm ± 3dB) for GSM 900 8-PSK Class E2 (+26dBm +3 /-4dB) for GSM 1800 8-PSK Class E2 (+26dBm +3 /-4dB) for GSM 1900 8-PSK Class 3 (+24dBm +1/-3dB) for UMTS 1900,WCDMA FDD BdII Class 3 (+24dBm +1/-3dB) for UMTS AWS, WCDMA FDD BdIV Class 3 (+24dBm +1/-3dB) for UMTS 850, WCDMA FDD BdV |
| Output power (according to Release 8) | Class 3 (+23dBm +-2dB) for LTE 1900, LTE FDD Bd2 Class 3 (+23dBm +-2dB) for LTE AWS, LTE FDD Bd4 Class 3 (+23dBm +-2dB) for LTE 850, LTE FDD Bd5 Class 3 (+23dBm +-2dB) for LTE 700, LTE FDD Bd13 Class 3 (+23dBm +-2dB) for LTE 700, LTE FDD Bd17 |
| Power supply | $3.3V \leq V_{BATT+} \leq 4.2V$ |
| Operating temperature (board temperature) | Normal operation: -30°C to +85°C Extended operation: -40°C to +95°C |
| Physical | Dimensions: 33mm x 29mm x 2.95mm Weight: approx. 4.5g |
| RoHS | All hardware components fully compliant with EU RoHS Directive |
| LTE features | |
| 3GPP Release 9 | UE CAT 3 supported DL 100Mbps, UL 50Mbps 2x2 MIMO in DL direction |
| HSPA features | |
| 3GPP Release 8 | UE CAT. 14, 24 DC-HSPA+ – DL 42Mbps HSUPA – UL 5.76Mbps Compressed mode (CM) supported according to 3GPP TS25.212 |

2.1 Key Features at a Glance

| Feature | Implementation |
|-----------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| UMTS features | |
| 3GPP Release 8 | PS data rate – 384 kbps DL / 384 kbps UL |
| GSM / GPRS / EGPRS features | |
| Data transfer | GPRS: <ul style="list-style-type: none"> • Multislot Class 12 • Mobile Station Class B • Coding Scheme 1 – 4 EGPRS: <ul style="list-style-type: none"> • Multislot Class 12 • EDGE E2 power class for 8 PSK • Downlink coding schemes – CS 1-4, MCS 1-9 • Uplink coding schemes – CS 1-4, MCS 1-9 • SRB loopback and test mode B • 8-bit, 11-bit RACH • 1 phase/2 phase access procedures • Link adaptation and IR • NACC, extended UL TBF • Mobile Station Class B |
| SMS | Point-to-point MT and MO Cell broadcast Text and PDU mode |
| Software | |
| AT commands | Hayes, 3GPP TS 27.007 and 27.005, and proprietary Gemalto M2M commands |
| Firmware update | Generic update from host application over USB and ASC0 |
| U/SIM application toolkit | USAT letter c; with BIP |
| GNSS Features | |
| Protocol | NMEA |
| Modes | Standalone GNSS Assisted GNSS - Control plane - E911 - User plane - gpsOneXTRA™ |
| General | Power saving modes Power supply for active antenna |
| Interfaces | |
| Module interface | Surface mount device with solderable connection pads (SMT application interface). Land grid array (LGA) technology ensures high solder joint reliability and provides the possibility to use an optional module mounting socket. For more information on how to integrate SMT modules see also [3] . This application note comprises chapters on module mounting and application layout issues as well as on additional SMT application development equipment. |
| Antenna | 50Ω. GSM/UMTS/LTE main antenna, UMTS/LTE Diversity/MIMO antenna, (active/passive) GNSS antenna |

2.1 Key Features at a Glance

| Feature | Implementation |
|---------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| USB | USB 2.0 High Speed (480Mbit/s) device interface |
| Serial interface | ASC0: <ul style="list-style-type: none"> 8-wire modem interface with status and control lines, unbalanced, asynchronous Adjustable baud rate of 115,200bps to 921,600bps Supports RTS0/CTS0 hardware flow control |
| UICC interface | 2 UICC interfaces (switchable) Supported chip cards: UICC/SIM/USIM 3V, 1.8V |
| Audio | 1 digital interface (PCM or I ² S) |
| Status | Signal line to indicate network connectivity state |
| RING0 | Signal line to indicate incoming calls and other types of URCs |
| Power on/off, Reset | |
| Power on/off | Switch-on by hardware signal IGT Switch-off by AT command (AT^SMSO) or IGT Automatic switch-off in case of critical temperature or voltage conditions |
| Reset | Orderly shutdown and reset by AT command |
| Emergency-off | Emergency-off by hardware signal EMERG_OFF if IGT is not active |
| Special Features | |
| Antenna | SAIC (Single Antenna Interference Cancellation) / DARP (Downlink Advanced Receiver Performance) Rx Diversity (receiver type 3i - 64-QAM) / MIMO |
| GPIO | 10 I/O pins of the application interface programmable as GPIO. GPIOs can be configured as low current indicator (LCI). GPIO1 can be configured as dead reckoning synchronization signal. GPIO2 can be configured as 700MHz antenna switch control signal. GPIOs can be configured as remote host wakeup lines. Programming is done via AT commands. |
| ADC inputs | Analog-to-Digital Converter with three unbalanced analog inputs. |
| Evaluation kit | |
| Evaluation module | PLS8-X/PLS8-V module soldered onto a dedicated PCB that can be connected to an adapter in order to be mounted onto the DSB75. |
| DSB75 | DSB75 Development Support Board designed to test and type approve Gemalto M2M modules and provide a sample configuration for application engineering. A special adapter is required to connect the PLS8-X/PLS8-V evaluation module to the DSB75. |

2.2 PLS8-X/PLS8-V System Overview

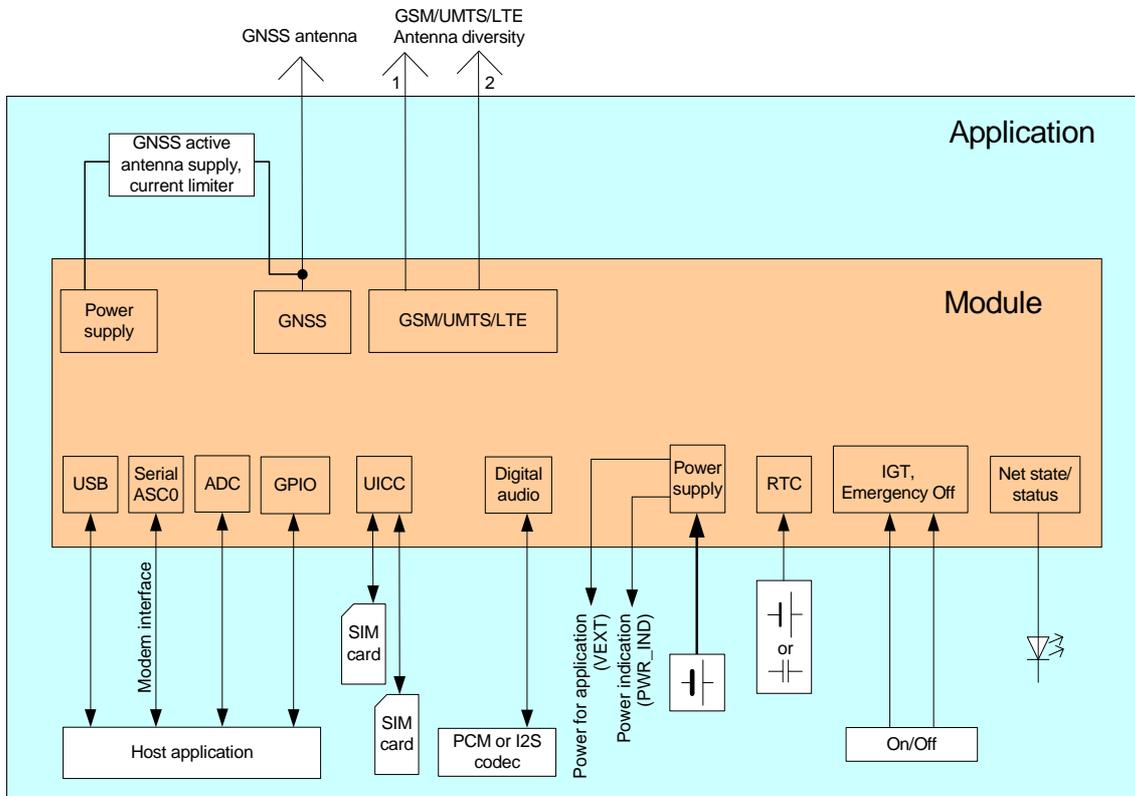


Figure 1: PLS8-X/PLS8-V system overview

2.3 Circuit Concept

2.3 Circuit Concept

Figure 2 shows a block diagram of the PLS8-X/PLS8-V module and illustrates the major functional components:

Baseband block:

- GSM/UMTS/LTE controller/transceiver/power supply
- Stacked Flash/RAM memory with multiplexed address data bus
- Application interface (SMT with connecting pads)

RF section:

- RF transceiver
- RF power amplifier/frontend
- RF filter
- GNSS receiver/Front end
- Antenna pad

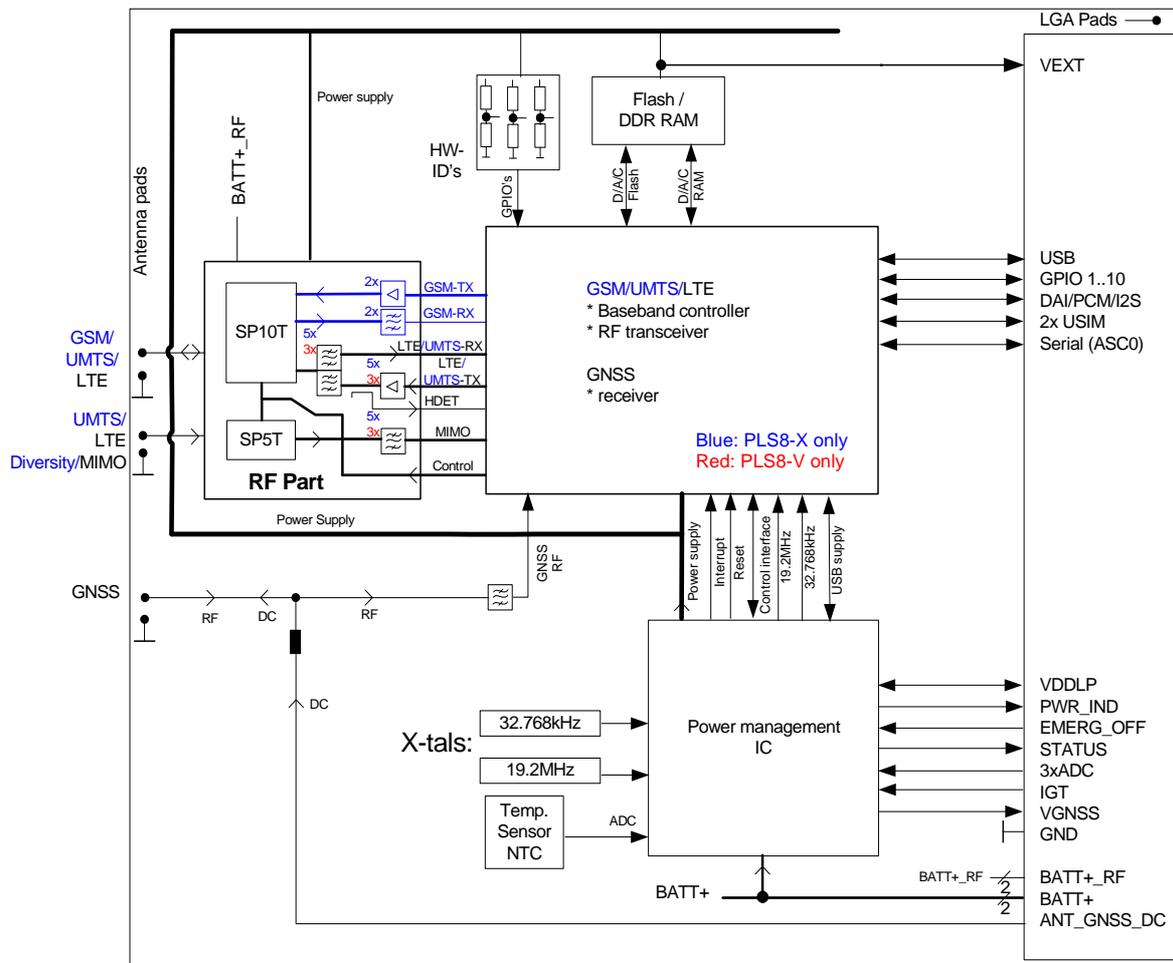


Figure 2: PLS8-X/PLS8-V block diagram

3 Application Interface

PLS8-X/PLS8-V is equipped with an SMT application interface (LGA pads) that connects to the external application. The host interface incorporates several sub-interfaces described in the following sections:

- Operating modes - see [Section 3.1](#)
- Power supply - see [Section 3.2](#)
- RTC backup - see [Section 3.5](#)
- Serial interface USB - see [Section 3.6](#)
- Serial interface ASC0 - [Section 3.7](#)
- UICC/SIM/USIM interface - see [Section 3.8](#)
- Digital audio interface (PCM or I²S) - see [Section 3.9](#)
- ADC interface - [Section 3.11](#)
- GPIO interface - [Section 3.12](#)
- Control and status lines: PWR_IND, STATUS, RING0, STATUS, LCI - see [Section 3.13](#)

3.1 Operating Modes

The table below briefly summarizes the various operating modes referred to in the following chapters.

Table 6: Overview of operating modes

| Mode | Function |
|------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Normal operation | GSM / GPRS / UMTS / HSPA / LTE SLEEP Power saving set automatically when no call is in progress and the USB connection is detached and no active communication via ASC0. Also, the GNSS active antenna mode has to be turned off or set to "auto". |
| | GSM / GPRS / UMTS / HSPA / LTE IDLE Power saving disabled or an USB connection active, but no data transfer in progress. |
| | GPRS DATA GPRS data transfer in progress. Power consumption depends on network settings (e.g. power control level), uplink / downlink data rates and GPRS configuration (e.g. used multislot settings). |
| | EGPRS DATA EGPRS data transfer in progress. Power consumption depends on network settings (e.g. power control level), uplink / downlink data rates and EGPRS configuration (e.g. used multislot settings). |
| | UMTS DATA UMTS data transfer in progress. Power consumption depends on network settings (e.g. TPC Pattern) and data transfer rate. |
| | HSPA DATA HSPA data transfer in progress. Power consumption depends on network settings (e.g. TPC Pattern) and data transfer rate. |
| | LTE DATA LTE data transfer in progress. Power consumption depends on network settings (e.g. TPC Pattern) and data transfer rate. |
| Power Down | Normal shutdown after sending the AT^SMSO command. Only a voltage regulator is active for powering the RTC. Software is not active. Interfaces are not accessible. Operating voltage (connected to BATT+) remains applied. |
| Airplane mode | Airplane mode shuts down the radio part of the module, causes the module to log off from the GSM/GPRS network and disables all AT commands whose execution requires a radio connection. Airplane mode can be controlled by AT command (see [1]). |

3.2 Power Supply

PLS8-X/PLS8-V needs to be connected to a power supply at the SMT application interface - 4 lines BATT+, and GND. There are two separate voltage domains for BATT+:

- BATT+_RF with 2 lines for the RF power amplifier supply
- BATT+ with 2 lines for the general power management.

The main power supply from an external application has to be a single voltage source and has to be expanded to two sub paths (star structure). Each voltage domain must be decoupled by application with low ESR capacitors ($\geq 47\mu\text{F}$ MLCC @ BATT+; $\geq 4 \times 47\mu\text{F}$ MLCC @ BATT+_RF) as close as possible to LGA pads. [Figure 3](#) shows a sample circuit for decoupling capacitors for BATT+.

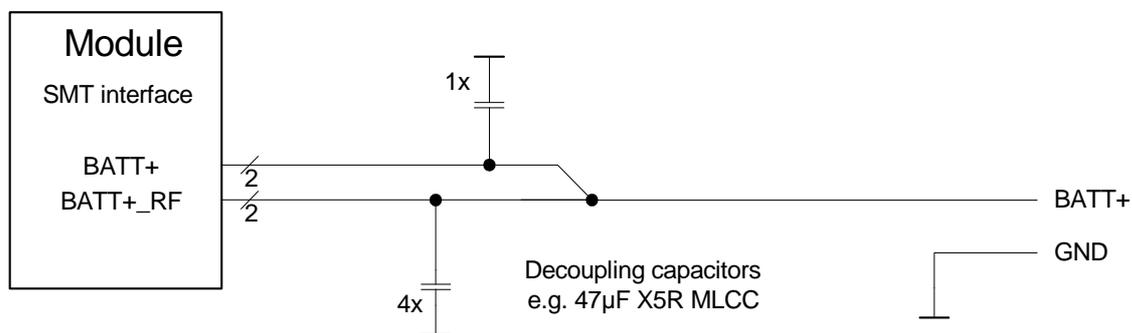


Figure 3: Decoupling capacitor(s) for BATT+

In addition, the VDDL P pad may be connected to an external capacitor or a battery to backup the RTC (see [Section 3.5](#)). Please note that for proper module startup the voltage at BATT+ should be higher than at VDDL P.

The power supply of PLS8-X/PLS8-V must be able to provide the peak current during the uplink transmission.

All key functions for supplying power to the device are handled by the power management IC. It provides the following features:

- Stabilizes the supply voltages for the baseband using switching regulators and low drop linear voltage regulators.
- Switches the module's power voltages for the power-up and -down procedures.
- Delivers, across the VEXT line, a regulated voltage for an external application.
- LDO to provide SIM power supply.

3.2.1 Minimizing Power Losses

When designing the power supply for your application please pay specific attention to power losses. Ensure that the input voltage $V_{\text{BATT+}}$ never drops below 3.3V on the PLS8-X/PLS8-V board, not even in a transmit burst where current consumption can rise to typical peaks of 2A. It should be noted that PLS8-X/PLS8-V switches off when exceeding these limits. Any voltage drops that may occur in a transmit burst should not exceed 400mV to ensure the expected RF performance in 2G networks.

The module switches off if the minimum battery voltage (V_{BATTmin}) is reached.

Example:

$V_{\text{Imin}} = 3.3\text{V}$

$D_{\text{max}} = 0.4\text{V}$

$V_{\text{BATTmin}} = V_{\text{Imin}} + D_{\text{max}}$

$V_{\text{BATTmin}} = 3.3\text{V} + 0.4\text{V} = 3.7\text{V}$

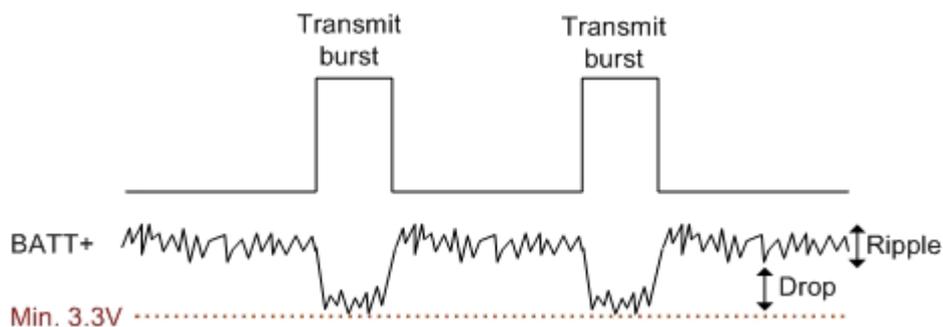


Figure 4: Power supply limits during transmit burst

3.2.2 Monitoring Power Supply by AT Command

To monitor the supply voltage you can use the `AT^SBV` command which returns the averaged value related to BATT+ and GND at the SMT application interface.

The module continuously measures the voltage at intervals depending on the operating mode of the RF interface. The duration of measuring ranges from 0.5 seconds in DATA mode to 50 seconds when PLS8-X/PLS8-V is in Limited Service (deregistered). The displayed voltage (in mV) is averaged over the last measuring period before the `AT^SBV` command was executed.

3.3 Power-Up / Power-Down Scenarios

In general, be sure not to turn on PLS8-X/PLS8-V while it is beyond the safety limits of voltage and temperature stated in [Section 6.1](#). PLS8-X/PLS8-V immediately switches off after having started and detected these inappropriate conditions. In extreme cases this can cause permanent damage to the module.

3.3.1 Turn on PLS8-X/PLS8-V

When the PLS8-X/PLS8-V module is in Power Down mode, it can be started to Normal mode by driving the IGT (ignition) line to ground. It is recommended to use an open drain/collector driver to avoid current flowing into this signal line. Pulling this signal low triggers a power-on sequence. To turn on PLS8-X/PLS8-V, IGT has to be kept active at least 100 milliseconds. After turning on PLS8-X/PLS8-V, IGT should be set inactive to prevent the module from turning on again after a shut down by AT command or EMERG_OFF. For details on signal states during startup see also [Section 3.3.2](#).

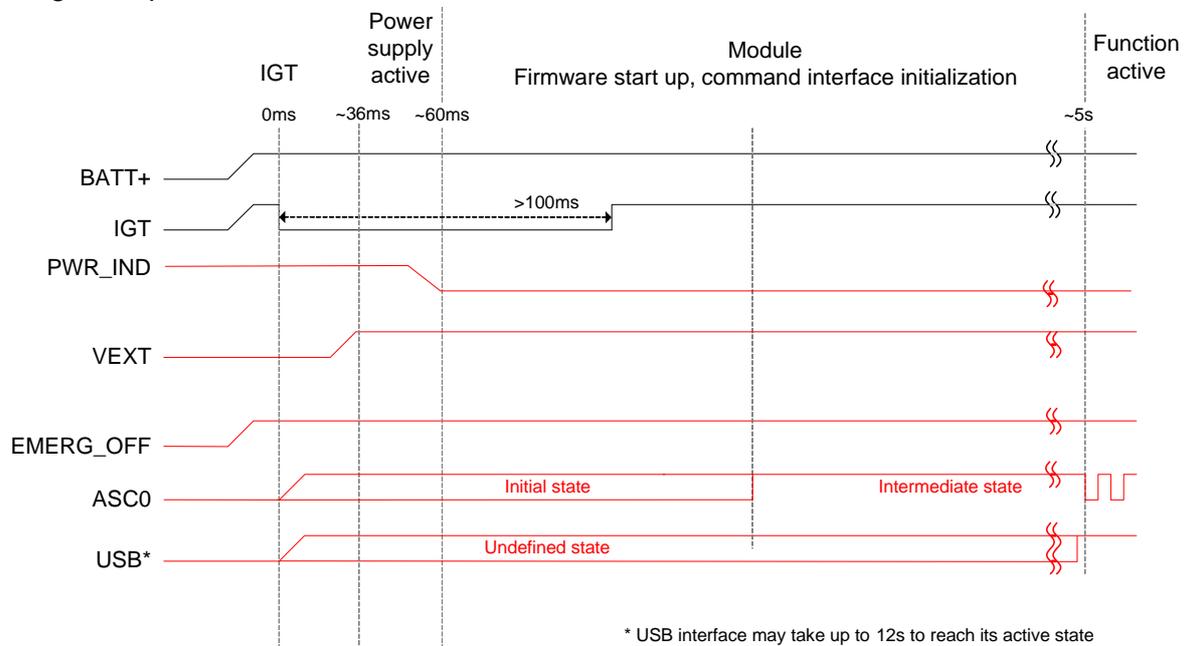


Figure 5: Power-on with IGT

Note: After power up IGT should remain high. Also note that with a USB connection the USB host may take up to 12 seconds to set up the virtual COM port connection.

After startup or mode change the following URCs are sent to every port able to receive AT commands indicating the module's ready state:

- "**^SYSSTART**" indicates that the module has entered Normal mode.
- "**^SYSSTART AIRPLANE MODE**" indicates that the module has entered Airplane mode.

These URCs notify the external application that the first AT command can be sent to the module. If these URCs are not used to detect then the only way of checking the module's ready state is polling. To do so, try to send characters (e.g. "at") until the module is responding.

3.3.2 Signal States after Startup

Table 7 describes the various states each interface signal passes through after startup and during operation.

Signals are in an initial state while the module is initializing. Once the startup initialization has completed, i.e. when the software is running, all signals are in defined state. The state of several signals will change again once the respective interface is activated or configured by AT command.

Table 7: Signal states

| Signal name | Power on reset | Startup phase | State after first firmware initialization |
|-------------------------|-------------------------|-------------------------|-------------------------------------------|
| | Duration appr. 60ms | Duration appr. 4s | After 4-5s |
| CCINx | PD and PU (24k) | PU(24k) | I, PU(24k) |
| CCRSTx | Not driven (similar PD) | Not driven (similar PD) | O, L ¹ O, H ² |
| CCIOx | PD(10k) | PD(10k) | PD(10k) ¹ |
| | | | PU(10k) ² |
| CCCLKx | Not driven (similar PD) | Not driven (similar PD) | O, L ¹ Clock ² |
| CCVCCx | Off | Off | Off ¹ 1.8V/3V ² |
| RXD0 | PD | PU | PU |
| TXD0 | PD | PD | PD |
| CTS0 | PD | PD | PD |
| RTS0 | PU and PD | PD | PD |
| DTR0 | PD | PD | PD |
| DCD0 | PD | PU ³ | PD |
| DSR0 | PD | PD | PD |
| RING0 | PD | O, H | O, H |
| PCM_I2S_IN | PU | PD | PD |
| PCM_I2S_CLK | PD | PD | PD |
| PCM_I2S_FSC | PD | PD | PD |
| PCM_I2S_OUT | PD | PD | PD |
| I2S_MCLKOUT | PD | PD | PD |
| PWR_IND | Z | O, L | O, L |
| STATUS | PD | PD | PD |
| EMERG_OFF | PU | I, PU | I, PU |
| IGT | I, PU | I, PU | I, PU |
| GPIO1...10 ⁴ | PD | PD | PD |

1. If CCINx = High level

2. If CCINx = Low level

3. No external pull down allowed during this phase.

4. Please note that during its startup phase the GPIO8 signal will be in an active low state for appr. 80ms.

| | |
|------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| L = Low level H = High level I = Input O = Output | PD = Pull down resistor with appr. 100k ¹ PD(...k) = Pull down resistor with ...k PU = Pull up resistor with appr. 100k PU(...k) = Pull up resistor with ...k, Z = High impedance |
|------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|

¹: Internal pulls are implemented using JFETs; strengths vary between devices, possible range: 55k...390k

3.3.3 Turn off PLS8-X/PLS8-V Using AT Command

The best and safest approach to powering down PLS8-X/PLS8-V is to issue the AT^SMSO command. This procedure lets PLS8-X/PLS8-V log off from the network and allows the software to enter into a secure state and save data before disconnecting the power supply. The mode is referred to as Power Down mode. In this mode, only the RTC stays active. After sending AT^SMSO do not enter any other AT commands. While powering down the module may still send some URCs. To verify that the module turned off it is possible to monitor the PWR_IND signal. A high state of the PWR_IND signal line indicates that the module is being switched off as shown in Figure 6.

Be sure not to disconnect the supply voltage V_{BATT+} before the module's switch off procedure has been completed and the VEXT signal has gone low. Otherwise you run the risk of losing data. Signal states during switch off are shown in Figure 6.

While PLS8-X/PLS8-V is in Power Down mode the application interface is switched off and must not be fed from any other source. Therefore, your application must be designed to avoid any current flow into any digital signal lines of the application interface. No special care is required for the USB interface which is protected from reverse current.

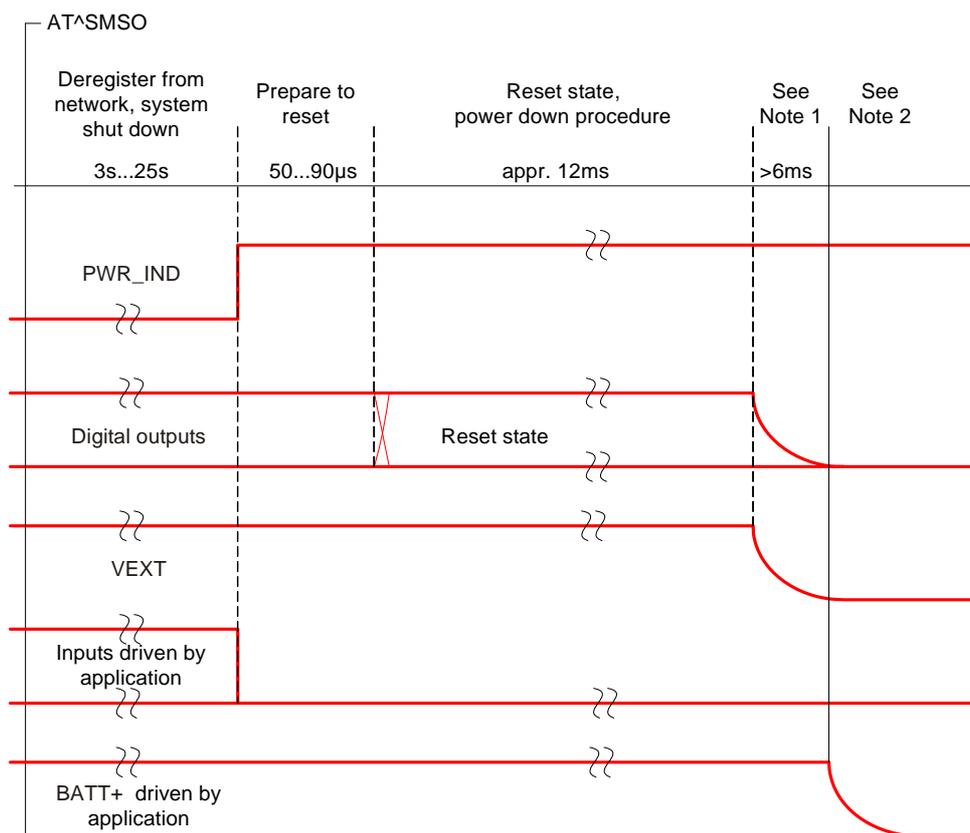


Figure 6: Signal states during turn-off procedure

- Note 1: Depending on capacitance load from host application
- Note 2: The power supply voltage (BATT+) may be disconnected or switched off only after the VEXT went low.
- Note 3: After module shutdown by means of AT command is completed, please allow for a time period of at least 1 second before restarting the module.

3.3.4 Turn off PLS8-X/PLS8-V Using IGT Line

The IGT line can be configured for use in two different switching modes: You can set the IGT line to switch on the module only, or to switch it on and off. The switching mode is determined by the parameter "MESHUTDOWN/OnIgnition" of the AT^SCFG command. This approach is useful for external application manufacturers who wish to have an ON/OFF switch installed on the host device.

By factory default, the ON/OFF switch mode of IGT is disabled:

```
at^scfg=meshutdown/onignition          # Query the current status of IGT.
^SCFG: "MESHUTDOWN/OnIgnition","off"  # IGT can be used only to switch on PLS8-X/
OK                                       PLS8-V.
                                         IGT works as described in Section 3.3.1.
```

To configure IGT for use as ON/OFF switch:

```
at^scfg=meshutdown/onignition          # Enable the ON/OFF switch mode of IGT.
^SCFG: "MESHUTDOWN/OnIgnition","on"   # IGT can be used to switch on and off PLS8-X/
OK                                       PLS8-V.
```

Take great care before changing the switching mode of the IGT line. To ensure that the IGT line works properly as ON/OFF switch it is of vital importance that the following conditions are met:

Switch-on condition: If the PLS8-X/PLS8-V is off, the IGT line must be asserted for at least 100 milliseconds before being released.

Switch-off condition: If the PLS8-X/PLS8-V is on, the IGT line must be asserted for at least 2.1 seconds before being released. The module switches off after the line is released. The switch-off routine is identical with the procedure initiated by AT^SMSO, i.e. the software performs an orderly shutdown as described in [Section 3.3.3](#).

Before switching off the module wait at least 12 seconds after startup.

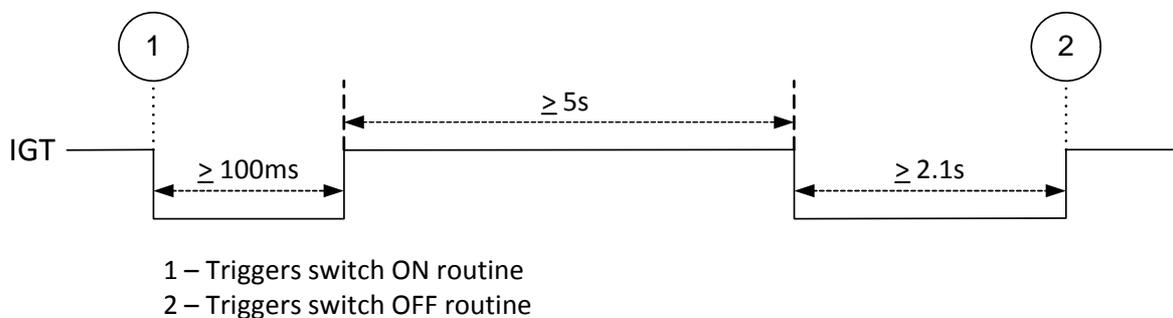


Figure 7: Timing of IGT if used as ON/OFF switch

3.3.5 Automatic Shutdown

Automatic shutdown takes effect if:

- The PLS8-X/PLS8-V board is exceeding the critical limits of overtemperature or undertemperature
- Undervoltage or overvoltage is detected

The automatic shutdown procedure is equivalent to the power down initiated with the AT^SMSO command, i.e. PLS8-X/PLS8-V logs off from the network and the software enters a secure state avoiding loss of data.

Alert messages transmitted before the device switches off are implemented as Unsolicited Result Codes (URCs). The presentation of the temperature URCs can be enabled or disabled with the AT commands AT^SCTM. The URC presentation mode varies with the condition, please see [Section 3.3.5.1](#) to [Section 3.3.5.4](#) for details. For further instructions on AT commands refer to [\[1\]](#).

3.3.5.1 Thermal Shutdown

The board temperature is constantly monitored by an internal NTC resistor located on the PCB. The values detected by the NTC resistor are measured directly on the board and therefore, are not fully identical with the ambient temperature.

Each time the board temperature goes out of range or back to normal, PLS8-X/PLS8-V instantly displays an alert (if enabled).

- URCs indicating the level "1" or "-1" allow the user to take appropriate precautions, such as protecting the module from exposure to extreme conditions. The presentation of the URCs depends on the settings selected with the AT^SCTM write command:
AT^SCTM=1: Presentation of URCs is always enabled.
AT^SCTM=0 (default): Presentation of URCs is enabled during the 2 minutes guard period after start-up of PLS8-X/PLS8-V. After expiry of the 2 minutes guard period, the presentation will be disabled, i.e. no URCs with alert levels "1" or "-1" will be generated.
- URCs indicating the level "2" or "-2" are instantly followed by an orderly shutdown. The presentation of these URCs is always enabled, i.e. they will be output even though the factory setting AT^SCTM=0 was never changed.

The maximum temperature ratings are stated in [Section 6.2](#). Refer to [Table 8](#) for the associated URCs.

Table 8: Temperature dependent behavior

| Sending temperature alert (2 minutes after PLS8-X/PLS8-V start-up, otherwise only if URC presentation enabled) | |
|----------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------|
| ^SCTM_B: 1 | Caution: Board close to overtemperature limit, i.e., board is 5°C below overtemperature limit. |
| ^SCTM_B: -1 | Caution: Board close to undertemperature limit, i.e., board is 5°C above undertemperature limit. |
| ^SCTM_B: 0 | Board back to uncritical temperature range, i.e., board is 6°C below its over- or above its undertemperature limit. |

3.3 Power-Up / Power-Down Scenarios

Table 8: Temperature dependent behavior

| Automatic shutdown (URC appears no matter whether or not presentation was enabled) | |
|------------------------------------------------------------------------------------|---------------------------------------------------------------------------------|
| ^SCTM_B: 2 | Alert: Board equal or beyond overtemperature limit. PLS8-X/PLS8-V switches off. |
| ^SCTM_B: -2 | Alert: Board equal or below undertemperature limit. PLS8-X/PLS8-V switches off. |

The AT^SCTM command can also be used to check the present status of the board. Depending on the selected mode, the read command returns the current board temperature in degrees Celsius or only a value that indicates whether the board is within the safe or critical temperature range. See [1] for further instructions.

3.3.5.2 Deferred Shutdown at Extreme Temperature Conditions

In the following cases, automatic shutdown will be deferred if a critical temperature limit is exceeded:

- While an emergency call is in progress.
- During a two minute guard period after power-up. This guard period has been introduced in order to allow for the user to make an emergency call. The start of any one of these calls extends the guard period until the end of the call. Any other network activity may be terminated by shutdown upon expiry of the guard time.

While in a "deferred shutdown" situation, PLS8-X/PLS8-V continues to measure the temperature and to deliver alert messages, but deactivates the shutdown functionality. Once the 2 minute guard period is expired or the call is terminated, full temperature control will be resumed. If the temperature is still out of range, PLS8-X/PLS8-V switches off immediately (without another alert message).

CAUTION! Automatic shutdown is a safety feature intended to prevent damage to the module. Extended usage of the deferred shutdown facilities provided may result in damage to the module, and possibly other severe consequences.

3.3.5.3 Undervoltage Shutdown

If the measured battery voltage is no more sufficient to set up a call the following URC will be presented:

^SBC: Undervoltage.

The URC indicates that the module is close to the undervoltage threshold. If undervoltage persists the module keeps sending the URC several times before switching off automatically.

This type of URC does not need to be activated by the user. It will be output automatically when fault conditions occur.

3.3.5.4 Overvoltage Shutdown

The overvoltage shutdown threshold is 100mV above the maximum supply voltage V_{BATT+} specified in [Table 22](#).

When the supply voltage approaches the overvoltage shutdown threshold the module will send the following URC:

^SBC: Overvoltage warning

This alert is sent once.

When the overvoltage shutdown threshold is exceeded the module will send the following URC

^SBC: Overvoltage shutdown

before it shuts down cleanly.

This type of URC does not need to be activated by the user. It will be output automatically when fault conditions occur.

Keep in mind that several PLS8-X/PLS8-V components are directly linked to BATT+ and, therefore, the supply voltage remains applied at major parts of PLS8-X/PLS8-V, even if the module is switched off. Especially the power amplifier is very sensitive to high voltage and might even be destroyed.

3.3.6 Turn off PLS8-X/PLS8-V in Case of Emergency

Caution: Use the EMERG_OFF line only when, due to serious problems, the software is not responding for more than 5 seconds. Pulling the EMERG_OFF line causes the loss of all information stored in the volatile memory. Therefore, this procedure is intended only for use in case of emergency, e.g. if PLS8-X/PLS8-V does not respond, if reset or shutdown via AT command fails.

The EMERG_OFF line is available on the application interface and can be used to switch off the module. To control the EMERG_OFF line it is recommended to use an open drain / collector driver.

To switch off, the EMERG_OFF line must be pulled to ground for longer than 40 milliseconds. After the 40 milliseconds and an additional delay period of 500 milliseconds the module shuts down as shown in [Figure 8](#).

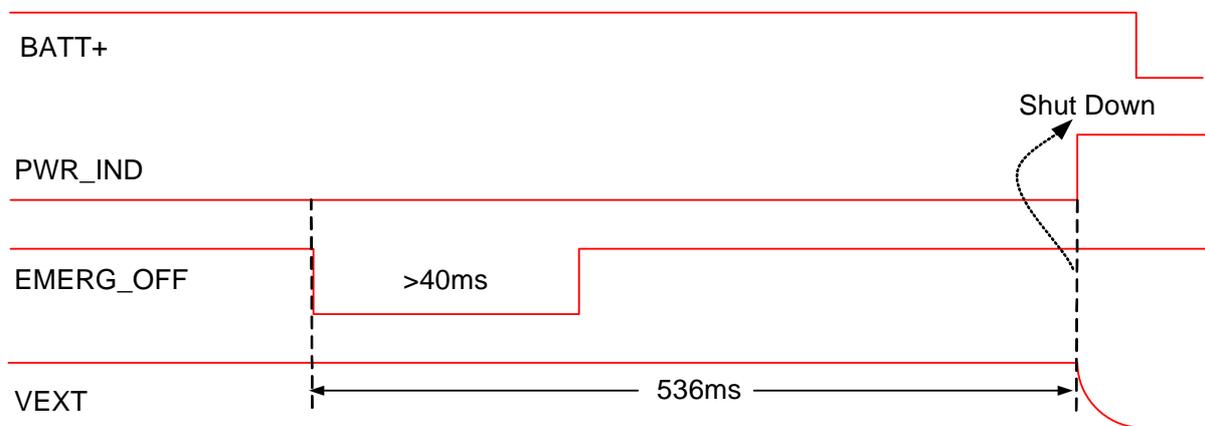


Figure 8: Shutdown by EMERG_OFF signal

Note: The power supply voltage (BATT+) may be disconnected or switched off only after having reached Shut Down as indicated by the PWR_IND signal going high. The power supply has to be available (again) before the module is restarted.

3.4 Power Saving

PLS8-X/PLS8-V is able to reduce its functionality to a minimum (during the so-called SLEEP mode) in order to minimize its current consumption. The following sections explain the module's network dependent power saving behavior. The power saving behavior is further configurable by AT command:

- `AT^SCFG= "MEopMode/PwrSave"`: The power save mode is by default enabled. While inactive, the module stays in power save (SLEEP) state, waking up only upon any of the following events:
 - Cyclically to meet basic technical demands, e.g. network requirements (such as regularly listening to paging messages from the base station as described in [Section 3.4.1](#), [Section 3.4.2](#) and [Section 3.4.3](#)).
 - Cyclically after expiry of a configured power saving period.
 - Data at any interface port, e.g., URCs for incoming calls.
 - A level state transition at GPIO1, GPIO3, GPIO4, GPIO5 and GPIO9.
- `AT^SCFG= "MEopMode/ExpectDTR"`: Power saving will take effect only if there is no transmission data pending on any of the module's USB ports. The expect DTR AT command ensures that data becoming pending on any USB port before an external application has signaled its readiness to receive the data is discarded. By default this behavior is enabled for all available USB CDC ACM and CDC ECM ports.
- `AT^SCFG="Radio/OutputPowerReduction"`: Output power reduction is possible for the module in GPRS multislot scenarios to reduce its output power according to 3GPP 45.005 section.

Please refer to [\[1\]](#) for more information on the above AT commands used to configure the module's power saving behavior.

The implementation of the USB host interface also influences the module's power saving behavior and therefore its current consumption. For more information see [Section 3.6](#). Another feature influencing the current consumption is the configuration of the GNSS antenna interface. For details see [Section 6.8](#). Also note that the command `AT^SBV`, which allows to monitor the module's power supply, is only available if the module is not in SLEEP mode. This means, the shorter the power saving periods, the faster and more precise the module's power supply monitoring is going to be (see also [Section 3.2.2](#)).

3.4.1 Power Saving while Attached to GSM Networks

The power saving possibilities while attached to a GSM network depend on the paging timing cycle of the base station. The duration of a paging timing cycle can be calculated using the following formula:

$$t = 4.615 \text{ ms (TDMA frame duration)} * 51 \text{ (number of frames)} * \text{DRX value.}$$

DRX (Discontinuous Reception) is a value from 2 to 9, resulting in paging timing cycles between 0.47 and 2.12 seconds. The DRX value of the base station is assigned by the GSM network operator.

Now, a paging timing cycle consists of the actual fixed length paging plus a variable length pause before the next paging. In the pauses between listening to paging messages, the module resumes power saving, as shown in [Figure 9](#).

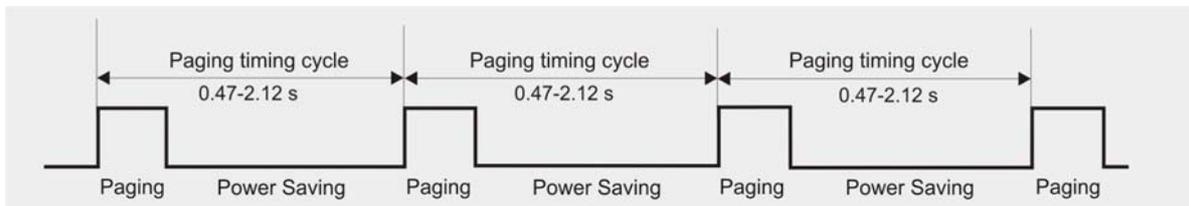


Figure 9: Power saving and paging in GSM networks

The varying pauses explain the different potential for power saving. The longer the pause the less power is consumed.

Generally, power saving depends on the module's application scenario and may differ from the above mentioned normal operation. The power saving interval may be shorter than 0.47 seconds or longer than 2.12 seconds.

3.4.2 Power Saving while Attached to WCDMA Networks

The power saving possibilities while attached to a WCDMA network depend on the paging timing cycle of the base station.

During normal WCDMA operation, i.e., the module is connected to a WCDMA network, the duration of a paging timing cycle varies. It may be calculated using the following formula:

$$t = 2^{\text{DRX value}} * 10 \text{ ms (WCDMA frame duration)}.$$

DRX (Discontinuous Reception) in WCDMA networks is a value between 6 and 9, thus resulting in paging timing cycles between 0.64 and 5.12 seconds. The DRX value of the base station is assigned by the WCDMA network operator.

Now, a paging timing cycle consists of the actual fixed length paging plus a variable length pause before the next paging. In the pauses between listening to paging messages, the module resumes power saving, as shown in [Figure 10](#).

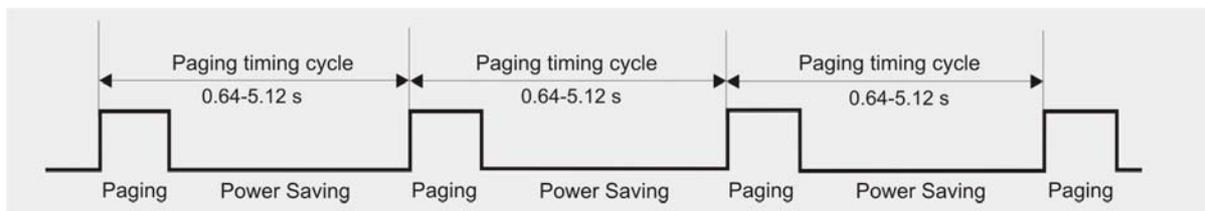


Figure 10: Power saving and paging in WCDMA networks

The varying pauses explain the different potential for power saving. The longer the pause the less power is consumed.

Generally, power saving depends on the module's application scenario and may differ from the above mentioned normal operation. The power saving interval may be shorter than 0.64 seconds or longer than 5.12 seconds.

3.4.3 Power Saving while Attached to LTE Networks

The power saving possibilities while attached to an LTE network depend on the paging timing cycle of the base station.

During normal LTE operation, i.e., the module is connected to an LTE network, the duration of a paging timing cycle varies. It may be calculated using the following formula:

$$t = \text{DRX Cycle Value} * 10 \text{ ms}$$

DRX cycle value in LTE networks is any of the four values: 32, 64, 128 and 256, thus resulting in paging timing cycles between 0.32 and 2.56 seconds. The DRX cycle value of the base station is assigned by the LTE network operator.

Now, a paging timing cycle consists of the actual fixed length paging plus a variable length pause before the next paging. In the pauses between listening to paging messages, the module resumes power saving, as shown in [Figure 11](#).

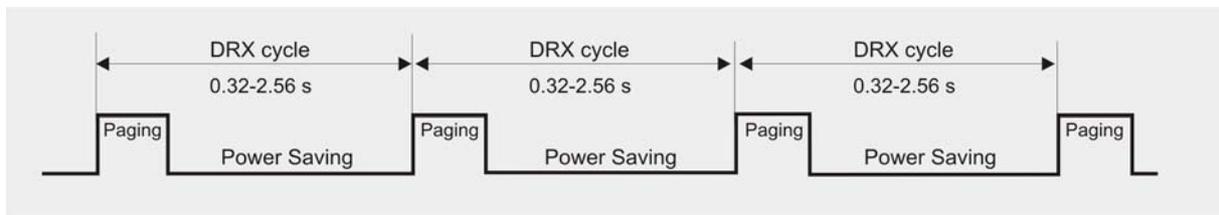


Figure 11: Power saving and paging in LTE networks

The varying pauses explain the different potential for power saving. The longer the pause the less power is consumed.

Generally, power saving depends on the module's application scenario and may differ from the above mentioned normal operation. The power saving interval may be shorter than 0.32 seconds or longer than 2.56 seconds.

3.4.4 Wake-up via RTS0

RTS0 can be used to wake up PLS8-X/PLS8-V from SLEEP mode. Assertion of RTS0 (i.e., toggle from inactive high to active low) serves as wake up event, thus allowing an external application to almost immediately terminate power saving. After RTS0 assertion, the CTS0 line signals module wake up, i.e., readiness of the AT command interface. It is therefore recommended to enable RTS/CTS flow control (default setting).

Figure 12 shows the described RTS0 wake up mechanism.

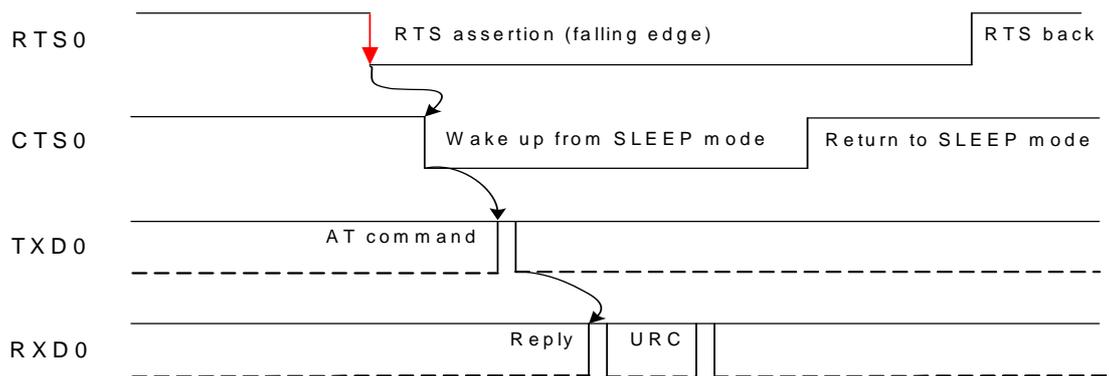


Figure 12: Wake-up via RTS0

3.5 RTC Backup

The internal Real Time Clock of PLS8-X/PLS8-V is supplied from a separate voltage regulator in the power supply component which is also active when PLS8-X/PLS8-V is in Power Down mode and BATT+ is available. An alarm function is provided that allows to wake up PLS8-X/PLS8-V. When the alarm time is reached the module wakes up to the functionality level (AT+CFUN) that was valid before power down. For example, if the module was in Airplane mode before power down, the module will wake up without logging on to the GSM/UMTS network.

In addition, you can use the VDDL P pad on the SMT interface to backup the RTC from an external capacitor or a battery (rechargeable or non-chargeable). The capacitor is charged from the internal LDO of PLS8-X/PLS8-V. If the voltage supply at BATT+ is disconnected the RTC can be powered by the capacitor. The size of the capacitor determines the duration of buffering when no voltage is applied to PLS8-X/PLS8-V, i.e. the greater the capacitor the longer PLS8-X/PLS8-V will save the date and time. It limits the output current of an empty capacitor or battery.

Figure 13 show various sample configurations.

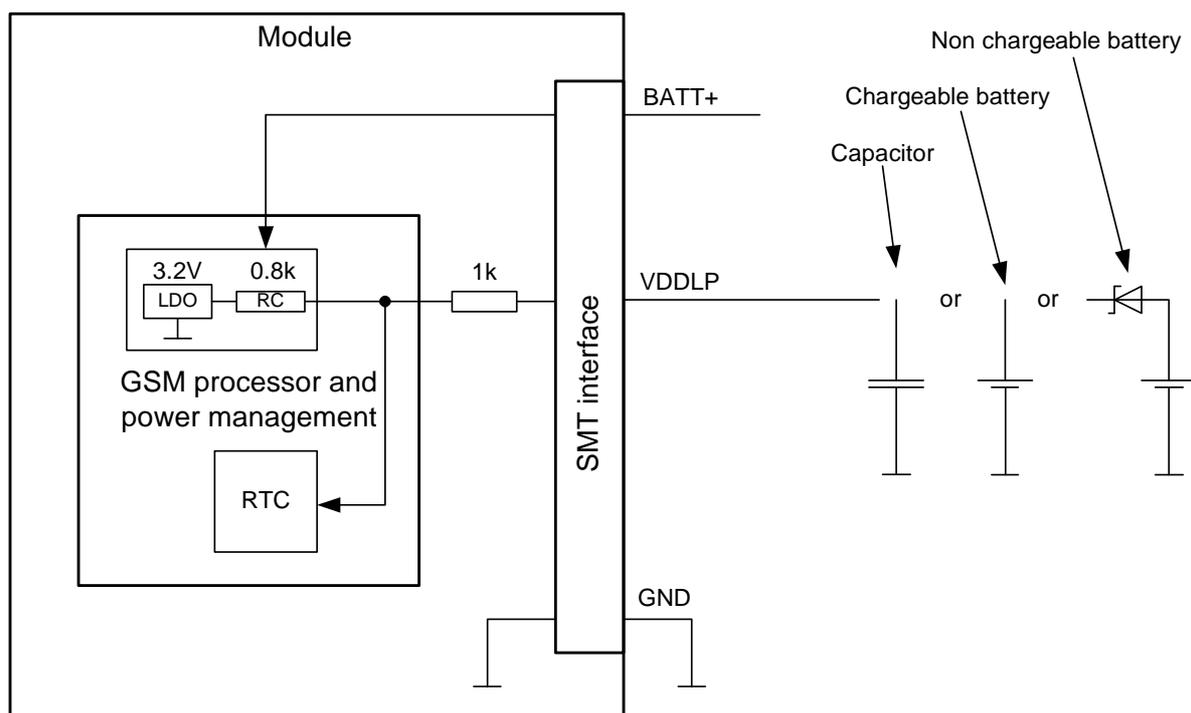
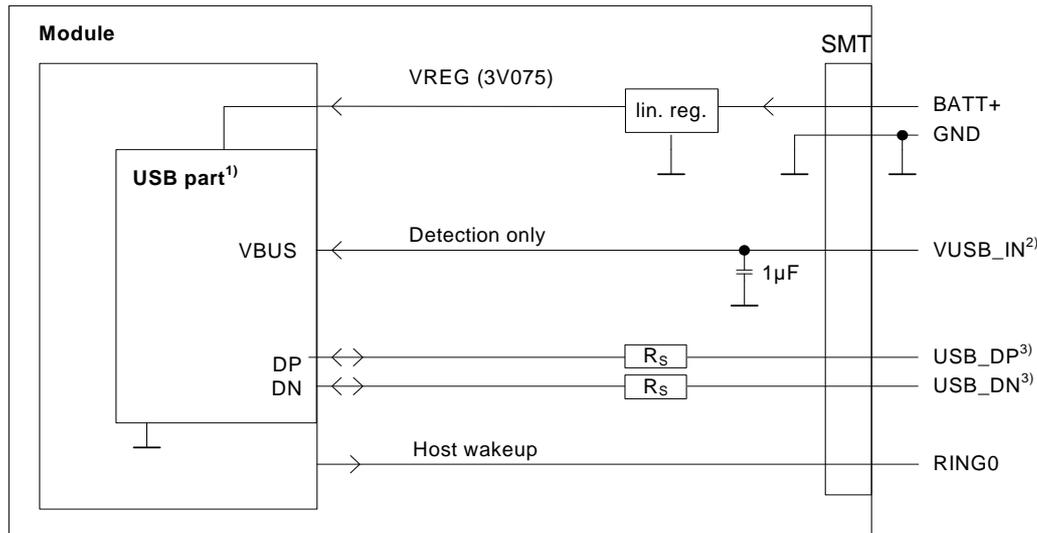


Figure 13: RTC supply variants

3.6 USB Interface

PLS8-X/PLS8-V supports a USB 2.0 High Speed (480Mbps) device interface. The USB interface is primarily intended for use as command and data interface and for downloading firmware.

The USB host is responsible for supplying the VUSB_IN line. This line is for voltage detection only. The USB part (driver and transceiver) is supplied by means of BATT+. This is because PLS8-X/PLS8-V is designed as a self-powered device compliant with the “Universal Serial Bus Specification Revision 2.0”¹.



¹) All serial (including R_S) and pull-up resistors for data lines are implemented.

²) Since VUSB_IN is used for detection only it is recommended not to add any further blocking capacitors on the VUSB_IN line.

³) If the USB interface is operated in High Speed mode (480MHz), it is recommended to take special care routing the data lines USB_DP and USB_DN. Application layout should in this case implement a differential impedance of 90 ohms for proper signal integrity.

Figure 14: USB circuit

To properly connect the module's USB interface to the external application, a USB 2.0 compatible connector and cable or hardware design is required. For more information on the USB related signals see [Table 22](#). Furthermore, the USB modem driver distributed with PLS8-X/PLS8-V needs to be installed.

¹. The specification is ready for download on <http://www.usb.org/developers/docs/>

3.6.1 Reducing Power Consumption

While a USB connection is active, the module will never switch into SLEEP mode. Only if the USB interface is in Suspended state or Detached (i.e., VUSB_IN = 0) is the module able to switch into SLEEP mode thereby saving power¹. There are two possibilities to enable power reduction mechanisms:

- **Recommended implementation of USB Suspend/Resume/Remote Wakeup:**

The USB host should be able to bring its USB interface into the Suspended state as described in the "Universal Serial Bus Specification Revision 2.0"². For this functionality to work, the VUSB_IN line should always be kept enabled. On incoming calls and other events PLS8-X/PLS8-V will then generate a Remote Wakeup request to resume the USB host controller.

See also [4] (USB Specification Revision 2.0, Section 10.2.7, p.282):

"If USB System wishes to place the bus in the Suspended state, it commands the Host Controller to stop all bus traffic, including SOFs. This causes all USB devices to enter the Suspended state. In this state, the USB System may enable the Host Controller to respond to bus wakeup events. This allows the Host Controller to respond to bus wakeup signaling to restart the host system."

- **Implementation for legacy USB applications not supporting USB Suspend/Resume:**

As an alternative to the regular USB suspend and resume mechanism it is possible to employ a remote wakeup line (e.g., the RING0 line) to wake up the host application in case of incoming calls or events signaled by URCs while the USB interface is in Detached state (i.e., VUSB_IN = 0). Every wakeup event will force a new USB enumeration. Therefore, the external application has to carefully consider the enumeration timings to avoid losing any signalled events. For details on this host wakeup functionality see [Section 3.13.3](#).

It is possible to prevent existing data connections from being disconnected while the USB interface is in detached state (i.e., VUSB_IN=0) by configuring at least one of the module's USB ports to contribute to a host wakeup, i.e., configuring the port to try to wake up a connected host in case an appropriate event occurs (see [1]: AT^SCFG="RemoteWakeUp/Ports"), and by configuring a GPIO as USB wakeup GPIO (see [1]: AT^SCFG="RemoteWakeUp/Event/USB").

¹. Please note that if the USB interface is employed, and a USB cable is connected, there should also be a terminal programm linked to the USB port in order to receive and process the initial SYSSTART URC after module startup. Otherwise, the SYSSTART URC remains pending in the USB driver's output buffer and this unprocessed data prevents the module from power saving.

². The specification is ready for download on <http://www.usb.org/developers/docs/>

3.7 Serial Interface ASC0

PLS8-X/PLS8-V offers an 8-wire unbalanced, asynchronous modem interface ASC0 conforming to ITU-T V.24 protocol DCE signalling. The electrical characteristics do not comply with ITU-T V.28. The significant levels are 0V (for low data bit or active state) and 1.8V (for high data bit or inactive state). For electrical characteristics please refer to [Table 22](#).

PLS8-X/PLS8-V is designed for use as a DCE. Based on the conventions for DCE-DTE connections it communicates with the customer application (DTE) using the following signals:

- Port TXD @ application sends data to the module's TXD0 signal line
- Port RXD @ application receives data from the module's RXD0 signal line

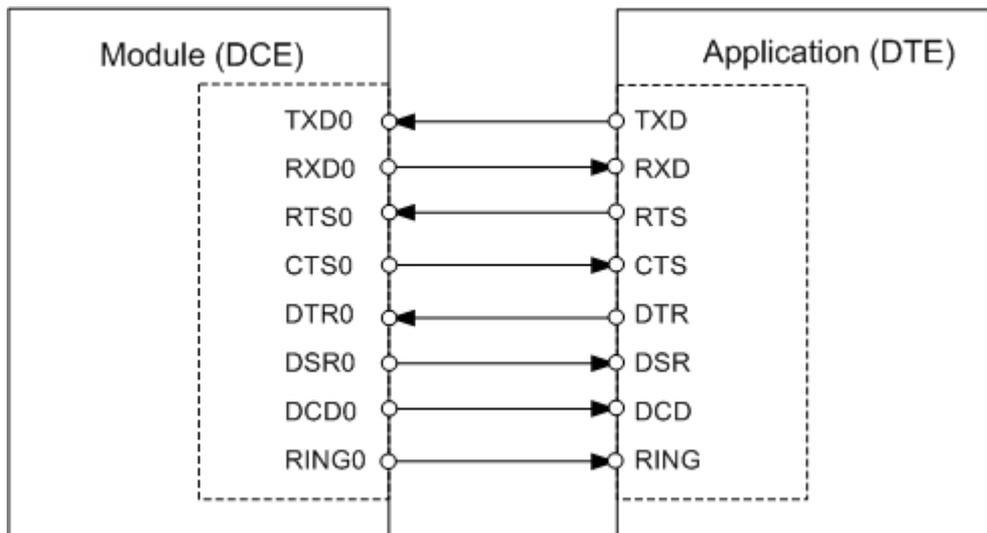


Figure 15: Serial interface ASC0

Features:

- Includes the data lines TXD0 and RXD0, the status lines RTS0 and CTS0 and, in addition, the modem control lines DTR0, DSR0, DCD0 and RING0.
- The RING0 signal serves to indicate incoming calls and other types of URCs (Unsolicited Result Code). It can also be used to send pulses to the host application, for example to wake up the application from power saving state. See [\[1\]](#) for details on how to configure the RING0 line by AT^SCFG.
- Configured for 8 data bits, no parity and 1 stop bit.
- ASC0 can be operated at fixed bit rates from 115,200bps up to 921,600bps.
- Supports RTS0/CTS0 hardware flow control.
- Wake up from SLEEP mode by RTS0 activation (high to low transition; see [Section 3.4.4](#)).

Note: If the ASC0 serial interface is the application's only interface, it is suggested to connect test points on the USB signal lines as a potential tracing possibility.

3.7 Serial Interface ASC0

Table 9: DCE-DTE wiring of ASC0

| V.24 circuit | DCE | | DTE | |
|--------------|---------------|------------------|---------------|------------------|
| | Line function | Signal direction | Line function | Signal direction |
| 103 | TXD0 | Input | TXD | Output |
| 104 | RXD0 | Output | RXD | Input |
| 105 | RTS0 | Input | RTS | Output |
| 106 | CTS0 | Output | CTS | Input |
| 108/2 | DTR0 | Input | DTR | Output |
| 107 | DSR0 | Output | DSR | Input |
| 109 | DCD0 | Output | DCD | Input |
| 125 | RING0 | Output | RING | Input |

3.8 UICC/SIM/USIM Interface

PLS8-X/PLS8-V has two UICC/SIM/USIM interfaces compatible with the 3GPP 31.102 and ETSI 102 221. These are wired to the host interface in order to be connected to an external SIM card holder. Five pads on the SMT application interface are reserved for each of the two SIM interfaces.

The UICC/SIM/USIM interfaces support 3V and 1.8V SIM cards. Please refer to [Table 22](#) for electrical specifications of the UICC/SIM/USIM interface lines depending on whether a 3V or 1.8V SIM card is used.

The CCINx signal serves to detect whether a tray (with SIM card) is present in the card holder. Using the CCINx signal is mandatory for compliance with the GSM 11.11 recommendation if the mechanical design of the host application allows the user to remove the SIM card during operation. To take advantage of this feature, an appropriate SIM card detect switch is required on the card holder. For example, this is true for the model supplied by Molex, which has been tested to operate with PLS8-X/PLS8-V and is part of the Gemalto M2M reference equipment submitted for type approval. See [Chapter 10](#) for Molex ordering numbers.

Table 10: Signals of the SIM interface (SMT application interface)

| Signal | Description |
|------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| GND | Ground connection for SIM interfaces. Optionally a separate SIM ground line using e.g., pad N11 may be used to improve EMC. |
| CCCLK1 CCCLK2 | Chipcard clock lines for 1 st and 2 nd SIM interface. |
| CCVCC1 CCVCC2 | SIM supply voltage lines for 1 st and 2 nd SIM interface. |
| CCIO1 CCIO2 | Serial data lines for 1 st and 2 nd SIM interface, input and output. |
| CCRS1 CCRS2 | Chipcard reset lines for 1 st and 2 nd SIM interface |
| CCIN1 CCIN2 | Input on the baseband processor for detecting a SIM card tray in the holder. If the SIM is removed during operation the SIM interface is shut down immediately to prevent destruction of the SIM. The CCINx signal is active low. The CCINx signal is mandatory for applications that allow the user to remove the SIM card during operation. The CCINx signal is solely intended for use with a SIM card. It must not be used for any other purposes. Failure to comply with this requirement may invalidate the type approval of PLS8-X/PLS8-V. |

Note: No guarantee can be given, nor any liability accepted, if loss of data is encountered after removing the SIM card during operation. Also, no guarantee can be given for properly initializing any SIM card that the user inserts after having removed the SIM card during operation. In this case, the application must restart PLS8-X/PLS8-V.

3.8 UICC/SIM/USIM Interface

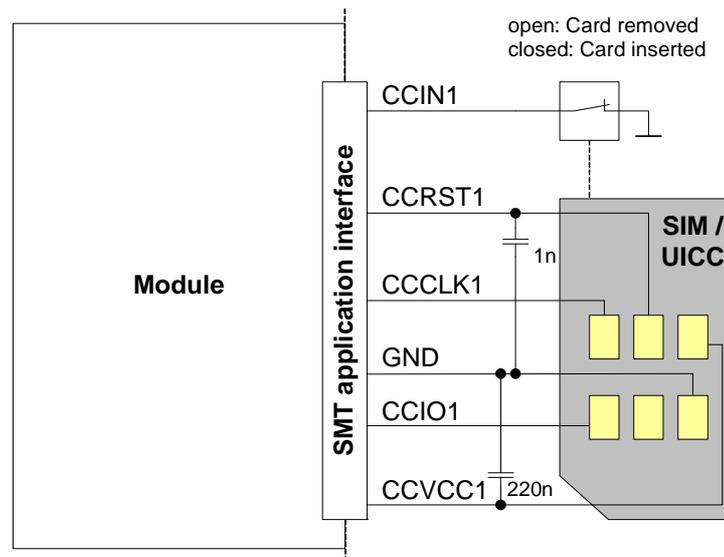


Figure 16: First UICC/SIM/USIM interface

The total cable length between the SMT application interface pads on PLS8-X/PLS8-V and the pads of the external SIM card holder must not exceed 100mm in order to meet the specifications of 3GPP TS 51.010-1 and to satisfy the requirements of EMC compliance.

To avoid possible cross-talk from the CCCLKx signal to the CCIOx signal be careful that both lines are not placed closely next to each other. A useful approach is using the GND line to shield the CCIOx line from the CCCLKx line.

An example for an optimized ESD protection for the SIM interface is shown in [Section 3.8.1](#).

Note: [Figure 16](#) shows how to connect a SIM card holder to the first SIM interface. With the second SIM interface some internally integrated components on the SIM circuit will have to be externally integrated as shown for the second SIM interface in [Figure 17](#).

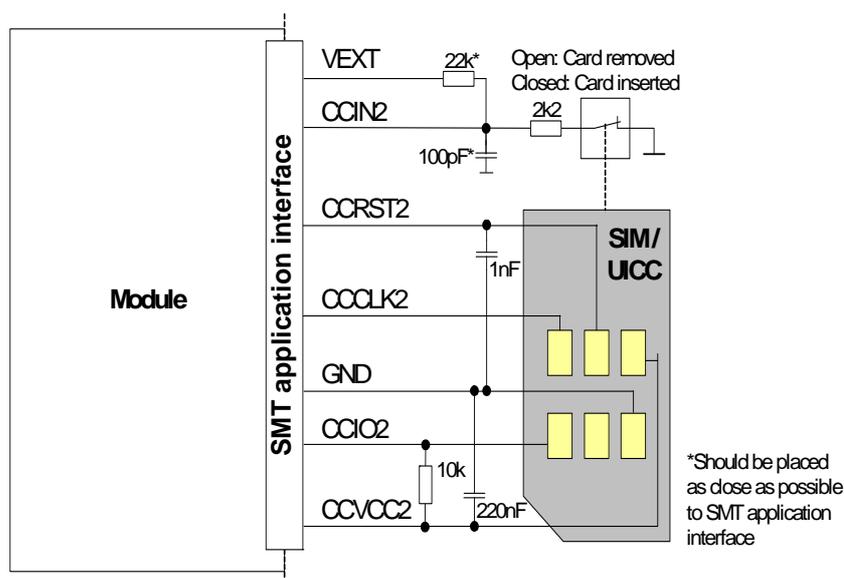


Figure 17: Second UICC/SIM/USIM interface

3.8.1 Enhanced ESD Protection for SIM Interface

To optimize ESD protection for the SIM interfaces it is possible to add ESD diodes to the interface lines of the first and second SIM interface as shown in the example given in [Figure 18](#).

The example was designed to meet ESD protection according ETSI EN 301 489-1/7: Contact discharge: $\pm 4\text{kV}$, air discharge: $\pm 8\text{kV}$.

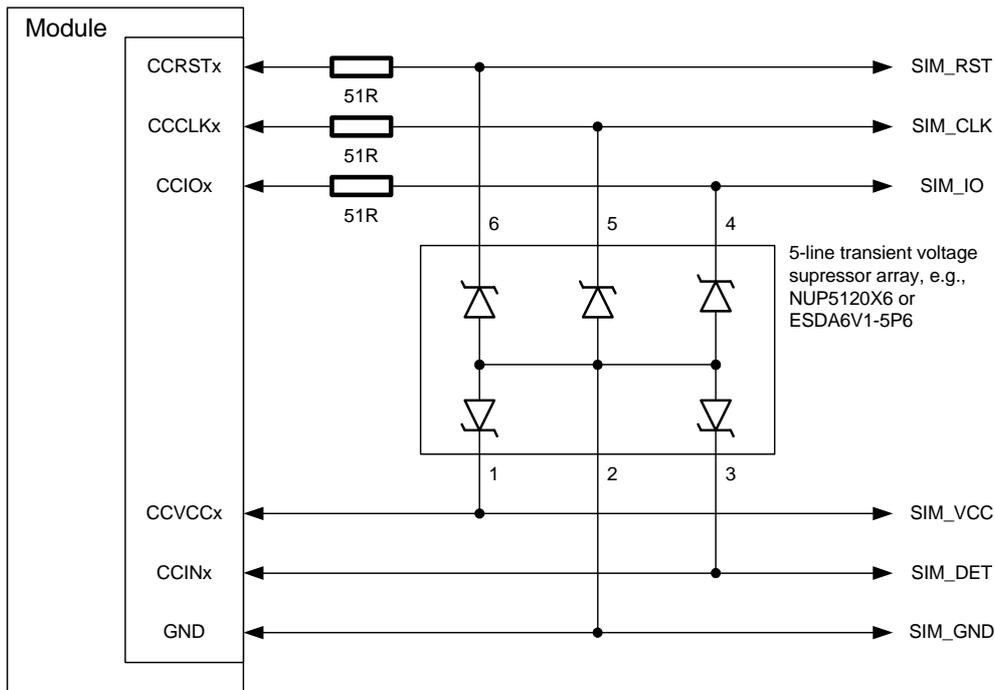


Figure 18: SIM interface - enhanced ESD protection

3.9 Digital Audio Interface

PLS8-X/PLS8-V has a digital audio interface that can be employed either as pulse code modulation interface (see [Section 3.9.1](#)) or as inter IC sound interface (see [Section 3.10](#)). Operation can be configured by AT command (see [\[1\]](#)). Default setting is pulse code modulation.

Note: As PLS8-X/PLS8-V is a data only module, the module's digital audio interface supports local tones only and is otherwise reserved for future use.

3.9.1 Pulse Code Modulation Interface (PCM)

PLS8-X/PLS8-V's PCM interface can be used to connect audio devices capable of pulse code modulation. For the PCM interface configuration the parameters <clock>, <mode>, <frame_mode>, <ext_clk_mode> and <sample_rate> of the AT^SAIC command can be configured in any combination (for details on AT^SAIC see [\[1\]](#)). [Table 11](#) lists the available PCM interface signals.

Table 11: Overview of PCM pin functions

| Signal name on SMT application interface | Signal configuration inactive | Signal direction: Master | Signal direction: Slave |
|------------------------------------------|-------------------------------|--------------------------|-------------------------|
| PCM_I2S_OUT | PD | O | O |
| PCM_I2S_IN | PD | I | I |
| PCM_I2S_FSC | PD | O | I |
| PCM_I2S_CLK | PD | O | I |

Characteristics of Audio Modes

PLS8-X/PLS8-V has various audio modes selectable with AT^SNFS (for details see [\[1\]](#)).

3.10 Inter IC Sound Interface (I²S)

The I²S Interface is a standardized bidirectional I²S ("Inter-IC Sound Interface") based digital audio interface for transmission of mono audio signals. The I²S interface can be enabled and configured using the AT command AT^SAIC (see [\[1\]](#)). An activation is possible only out of tone presentation. The I²S properties and capabilities comply with the requirements layed out in the Phillips I2S Bus Specifications, revised June 5, 1996. The digital audio interface pads available for the PCM interface are also available for the I²S interface. In I²S mode they have the same electrical characteristics. For the master clock option there is a separate line (see [Section 6.5](#) for more information on these lines). [Table 12](#) lists the available I²S interface signals.

Table 12: Overview of I²S pin functions

| Signal name on SMT application interface | Signal configuration inactive | Signal direction: Master |
|------------------------------------------|-------------------------------|--------------------------|
| PCM_I2S_OUT | PD | O |
| PCM_I2S_IN | PD | I |
| PCM_I2S_FSC | PD | O |
| PCM_I2S_CLK | PD | O |
| I2S_MCLKOUT | PD | O |

3.11 Analog-to-Digital Converter (ADC)

PLS8-X/PLS8-V provides three unbalanced ADC input lines: ADC1_IN, ADC2_IN and ADC3_IN. They can be used to measure three independent, externally connected DC voltages in the range of 0.3V to 3.075V.

The AT^SRADC command can be employed to select the ADC line, set the measurement mode and read out the measurement results.

3.12 GPIO Interface

PLS8-X/PLS8-V has 10 GPIOs for external hardware devices. Each GPIO can be configured for use as input or output. All settings are AT command controlled.

The IO port driver has to be open before using and configuring GPIOs. Before changing the configuration of a GPIO pin (e.g. input to output) the pin has to be closed. If the GPIO pins are not configured or the pins/driver were closed, the GPIO pins are high-Z with pull down resistor. If a GPIO is configured to input, the pin has high-Z without pull resistor.

GPIO1 can be configured as dead reckoning synchronization line (see [Chapter 4](#)), GPIO2 can be configured as 700MHz antenna switch control signal (see [Section 3.13.6](#)), GPIO6 may be configured as low current indicator signal (see [Section 3.13.4](#)), and GPIOs may be set as remote host wakeup lines (see [Section 3.13.3](#)).

If the PLS8-X/PLS8-V stays in power save (SLEEP) mode a level state transition at GPIO1, GPIO3, GPIO4, GPIO5 and GPIO9 will wake up the module. To query the level state the AT^SCPOL command may be used.

3.13 Control Signals

3.13.1 PWR_IND Signal

PWR_IND notifies the on/off state of the module. For state detection an external pull-up resistor is required (cp. R1 in below [Figure 19](#)). As long as the feeding voltage is applied at the pull-up resistor, a high state of PWR_IND indicates that the module is switched off.

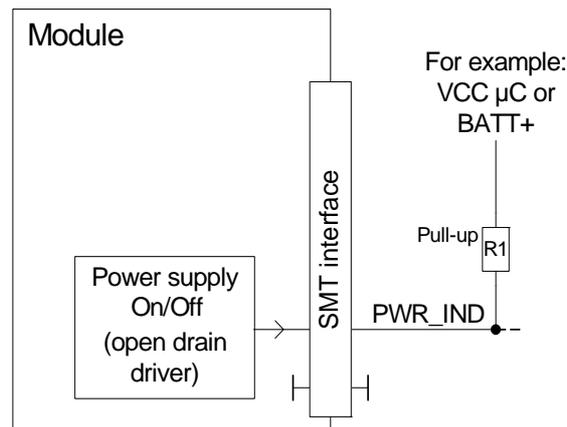


Figure 19: PWR_IND signal

3.13.2 Behavior of the RING0 Line

The RING0 line serves to indicate incoming calls and other types of URCs (Unsolicited Result Code).

Although not mandatory for use in a host application, it is strongly suggested that you connect the RING0 line to an interrupt line of your application. In this case, the application can be designed to receive an interrupt when a falling edge on RING0 occurs. This solution is most effective, particularly, for waking up an application from power saving. Therefore, utilizing the RING0 line provides an option to significantly reduce the overall current consumption of your application.

The RING0 line behavior and usage can be configured by AT command. For details see [\[1\]](#): AT^SCFG.

3.13.3 Remote Wakeup

If no call, data or message transfer is in progress, the external host application may shut down its own module interfaces or other components in order to save power. If a call, data, or other request (URC) arrives, the external application can be notified of this event and be woken up again by a state transition of a configurable remote wakeup line. Available as remote wakeup lines are all GPIO signals as well as the RING0 line. Please refer to [1]: AT^SCFG: "RemoteWakeUp/..." for details on how to configure these lines for defined wakeup events on specified device interfaces. Possible states are listed in Table 13.

If no line is specifically configured as remote wakeup signal, the remote USB suspend and resume mechanism as specified in the "Universal Serial Bus Specification Revision 2.0"¹ applies for the USB interface (see Section 3.6), or the RING0 line may be employed with USB applications not supporting this mechanism (see also Section 3.6.1). This legacy behaviour of the RING0 line as remote host wakeup line has to be enabled and configured by AT command (see [1]: AT^SCFG: "URC/Ringline"). Possible states are listed in Table 13.

Table 13: Host wakeup lines

| Signal | I/O/P | Description |
|--------|-------|---------------------------------------------------------------------------------------------|
| RING0 | O | Inactive to active low transition: 0 = The host shall wake up 1 = No wake up request |
| GPIOx | O | Inactive to active high transition: 0 = No wake up request 1 = The host shall wake up |

¹. The specification is ready for download on <http://www.usb.org/developers/docs/>

3.13.4 Low Current Indicator (LCI)

A low current indication is optionally available over a GPIO line. By default, low current indication is disabled and the GPIO pads can be configured and employed as usual.

For a GPIO pad to work as a low current indicator the feature has to be enabled by AT command (see [1]: AT^SCFG: MEopMode/PowerMgmt/LCI). By default, the GPIO6 pad is configured as LCI signal.

If enabled, the GPIOx/LCI signal is high when the module is sleeping. During its sleep the module will for the most part be slow clocked with 32kHz RTC.

Table 14: Low current indicator line

| Signal | I/O/P | Description |
|-----------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| GPIOx/LCI | O | Inactive to active high transition: 0 = High current consumption The module draws its power via BATT+ 1 = Low current consumption (only reached during SLEEP mode) The module draws only a low current via BATT+ |

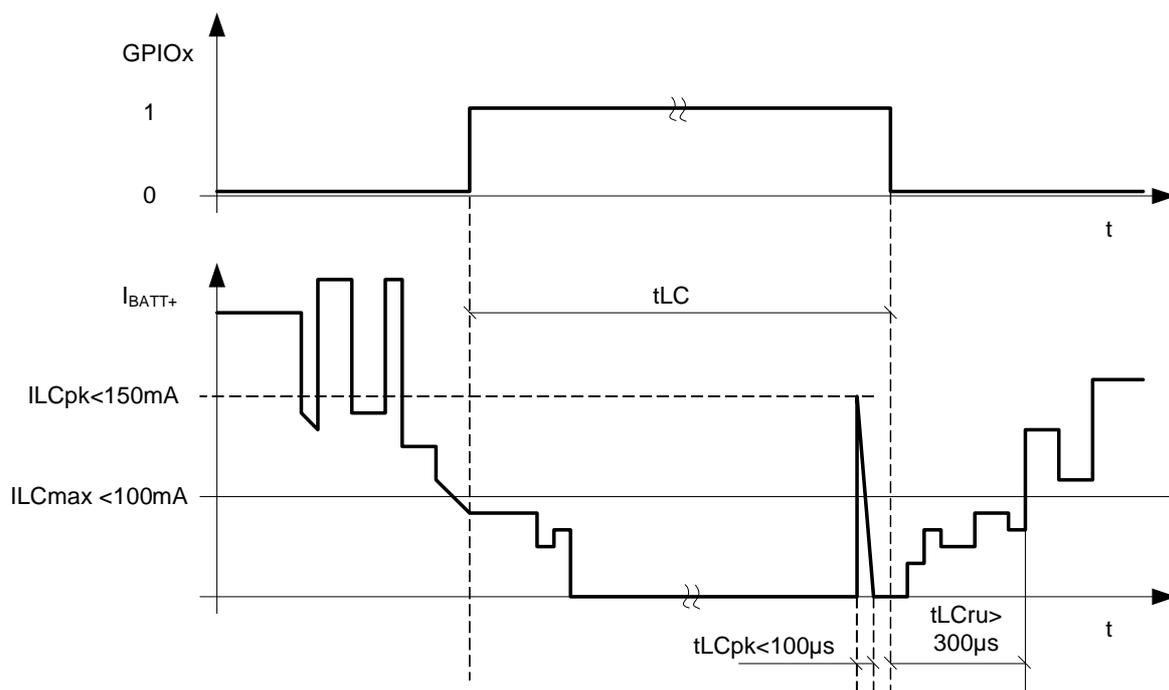


Figure 20: Low current indication timing (still to be confirmed)

- tLC Time for the I_{BATT+} current consumption: $ILC_{max} < 100\text{mA}$.
- tLCpk Max. time duration for the inrush current peak at the end of the low current period.
- tLCru When the GPIOx signal becomes inactive (low) the current ramps up to the maximum low current value within tLCru.
- ILCpk When the module turns from sleep to normal operation some internal supply voltages will be switched on. That causes a small inrush current peak.
- ILCmax During the low current period tLC the current consumption does not exceed the ILCmax value.

3.13.5 Network Connectivity and Technology Status Signals

The STATUS line serves to indicate the module's network connectivity state or the underlying network technology (2G or 3G/4G) and can be used to control an externally connected LED as shown in [Figure 21](#). To operate the LED a buffer, e.g. a transistor or gate, must be included in the external application.

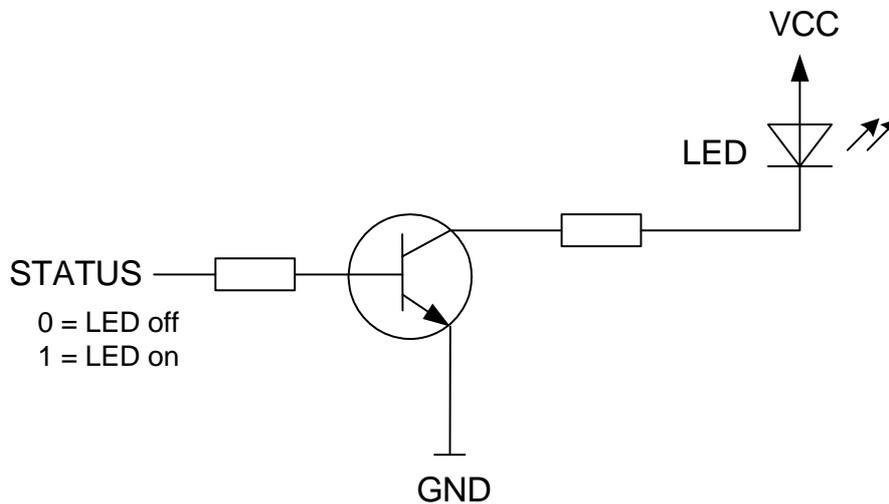


Figure 21: LED circuit (example)

For electrical characteristics of the STATUS line see [Table 22](#). The network connectivity and technology signal function is volatile and has to be activated after module startup with AT^SLED. For details on the command as well as status and mode indications through blinking intervals see [\[1\]](#).

3.13.6 700MHz Antenna Switch Control

To provide for an antenna optimization over a wide frequency range, the GPIO2 (ANT_SWITCH) line can be configured as a control signal for a possible external antenna switch that is able to change between an antenna covering the 700MHz band and an antenna covering all other bands - depending on the frequency band currently being used by the module.

If the control switch functionality is enabled, GPIO2 is set to "high" (1) if the module is employing frequencies in the 700 MHz range (i.e., LTE band 17) and "low" (0) for all other frequencies, including the 800/850 MHz frequency bands.

A GPIO2 signal switch is triggered by all module internal activities involving a change of the used frequency, even if only temporary (e.g., inter-band scanning using compressed mode). The maximum delay/deviation between internal usage change of the frequency band, and the GPIO2 signal change is 10 microseconds.

For electrical characteristics of the GPIO2 (ANT_SWITCH) line see [Table 22](#). The antenna switch control is non-volatile and has to be activated after module startup with `AT^SCFG="GPIO/Mode/Antenna"`. For details on the command see [\[1\]](#).

4 GNSS Receiver

PLS8-X/PLS8-V integrates a GNSS receiver that offers the full performance of GPS/GLONASS technology. The GNSS receiver is able to continuously track all satellites in view, thus providing accurate satellite position data.

The integrated GNSS receiver supports the NMEA protocol via USB or ASC0 interface. NMEA is a combined electrical and data specification for communication between various (marine) electronic devices including GNSS receivers. It has been defined and controlled by the US based National Marine Electronics Association. For more information on the NMEA Standard please refer to <http://www.nmea.org>.

Depending on the receiver's knowledge of last position, current time and ephemeris data, the receiver's startup time (i.e., TTFF = Time-To-First-Fix) may vary: If the receiver has no knowledge of its last position or time, a startup takes considerably longer than if the receiver has still knowledge of its last position, time and almanac or has still access to valid ephemeris data and the precise time. For more information see [Section 6.8](#).

By default, the GNSS receiver is switched off. It has to be switched on and configured using AT commands. For more information on how to control the GNSS interface via the AT commands see [\[1\]](#).

Dead Reckoning Sync Line:

Dead reckoning solutions are used in (automotive) platforms to determine the (vehicles) location even when there is no GPS signal available (e.g. in tunnels, basement garages or even between high buildings in cities).

In addition to dead reckoning related NMEA sentences (for details see [\[1\]](#): GNSS sentences), PLS8-X/PLS8-V provides a dead reckoning synchronization line (DR_SYNC line) to be employed in external dead reckoning applications. DR_SYNC is derived from the GPS signal clock as 1 pulse per second (1PPS) signal, with a frequency of 1Hz, an accuracy of +/-5 ms, and a high state pulse of 1ms. The DR_SYNC signal is provided as long as synchronized with the GPS satellite clock, and continues for approximately 6 minutes after GPS signal loss. DR_SYNC can be configured for the GPIO1 pad.

DR_SYNC can be activated using the AT command AT^SGPSC. For more information on the command please refer to [\[1\]](#), for electrical characteristics see [Table 22](#).

5 Antenna Interfaces

5.1 GSM/UMTS/LTE Antenna Interface

The PLS8-X/PLS8-V GSM/UMTS/LTE antenna interface comprises a GSM/UMTS/LTE main antenna as well as a UMTS/LTE Rx diversity/MIMO antenna to improve signal reliability and quality¹. The interface has an impedance of 50Ω. PLS8-X/PLS8-V is capable of sustaining a total mismatch at the antenna interface without any damage, even when transmitting at maximum RF power.

The external antennas must be matched properly to achieve best performance regarding radiated power, modulation accuracy and harmonic suppression. Matching networks are not included on the PLS8-X/PLS8-V PCB and should be placed in the host application, if the antenna does not have an impedance of 50Ω.

Regarding the return loss PLS8-X/PLS8-V provides the following values in the active band:

Table 15: Return loss in the active band

| State of module | Return loss of module | Recommended return loss of application |
|-----------------|-----------------------|----------------------------------------|
| Receive | ≥ 8dB | ≥ 12dB |
| Transmit | not applicable | ≥ 12dB |
| Idle | ≤ 5dB | not applicable |

¹. By delivery default the UMTS/LTE Rx diversity/MIMO antenna is configured as available for the module since its usage is mandatory for LTE. Please refer to [1] for details on how to configure antenna settings.

5.1.1 Antenna Installation

The antenna is connected by soldering the antenna pads (ANT_MAIN; ANT_DRX_MIMO) and their neighboring ground pads directly to the application's PCB.

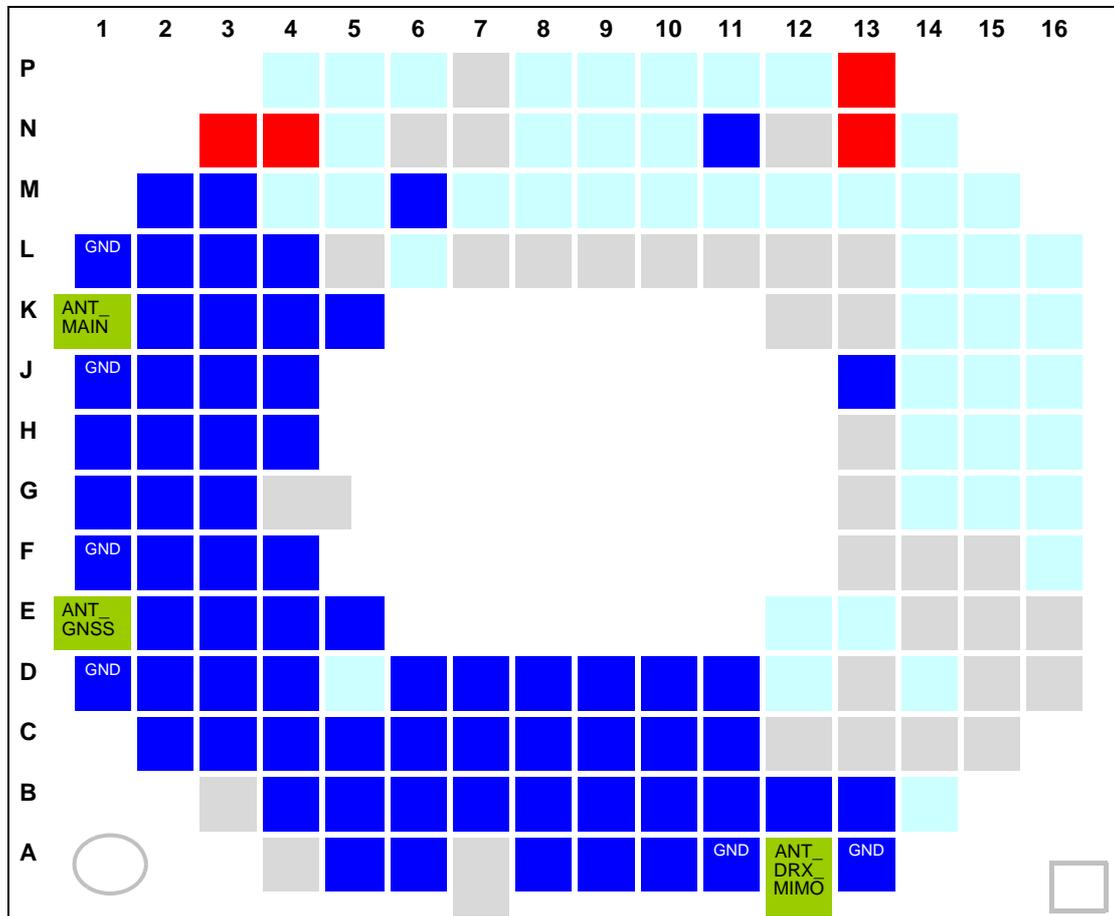


Figure 22: Antenna pads (bottom view)

The distance between the antenna pads and their neighboring GND pads has been optimized for best possible impedance. To prevent mismatch, special attention should be paid to these pads on the application's PCB.

The wiring of the antenna connection, starting from the antenna pad to the application's antenna should result in a 50Ω line impedance. Line width and distance to the GND plane need to be optimized with regard to the PCB's layer stack. Some examples are given in [Section 5.1.2](#).

To prevent receiver desensitization due to interferences generated by fast transients like high speed clocks on the external application PCB, it is recommended to realize the antenna connection line using embedded Stripline rather than Micro-Stripline technology. Please see [Section 5.1.2](#) for examples of how to design the antenna connection in order to achieve the required 50Ω line impedance.

For type approval purposes, the use of a 50Ω coaxial antenna connector (U.FL-R-SMT) might be necessary. In this case the U.FL-R-SMT connector should be placed as close as possible to PLS8-X/PLS8-V's antenna pad.

5.1.2 RF Line Routing Design

5.1.2.1 Line Arrangement Examples

Several dedicated tools are available to calculate line arrangements for specific applications and PCB materials - for example from <http://www.polarinstruments.com/> (commercial software) or from <http://web.awrcorp.com/Usa/Products/Optional-Products/TX-Line/> (free software).

Embedded Stripline

This below figure shows line arrangement examples for embedded stripline.

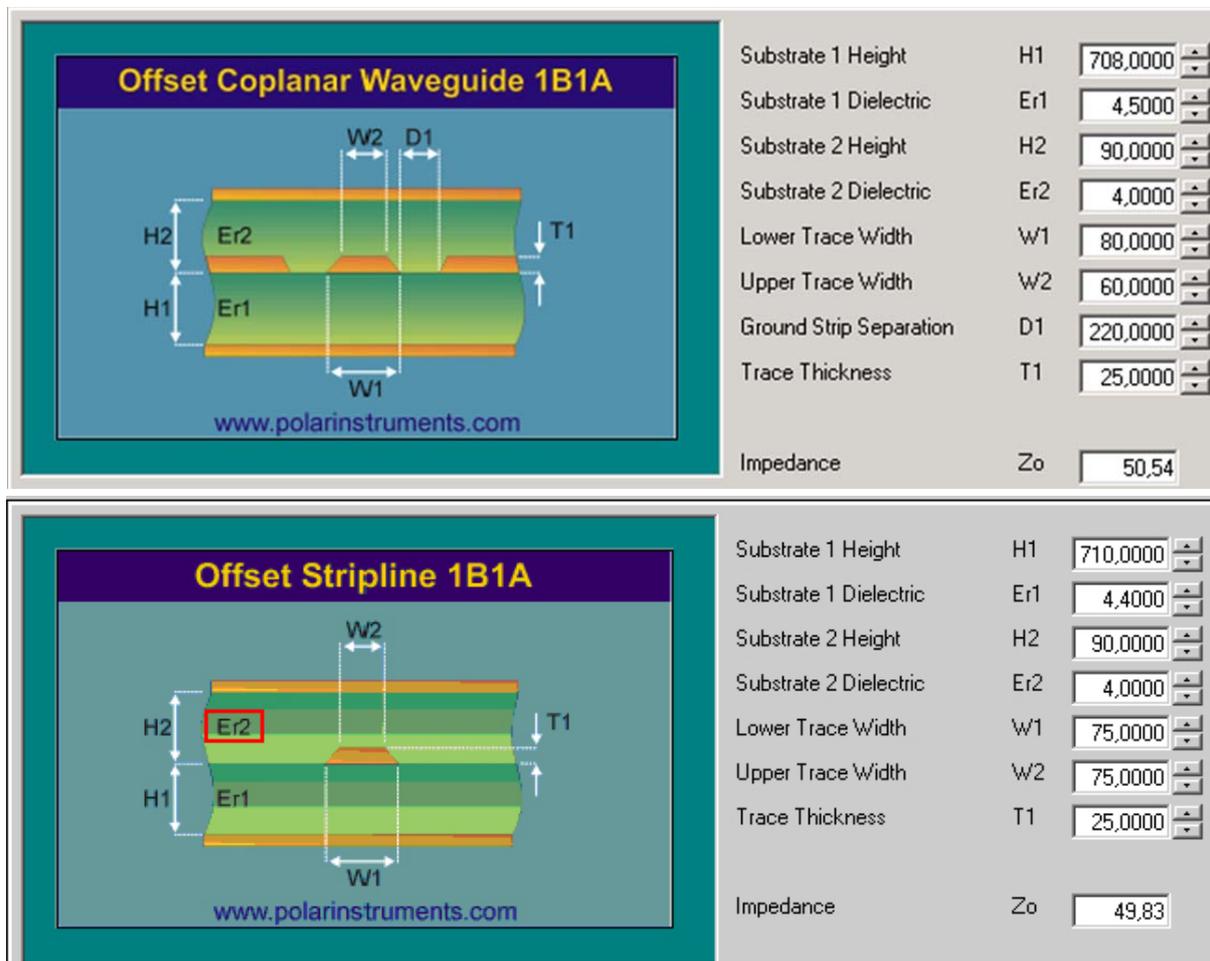


Figure 23: Embedded Stripline line arrangement

Micro-Stripline

This section gives two line arrangement examples for micro-stripline.

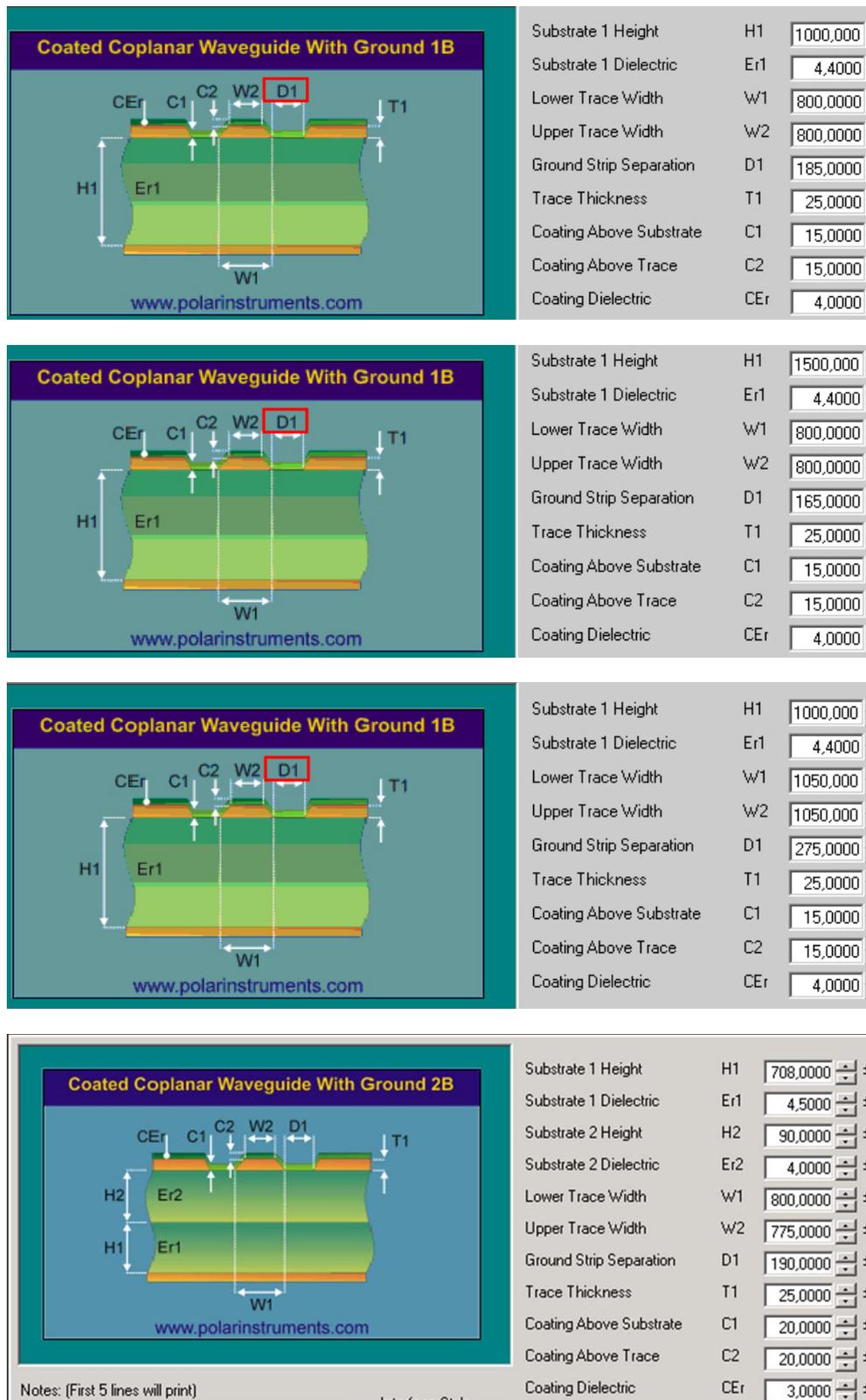


Figure 24: Micro-Stripline line arrangement samples

5.1.2.2 Routing Example

Interface to RF Connector

Figure 25 shows a sample connection of a module's antenna pad at the bottom layer of the module PCB with an application PCB's coaxial antenna connector. Line impedance depends on line width, but also on other PCB characteristics like dielectric, height and layer gap. The sample stripline width of 0.33mm is recommended for an application with a PCB layer stack resembling the one of the PLS8-X/PLS8-V evaluation board shown in Figure 26. For different layer stacks the stripline width will have to be adapted accordingly.

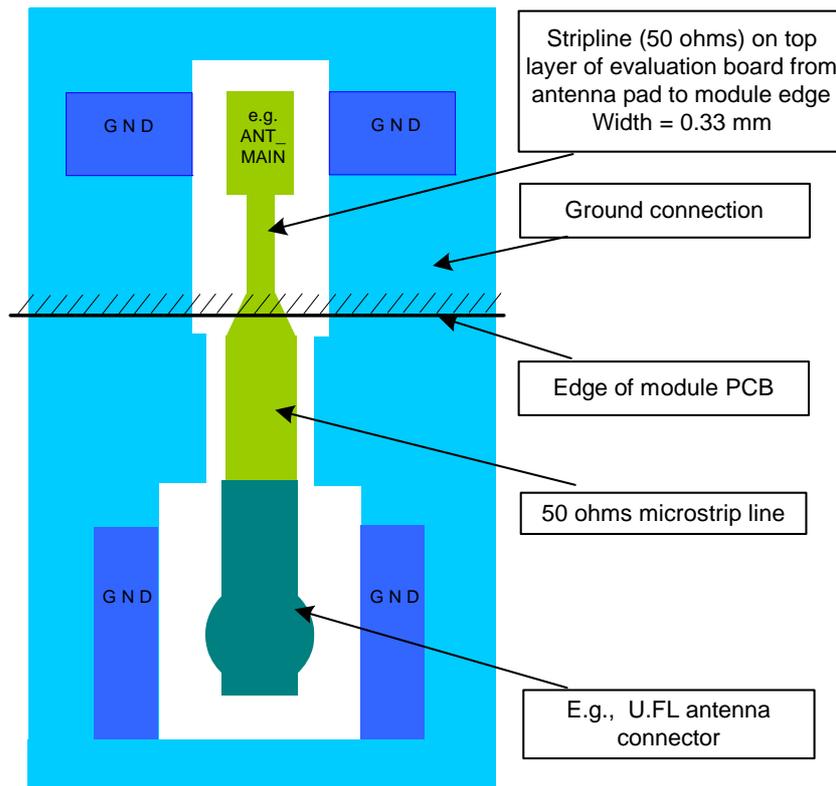


Figure 25: Routing to application's RF connector

| Layer No. | Construction | Finished thickness (um) |
|----------------------------------|-------------------------|-------------------------|
| s/m | | 15 |
| 1 | | 25 |
| | Prepreg :1080X1 RC:64% | 65 |
| 2 | | 25 |
| | CORE:28mil H/Hoz 7628x4 | 708 |
| 3 | | 25 |
| | Prepreg :1080X1 RC:64% | 65 |
| 4 | | 25 |
| s/m | | 15 |
| Total thickness (including S/M): | | 968 |

Figure 26: PLS8-X/PLS8-V evaluation board layer table

5.2 GNSS Antenna Interface

In addition to the RF antenna interface PLS8-X/PLS8-V also has a GNSS antenna interface. See [Section 6.5](#) to find out where the GNSS antenna pad is located. The GNSS pad itself is the same as for the RF antenna interface (see [Section 5.1.1](#)).

It is possible to connect active or passive GNSS antennas. In either case they must have 50Ω impedance. The simultaneous operation of GSM and GNSS is implemented. For electrical characteristics see [Section 6.8](#).

PLS8-X/PLS8-V provides the supply voltage VGNSS for the GNSS active antenna (3.05V). It has to be enabled by software when the GNSS receiver becomes active, otherwise VGNSS should be off (power saving). VGNSS is not short circuit protected. This will have to be provided for by an external application. The DC voltage should be fed back via ANT_GNSS_DC for coupling into the GNSS antenna path. [Figure 27](#) shows the flexibility in realizing the power supply for an active GNSS antenna by giving two sample circuits realizing the supply voltage for an active GNSS antenna - one with short circuit protection and one with an external LDO employed.

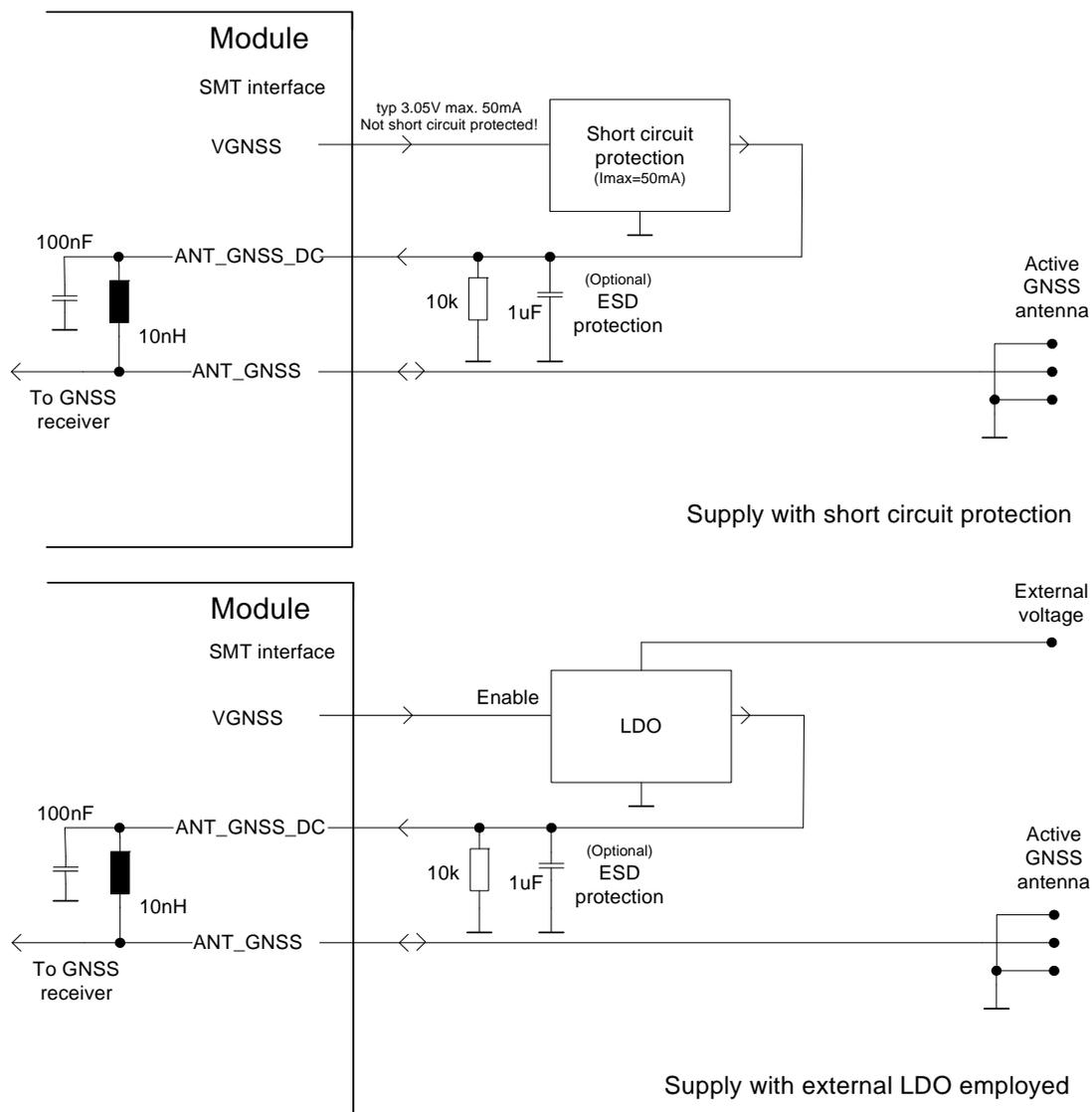


Figure 27: Supply voltage for active GNSS antenna

Figure 28 shows sample circuits realizing ESD protection for a passive GNSS antenna.

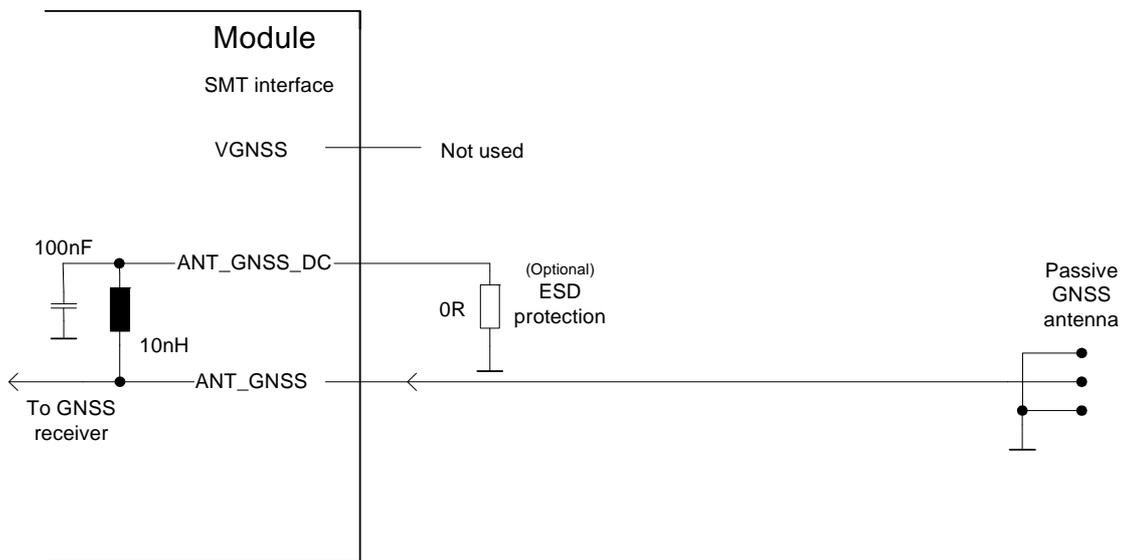


Figure 28: ESD protection for passive GNSS antenna

6 Electrical, Reliability and Radio Characteristics

6.1 Absolute Maximum Ratings

The absolute maximum ratings stated in [Table 16](#) are stress ratings under any conditions. Stresses beyond any of these limits will cause permanent damage to PLS8-X/PLS8-V.

Table 16: Absolute maximum ratings

| Parameter | Min | Max | Unit |
|---------------------------------------------------------------|------|------|------|
| Supply voltage BATT+ | -0.5 | +6.0 | V |
| Voltage at all digital lines in Power Down mode | -0.5 | +0.5 | V |
| Voltage at digital lines in normal operation | -0.5 | +2.3 | V |
| Voltage at SIM/USIM interface, CCVCC 1.8V in normal operation | -0.5 | +2.3 | V |
| Voltage at SIM/USIM interface, CCVCC 3.0V in normal operation | -0.5 | +3.4 | V |
| VDDL input voltage | -0.3 | +3.5 | V |
| Voltage at ADC lines if the module is powered by BATT+ | -0.5 | +3.5 | V |
| Voltage at ADC lines if the module is not powered | -0.5 | +0.5 | V |
| VEXT maximum current shorted to GND | | -300 | mA |
| VUSB_IN, USB_DN, USB_DP | -0.3 | 5.75 | V |
| Voltage at PWR_IND line | -0.5 | 5.5 | V |
| PWR_IND input current if PWR_IND= low | | 2 | mA |
| Voltage at following signals: IGT, EMERG_OFF | -0.5 | 2.5 | V |
| GNSS antenna supply VGNSS | | 300 | mA |

6.2 Operating Temperatures

Table 17: Board temperature

| Parameter | Min | Typ | Max | Unit |
|---------------------------------------------|------|-----|------|------|
| Operating temperature range ¹ | | | | |
| Normal temperature range | +15 | +25 | +55 | °C |
| Extreme temperature range | -30 | | +85 | °C |
| Extended temperature range ² | -40 | | +95 | °C |
| Automatic shutdown ³ | | | | |
| Temperature measured on PLS8-X/PLS8-V board | <-40 | --- | >+95 | °C |

- ¹. Operating temperature range according to 3GPP type approval specification.
- ². Extended operation allows normal mode data transmissions for limited time until automatic thermal shut-down takes effect.
Within the extended temperature range (outside the operating temperature range) there should not be any unrecoverable malfunctioning. General performance parameters like Pout or RX sensitivity however may be reduced in their values. The module's life time may also be affected, if deviating from a general temperature allocation model (for details see [Section 6.2.1](#)).
- ³. Due to temperature measurement uncertainty, a tolerance on the stated shutdown thresholds may occur. The possible deviation is in the range of ± 2°C at the overtemperature and undertemperature limit.

See also [Section 3.3.5](#) for information about the NTC for on-board temperature measurement, automatic thermal shutdown and alert messages.

Note that within the specified operating temperature ranges the board temperature may vary to a great extent depending on operating mode, used frequency band, radio output power and current supply voltage. Note also the differences and dependencies that usually exist between board (PCB) temperature and ambient temperature as shown in the following [Figure 29](#). The possible ambient temperature range depends on the mechanical application design including the module and the PCB with its size and layout. A thermal solution will have to take these differences into account and should therefore be an integral part of application design.

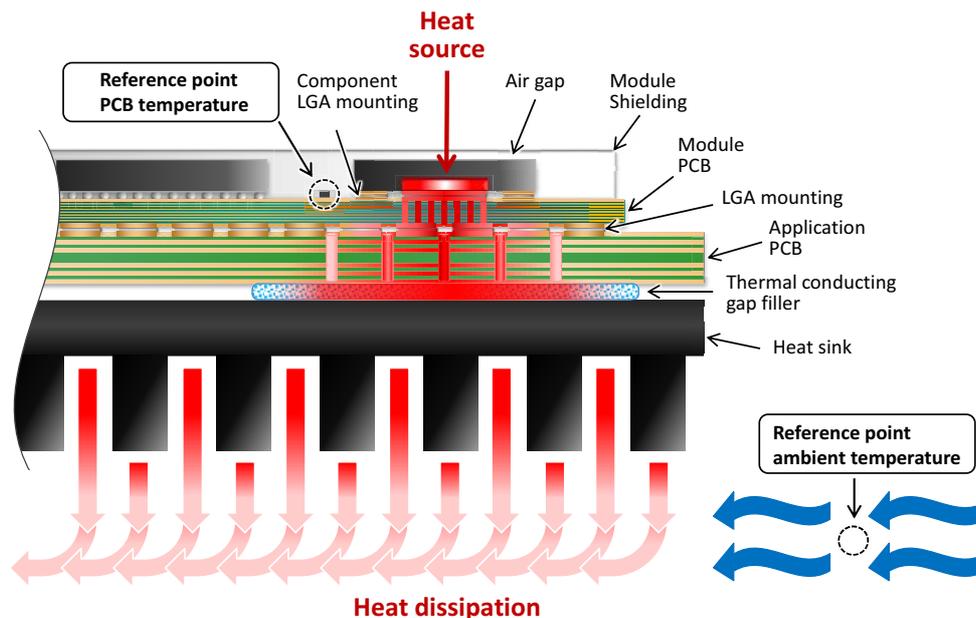


Figure 29: Board and ambient temperature differences

6.3 Storage Conditions

6.2.1 Temperature Allocation Model

The temperature allocation model shown in [Table 18](#) assumes shares of a module's average lifetime of 10 years (given in %) during which the module is operated at certain temperatures.

Table 18: Temperature allocation model

| | | | | | | | | |
|-------------------------------------------|-----|-----|-----|----|----|----|----|----|
| Module lifetime share (in %) ¹ | 1 | 1 | 5 | 53 | 35 | 3 | 1 | 1 |
| Module Temperature (in °C) | -40 | -30 | -10 | 20 | 40 | 70 | 85 | 95 |

¹. Based on an assumed average module lifetime of 10 years (=100%).

Any deviations from the above temperature allocation model may reduce the module's life span, for example if the module is operated close to the maximum automatic shutdown temperature not only for 1% but for 20% of its product life.

6.3 Storage Conditions

The conditions stated below are only valid for modules in their original packed state in weather protected, non-temperature-controlled storage locations. Normal storage time under these conditions is 12 months maximum. The modules will be delivered in a packaging that meets the requirements according "IPD/JEDEC J-STD-033B.1" for Low Temperature Carriers.

Table 19: Storage conditions

| Type | Condition | Unit | Reference |
|--------------------------------------------------------------------------|----------------------------|------------------------------|------------------------------------------------------------------------------------|
| Humidity relative: Low High | 10 90 at 40°C | % | CbIPC/JEDEC J-STD-033A |
| Air pressure: Low High | 70 106 | kPa | IEC TR 60271-3-1: 1K4 IEC TR 60271-3-1: 1K4 |
| Movement of surrounding air | 1.0 | m/s | IEC TR 60271-3-1: 1K4 |
| Water: rain, dripping, icing and frosting | Not allowed | --- | --- |
| Radiation: Solar Heat | 1120 600 | W/m ² | ETS 300 019-2-1: T1.2, IEC 60068-2-2 Bb ETS 300 019-2-1: T1.2, IEC 60068-2-2 Bb |
| Chemically active substances | Not recommended | | IEC TR 60271-3-1: 1C1L |
| Mechanically active substances | Not recommended | | IEC TR 60271-3-1: 1S1 |
| Vibration sinusoidal: Displacement Acceleration Frequency range | 1.5 5 2-9 9-200 | mm m/s ² Hz | IEC TR 60271-3-1: 1M2 |
| Shocks: Shock spectrum Duration Acceleration | Semi-sinusoidal 1 50 | ms m/s ² | IEC 60068-2-27 Ea |

6.4 Reliability Characteristics

The test conditions stated below are an extract of the complete test specifications.

Table 20: Summary of reliability test conditions

| Type of test | Conditions | Standard |
|----------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------|
| Vibration | Frequency range: 10-20Hz; acceleration: 5g Frequency range: 20-500Hz; acceleration: 20g Duration: 20h per axis; 3 axes | DIN IEC 60068-2-6 ¹ |
| Shock half-sinus | Acceleration: 500g Shock duration: 1ms 1 shock per axis 6 positions (\pm x, y and z) | DIN IEC 60068-2-27 |
| Dry heat | Temperature: $+70 \pm 2^\circ\text{C}$ Test duration: 16h Humidity in the test chamber: $< 50\%$ | EN 60068-2-2 Bb ETS 300 019-2-7 |
| Temperature change (shock) | Low temperature: $-40 \pm 2^\circ\text{C}$ High temperature: $+85 \pm 2^\circ\text{C}$ Changeover time: $< 30\text{s}$ (dual chamber system) Test duration: 1h Number of repetitions: 100 | DIN IEC 60068-2-14 Na ETS 300 019-2-7 |
| Damp heat cyclic | High temperature: $+55 \pm 2^\circ\text{C}$ Low temperature: $+25 \pm 2^\circ\text{C}$ Humidity: $93\% \pm 3\%$ Number of repetitions: 6 Test duration: 12h + 12h | DIN IEC 60068-2-30 Db ETS 300 019-2-5 |
| Cold (constant exposure) | Temperature: $-40 \pm 2^\circ\text{C}$ Test duration: 16h | DIN IEC 60068-2-1 |

¹. For reliability tests in the frequency range 20-500Hz the Standard's acceleration reference value was increased to 20g.

6.4.1 Bending Tests

From experience with other modules an elongation of up to 200µm/m is acceptable for PLS8-X/PLS8-V modules as a result of bending strains.

Tests (based on EN 60068-2-21) showed that if applying a force of 10N at the middle of the module, i.e., the evaluation module with the actual PLS8-X/PLS8-V module soldered onto the evaluation PCB as shown in [Figure 30](#), the possible elongation is clearly below the value of 200µm/m. Therefore, a force of 10N is recommended as maximum force.

Please note that these values only apply for a one-off short stress. The module will have to be mounted free of any strains and without being exposed to dynamic pressures.

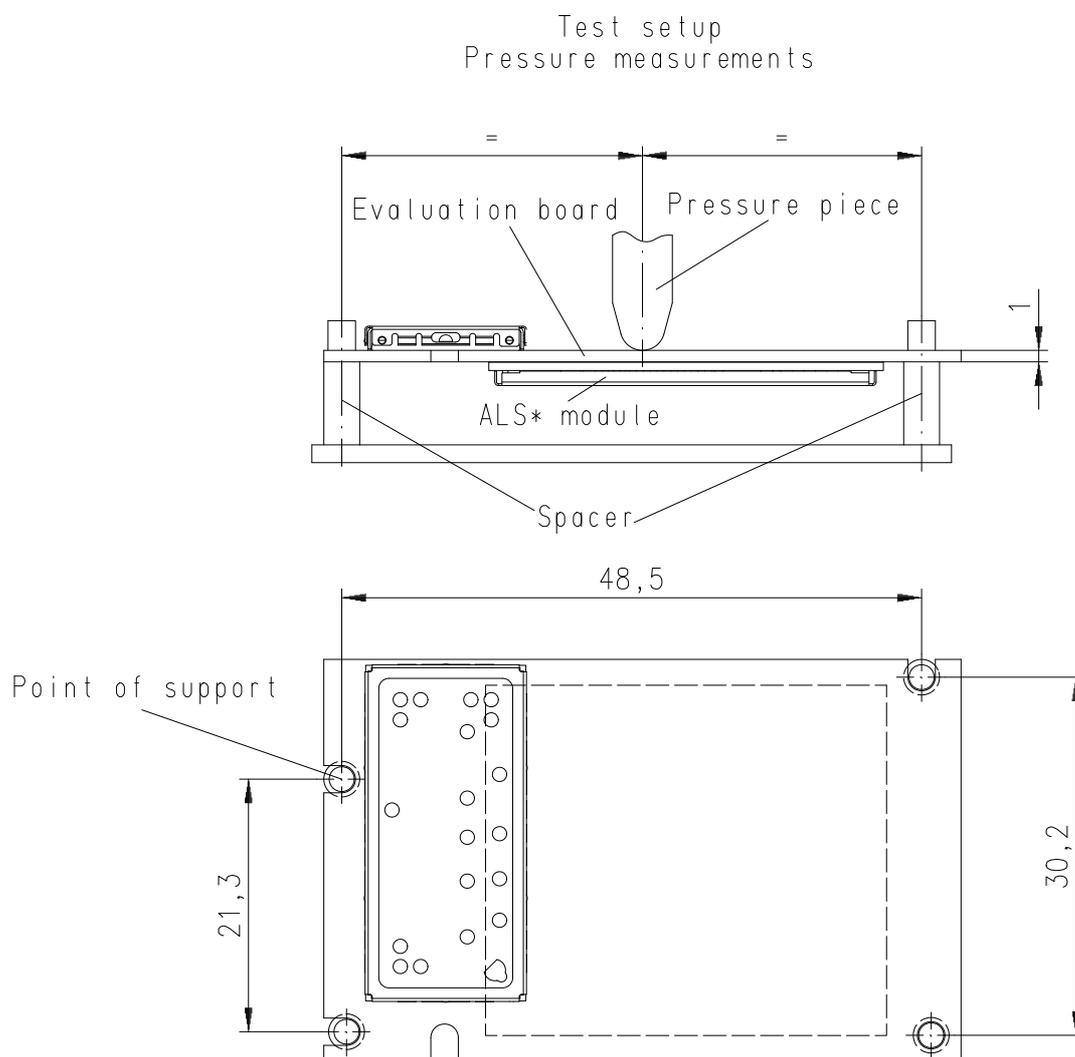


Figure 30: Bending test setup

6.5 Pad Assignment and Signal Description

The SMT application interface on the PLS8-X/PLS8-V provides connecting pads to integrate the module into external applications. [Table 21](#) lists the pads' assignments. [Figure 31](#) (bottom view) and [Figure 32](#) (top view) show the connecting pads' numbering plan.

Please note that pads marked "rfu" (reserved for future use) and further qualified as "dnu" (do not use) may be soldered but should not be connected to an external application. Pads marked "rfu" and qualified as "GND" (ground) are assigned to ground with PLS8-X/PLS8-V modules, but may have different assignments with future Gemalto M2M products using the same pad layout.

Gemalto strongly recommends to solder all connecting pads for mechanical stability and heat dissipation.

6.5 Pad Assignment and Signal Description

Table 21: Overview: Pad assignments¹

| Pad No. | Signal Name | Pad No. | Signal Name | Pad No. | Signal Name |
|---------|--------------|---------|-------------|---------|-------------|
| A4 | nc | E2 | GND | L2 | GND |
| A5 | GND | E3 | GND | L3 | GND |
| A6 | GND | E4 | GND | L4 | GND |
| A7 | rfu (dnu) | E5 | GND | L5 | rfu (dnu) |
| A8 | GND | E12 | CCIO2 | L6 | CCVCC2 |
| A9 | GND | E13 | CCRST2 | L7 | rfu (dnu) |
| A10 | GND | E14 | rfu (dnu) | L8 | rfu (dnu) |
| A11 | GND | E15 | rfu (dnu) | L9 | rfu (dnu) |
| A12 | ANT_DRX_MIMO | E16 | rfu (dnu) | L10 | rfu (dnu) |
| A13 | GND | F1 | GND | L11 | rfu (dnu) |
| B3 | nc | F2 | GND | L12 | rfu (dnu) |
| B4 | GND | F3 | GND | L13 | rfu (dnu) |
| B5 | GND | F4 | GND | L14 | CCRST1 |
| B6 | GND | F13 | rfu (dnu) | L15 | CCCLK1 |
| B7 | GND | F14 | rfu (dnu) | L16 | IGT |
| B8 | GND | F15 | rfu (dnu) | M2 | GND |
| B9 | GND | F16 | GPIO10 | M3 | GND |
| B10 | GND | G1 | GND | M4 | PWR_IND |
| B11 | GND | G2 | GND | M5 | VEXT |
| B12 | GND | G3 | GND | M6 | GND |
| B13 | GND | G4 | rfu (dnu) | M7 | PCM_I2S_IN |
| B14 | STATUS | G13 | rfu (dnu) | M8 | PCM_I2S_CLK |
| C2 | GND | G14 | GPIO7 | M9 | PCM_I2S_FSC |
| C3 | GND | G15 | GPIO8 | M10 | PCM_I2S_OUT |
| C4 | GND | G16 | GPIO9 | M11 | ADC3_IN |
| C5 | GND | H1 | GND | M12 | ADC2_IN |
| C6 | GND | H2 | GND | M13 | ADC1_IN |
| C7 | GND | H3 | GND | M14 | CCIN1 |
| C8 | GND | H4 | GND | M15 | VDDL |
| C9 | GND | H13 | rfu (dnu) | N3 | BATT+_RF |
| C10 | GND | H14 | GPIO4 | N4 | BATT+_RF |
| C11 | GND | H15 | GPIO5 | N5 | VUSB_IN |
| C12 | rfu (dnu) | H16 | GPIO6 | N6 | rfu (dnu) |
| C13 | rfu (dnu) | J1 | GND | N7 | rfu (dnu) |
| C14 | rfu (dnu) | J2 | GND | N8 | CTS0 |
| C15 | rfu (dnu) | J3 | GND | N9 | DCD0 |
| D1 | GND | J4 | GND | N10 | RTS0 |
| D2 | GND | J13 | GND | N11 | GND |
| D3 | GND | J14 | GPIO1 | N12 | rfu (dnu) |
| D4 | GND | J15 | GPIO2 | N13 | BATT+ |
| D5 | ANT_GNSS_DC | J16 | GPIO3 | N14 | EMERG_OFF |
| D6 | GND | K1 | ANT_MAIN | P4 | USB_DP |
| D7 | GND | K2 | GND | P5 | USB_DN |
| D8 | GND | K3 | GND | P6 | I2S_MCLKOUT |
| D9 | GND | K4 | GND | P7 | rfu (dnu) |
| D10 | GND | K5 | GND | P8 | DTR0 |
| D11 | GND | K12 | rfu (dnu) | P9 | DSR0 |
| D12 | CCIN2 | K13 | rfu (dnu) | P10 | RING0 |
| D13 | rfu (dnu) | K14 | CCIO1 | P11 | RXD0 |
| D14 | CCCLK2 | K15 | CCVCC1 | P12 | TXD0 |
| D15 | rfu (dnu) | K16 | VGNSS | P13 | BATT+ |
| D16 | rfu (dnu) | L1 | GND | | |
| E1 | ANT_GNSS | | | | |

¹: nc = not connected; rfu = reserved for future use; dnu = do not use

6.5 Pad Assignment and Signal Description

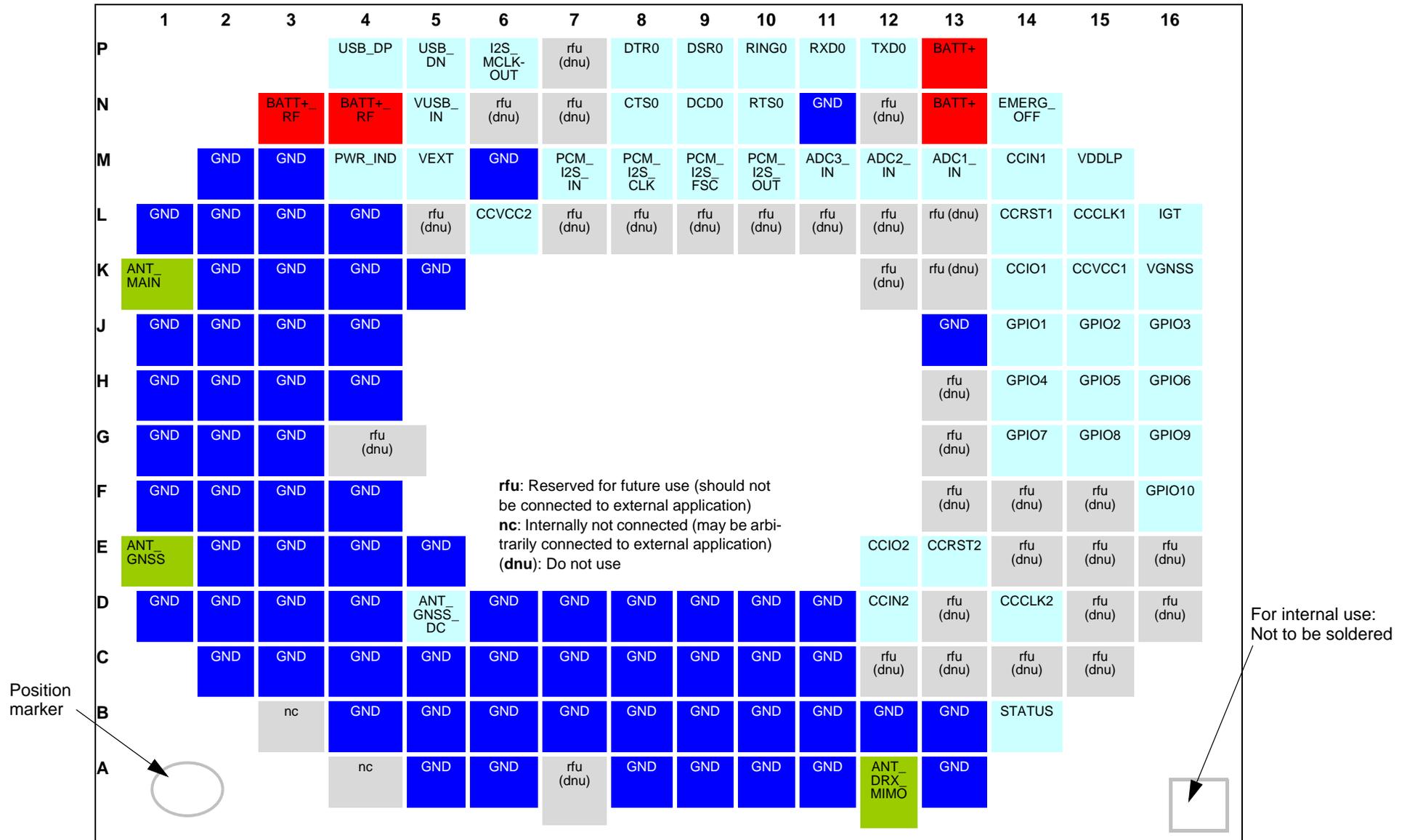


Figure 31: PLS8-X/PLS8-V bottom view: Pad assignments

6.5 Pad Assignment and Signal Description

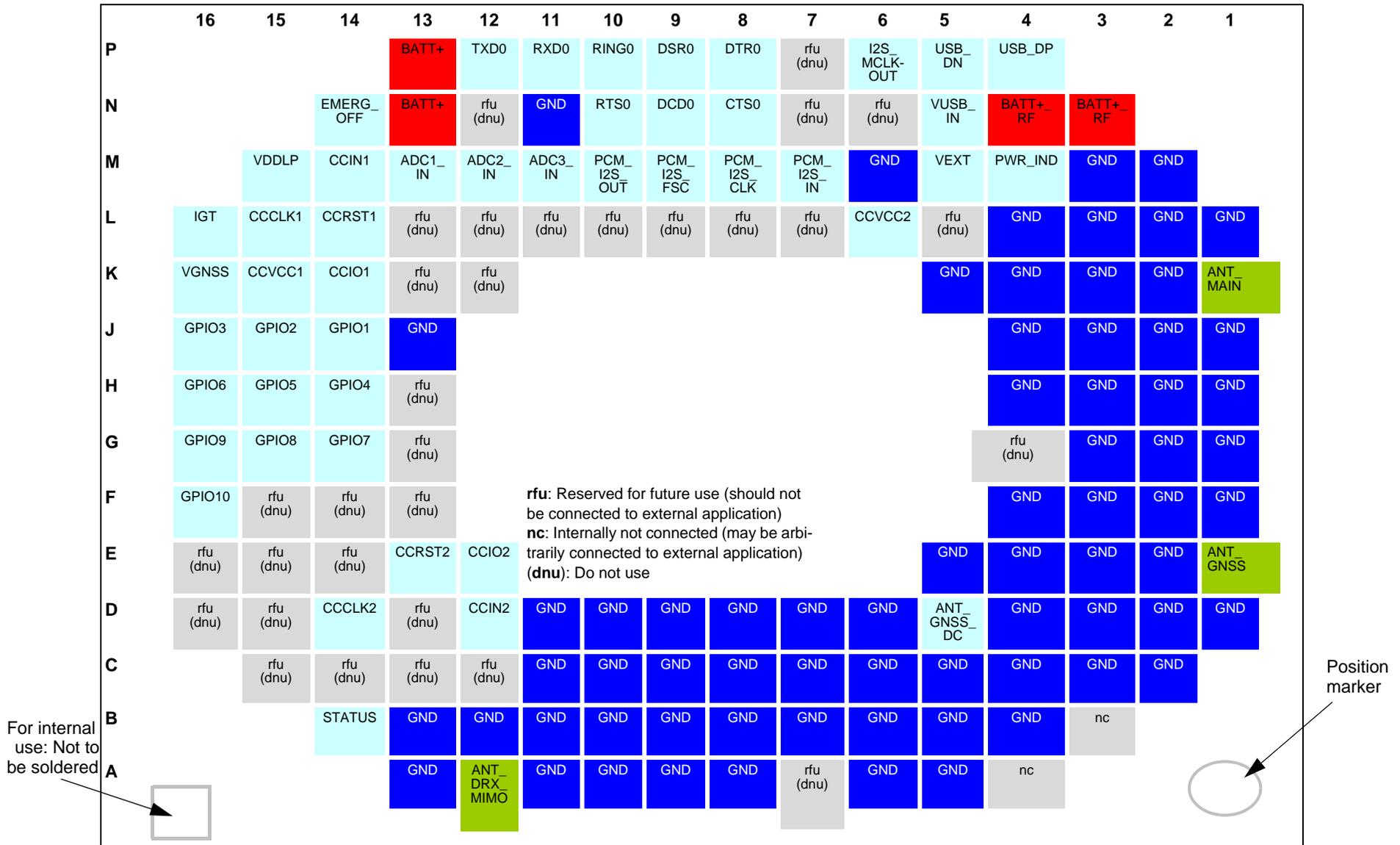


Figure 32: PLS8-X/PLS8-V top view: Pad assignments

6.5 Pad Assignment and Signal Description

Please note that the reference voltages listed in [Table 22](#) are the values measured directly on the PLS8-X/PLS8-V module. They do not apply to the accessories connected.

Table 22: Signal description

| Function | Signal name | IO | Signal form and level | Comment |
|-------------------------------------------------|-------------|----|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Power supply | BATT+_RF | I | $V_{I,max} = 4.2V$ $V_{I,norm} = 3.8V$ $V_{I,min} = 3.3V$ during Tx burst on board $I_{max} \approx 2A$, during Tx burst (GSM)  $n \text{ Tx} = n \times 577\mu s$ peak current every 4.615ms | Lines of BATT+ and GND must be connected in parallel for supply purposes because higher peak currents may occur. Minimum voltage must not fall below 3.3V including drop, ripple, spikes. |
| | BATT+ | I | $V_{I,max} = 4.2V$ $V_{I,norm} = 3.8V$ $V_{I,min} = 3.3V$ during Tx burst on board $I_{max} = 350mA$ | For proper module power up the voltage at BATT+ must be greater than at VDDL P. |
| Power supply | GND | | Ground | Application Ground |
| External supply voltage | VEXT | O | $CL_{max} = 1\mu F$ $V_O = 1.80V +1\% -5\%$ $I_{O,max} = -50mA$ | VEXT may be used for application circuits. If unused keep line open. The external digital logic must not cause any spikes or glitches on voltage VEXT. Do not exceed IOmax |
| Supply voltage for active GNSS antenna (Output) | VGNSS | O | $CL_{max} = 2.2\mu$ $V_O = 3.05V \pm 1\%$ $@I_O = -20mA$ $I_{O,max} = -50mA$ | Available if GNSS antenna DC power is enabled (configurable by AT command; see Section 6.8). |
| Supply voltage for active GNSS antenna (Input) | ANT_GNSS_DC | I | $V_{I,max} = 6V$ The input current has to be limited at 50mA (antenna short circuit protection) | If unused connect to GND. |
| Ignition | IGT | I | $R_{PU} \approx 200k\Omega$ $V_{OH,max} = 1.8V$ $V_{IH,max} = 2.1V$ $V_{IH,min} = 1.17V$ $V_{IL,max} = 300mV$ Low impulse width > 100ms | This signal switches the module ON. It is recommended to drive this line low by an open drain or open collector driver connected to GND. |
| Emergency off | EMERG_OFF | I | $R_{PU} \approx 40k\Omega$ $V_{OH,max} = 1.8V$ $V_{IH,max} = 2.1V$ $V_{IH,min} = 1.17V$ $V_{IL,max} = 300mV$  low impulse width > 40ms | It is recommended to drive this line low by an open drain or open collector driver connected to GND. If unused keep line open. |

6.5 Pad Assignment and Signal Description

Table 22: Signal description

| Function | Signal name | IO | Signal form and level | Comment |
|-------------------------|------------------|-----|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| RTC backup | VDDL | O | $V_{OLmax} = 3.20V$ while BATT+ =>3.3V $R_I = 1.8k\Omega$ | If unused keep line open. |
| | | I | $V_I = 1.5V...3.25V$ at $I_{max} = 10\mu A$ while BATT+ = 0V | |
| Connectivity status | STATUS | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | Status signalling e.g. with ext. LED circuit |
| SIM card detection (2x) | CCIN1 | I | $R_{PU} \approx 24.2k\Omega$ $V_{OHmax} = 1.9V$ $V_{IHmin} = 1.15V$ $V_{IHmax} = 1.9V$ $V_{ILmax} = 0.4V$ | CCINx = Low, SIM card inserted. If SIM card holder does not support CCIN, connect to GND. |
| | CCIN2 | I | $V_{IHmin} = 1.15V$ $V_{IHmax} = 2.1V$ $V_{ILmax} = 0.63V$ $I_{IHPD} = 27.5\mu A...97.5\mu A$ | CCIN2: External pull-up required - for details please refer to Section 3.8 . If 2 nd SIM interface not used, keep line open. |
| 3V SIM card interface | CCRST1 CCRST2 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 2.57V$ at $I = -2mA$ $V_{OHmax} = 3.08V$ | Maximum cable length or copper track should be not longer than 100mm to SIM card holder. CCIO2: External 10k Ω pull-up required - for details please refer to Section 3.8 . If 2 nd SIM interface not used, keep lines open. |
| | CCIO1 CCIO2 | I/O | $R_{PU} \approx 4.8...9.5k\Omega$ $V_{ILmax} = 0.76V$ $V_{ILmin} = -0.3V$ $V_{IHmin} = 1.98V$ $V_{IHmax} = 3.35V$ $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 2.57V$ at $I = -0.05mA$ $V_{OHmax} = 3.08V$ | |
| | CCCLK1 CCCLK2 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 2.57V$ at $I = -2mA$ $V_{OHmax} = 3.08V$ | |
| | CCVCC1 CCVCC2 | O | $V_{Omin} = 3.0V$ $V_{Otyp} = 3.05V$ $V_{Omax} = 3.08V$ $I_{Omax} = -50mA$ | |

6.5 Pad Assignment and Signal Description

Table 22: Signal description

| Function | Signal name | IO | Signal form and level | Comment |
|-----------------------------|------------------|-----|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1.8V SIM card interface | CCRST1 CCRST2 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | Maximum cable length or copper track should be not longer than 100mm to SIM card holder. CCIO2: External 10k Ω pull-up required - for details please refer to Section 3.8 . If 2 nd SIM interface not used, keep lines open. |
| | CCIO1 CCIO2 | I/O | $R_I \approx 4.8...9.5k\Omega$ $V_{ILmax} = 0.62V$ $V_{ILmin} = -0.3V$ $V_{IHmin} = 1.20V$ $V_{IHmax} = 2.1V$ $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.32V$ at $I = -0.05mA$ $V_{OHmax} = 1.82V$ | |
| | CCCLK1 CCCLK2 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.32V$ at $I = -2mA$ $V_{OHmax} = 1.82V$ | |
| | CCVCC1 CCVCC2 | O | $V_{Omin} = 1.75V$ $V_{Otyp} = 1.80V$ $V_{Omax} = 1.82V$ $I_{Omax} = -50mA$ | |
| Serial Modem Interface ASC0 | RXD0 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | If unused keep line open. |
| | CTS0 | O | | |
| | DSR0 | O | | |
| | DCD0 | O | | |
| | RING0 | O | | |
| | TXD0 | I | $V_{ILmax} = 0.6V$ at $30\mu A$ $V_{IHmin} = 1.20V$ at $-30\mu A$ $V_{IHmax} = 2V$ | |
| | RTS0 | I | | |
| | DTR0 | I | | |
| Power indicator | PWR_IND | O | $V_{IHmax} = 5.5V$ $V_{OLmax} = 0.4V$ at $I_{max} = 1mA$ | PWR_IND (Power Indicator) notifies the module's on/off state. PWR_IND is an open collector that needs to be connected to an external pull-up resistor. Low state of the open collector indicates that the module is on. Vice versa, high level notifies the Power Down mode. Therefore, signal may be used to enable external voltage regulators that supply an external logic for communication with the module, e.g. level converters. |
| Host wakeup | RING0 | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | If unused keep line open. |

6.5 Pad Assignment and Signal Description

Table 22: Signal description

| Function | Signal name | IO | Signal form and level | Comment |
|---------------------------------------------------|-----------------------------------------------------------------------------------------|-----|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| USB | VUSB_IN | I | $V_{INmin} = 3.0V$ $V_{INmax} = 5.25V$ $I_{typ} = 150\mu A$ $I_{max} = 200\mu A$ $C_{in} = 1\mu F$ In case of $V_{ripple} \geq 10mV_{pp}$ (with $f > 300kHz$), and V_{BUS_IN} driven in the voltage range 4.08V...4.11V, use of an RC filter 1k Ω /100nF is required. | If the USB interface is not used please connect this line to GND. Since VUSB_IN is used for detection only it is recommended not to add any further blocking capacitors on the VUSB_IN line. |
| | USB_DN | I/O | All electrical characteristics according to USB Implementers' Forum, USB 2.0 High Speed Specification. | Keep lines open if VUSB_IN connects to GND. |
| | USB_DP | I/O | | USB High Speed mode operation requires a differential impedance of 90 Ω . |
| Digital audio interface (PCM or I ² S) | PCM_I2S_IN | I | $V_{ILmax} = 0.6V$ at 30 μA $V_{IHmin} = 1.20V$ at -30 μA $V_{IHmax} = 2V$ $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | PCM Master/Slave mode. I ² S Master mode. |
| | PCM_I2S_CLK | I/O | | If unused keep lines open. |
| | PCM_I2S_FSC | I/O | | Available for local tones only - see Section 3.9 . |
| | PCM_I2S_OUT | O | | |
| | I2S_MCLKOUT | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ $F = 2048kHz$ (at 8kHz sample rate) $F = 4096kHz$ (at 16kHz sample rate) | Master clock option for audio codecs without PLL. If unused keep line open. |
| GPIO interface | GPIO1 GPIO2 GPIO3 GPIO4 GPIO5 GPIO6 GPIO7 GPIO8 GPIO9 GPIO10 | I/O | $V_{ILmax} = 0.6V$ at 30 μA $V_{IHmin} = 1.20V$ at -30 μA $V_{IHmax} = 2V$ $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | If unused keep lines open. Following functions can be configured for GPIOs using AT commands: GPIO1 --> Dead reckoning synchronization GPIO2 --> 700MHz antenna control switch Any GPIO --> Low current indication. By default GPIO6 is configured as LCI line. Any GPIO --> Remote host wakeup line |
| Dead reckoning synchronization | GPIO1 (DR_SYNC) | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | 1 pulse per second dead reckoning synchronization signal for usage in external dead reckoning applications (see Chapter 4). |
| 700MHz antenna control switch | GPIO2 (ANT_SWITCH) | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | Line can be configured as a control signal for a possible external 700MHz antenna switch (see Section 3.13.6). |

6.5 Pad Assignment and Signal Description

Table 22: Signal description

| Function | Signal name | IO | Signal form and level | Comment |
|------------------------|---------------------------------|----|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|
| Low Current Indication | GPIOx | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | If the feature is enabled (see Section 3.13.4). |
| | | I | $V_{IHmax} = 2V$ $R_{PD} = \text{appr. } 100k\Omega$ | If the feature is disabled (see Section 3.13.4). |
| Remote host wakeup | GPIOx | O | $V_{OLmax} = 0.45V$ at $I = 2mA$ $V_{OHmin} = 1.35V$ at $I = -2mA$ $V_{OHmax} = 1.85V$ | If feature is enabled (see Section 3.13.3). |
| ADC interface | ADC1_IN, ADC2_IN, ADC3_IN | I | Full specification compliance range $V_{Imin} \geq 0.3V$ $V_{Imax} \leq 3.075V$ Degraded accuracy range $V_{Imin} = 0.05V \dots 0.3V$ $R_{idc} > 1M\Omega$ Resolution: 12 Bit Offset error: $< \pm 10mV$ Gain error: $< 1\%$ analog bandwidth: $< 16kHz$ conversion time: $853\mu s$ | If unused keep line open. |

6.6 Power Supply Ratings

6.6 Power Supply Ratings

Table 23 and Table 24 assemble various voltage supply and current consumption ratings of the module.

Table 23: Voltage supply ratings

| | Description | Conditions | Min | Typ | Max | Unit |
|-------|----------------------------------------------------|---------------------------------------------------------------------------------------------------------------------|-----|-----|-----------|--------------------------------------|
| BATT+ | Supply voltage | Directly measured at Module. Voltage must stay within the min/max values, including voltage drop, ripple, spikes | 3.3 | 3.8 | 4.2 | V |
| | Maximum allowed voltage drop during transmit burst | Normal condition, power control level for Pout max | | | 400 | mV |
| | Voltage ripple | Normal condition, power control level for Pout max @ f <= 250 kHz @ f > 250 kHz | | | 120 90 | mV _{pp} mV _{pp} |

Table 24: Current consumption ratings¹

| | Description | Conditions | Typical rating | Unit | |
|---------------------------------|-----------------------------------------------|--------------------------------------------------------|-------------------------|------|----|
| I _{VDDL} @ 3V | OFF State supply current | Power down | 4 | μA | |
| I _{BATT+} ² | OFF State supply current | Power Down | 40 | μA | |
| | Average GSM / GPRS supply current (GNSS off) | SLEEP ³ @ DRX=9 (no communication via UART) | USB disconnected | 2.0 | mA |
| | | SLEEP ³ @ DRX=5 (no communication via UART) | USB disconnected | 2.5 | mA |
| | | SLEEP ³ @ DRX=2 (no communication via UART) | USB disconnected | 3.7 | mA |
| | | IDLE @ DRX=2 UART active, but no communication | USB disconnected | 40 | mA |
| | | | USB active | 50 | mA |
| | | Voice call GSM850/900; PCL=5 | @50Ω | 330 | mA |
| | | GPRS Data transfer GSM850/900; PCL=5; 1Tx/4Rx | ROPR=8 (max. reduction) | 320 | mA |
| | | | ROPR=4 (no reduction) | | |
| | | GPRS Data transfer GSM850/900; PCL=5; 2Tx/3Rx | ROPR=8 (max. reduction) | 430 | mA |
| | | | ROPR=4 (no reduction) | 540 | |
| | GPRS Data transfer GSM850/900; PCL=5; 4Tx/1Rx | ROPR=8 (max. reduction) | 600 | mA | |
| ROPR=4 (no reduction) | | 930 | | | |
| @ total mismatch | | 990 | | | |

6.6 Power Supply Ratings

Table 24: Current consumption ratings¹

| | Description | Conditions | Typical rating | Unit | |
|-------------------------------------------------------|----------------------------------------------|-------------------------------------------------------------------------|----------------------------|------|----|
| I_{BATT+}^2 | Average GSM / GPRS supply current (GNSS off) | EDGE Data transfer GSM850/900; PCL=5; 1Tx/ 4Rx | ROPR=8 (max. reduction) | 220 | mA |
| | | | ROPR=4 (no reduction) | | |
| | | EDGE Data transfer GSM850/900; PCL=5; 2Tx/ 3Rx | ROPR=8 (max. reduction) | 300 | mA |
| | | | ROPR=4 (no reduction) | 340 | |
| | | EDGE Data transfer GSM850/900; PCL=5; 4Tx/ 1Rx | ROPR=8 (max. reduction) | 490 | mA |
| | | | ROPR=4 (no reduction) | 570 | |
| | | Voice call GSM1800/1900; PCL=0 | @50Ω | 240 | mA |
| | | GPRS Data transfer GSM1800/1900; PCL=0; 1Tx/4Rx | ROPR=8 (max. reduction) | 230 | mA |
| | | | ROPR=4 (no reduction) | | |
| | | GPRS Data transfer GSM1800/1900; PCL=0; 2Tx/3Rx | ROPR=8 (max. reduction) | 300 | mA |
| | | | ROPR=4 (no reduction) | 360 | |
| | | GPRS Data transfer GSM1800/1900; PCL=0; 4Tx/1Rx | ROPR=8 (max. reduction) | 410 | mA |
| | | | ROPR=4 (no reduction) | 590 | |
| | | EDGE Data transfer GSM1800/1900; PCL=0; 1Tx/4Rx | ROPR=8 (max. reduction) | 190 | mA |
| | | | ROPR=4 (no reduction) | | |
| | | EDGE Data transfer GSM1800/1900; PCL=0; 2Tx/3Rx | ROPR=8 (max. reduction) | 250 | mA |
| ROPR=4 (no reduction) | 290 | | | | |
| EDGE Data transfer GSM1800/1900; PCL=0; 4Tx/1Rx | ROPR=8 (max. reduction) | 380 | mA | | |
| | ROPR=4 (no reduction) | 460 | | | |
| Peak current during GSM transmit burst | Voice call GSM850/900; PCL=5 | @50Ω | 2.1 | A | |
| | | @total mismatch | 2.4 | | |
| | Voice call GSM1800/1900; PCL=0 | @50Ω | 1.3 | A | |
| | | @total mismatch | 1.6 | | |
| I_{BATT+}^2 | Average GSM / GNSS supply current (GNSS on) | GSM active (UART/USB active); @DRX=2 & GNSS NMEA output off | 65 | mA | |
| | | GSM active (UART/USB active); @DRX=2 & GNSS NMEA output on ⁴ | 85 | mA | |

6.6 Power Supply Ratings

Table 24: Current consumption ratings¹

| | Description | Conditions | | Typical rating | Unit | |
|---------------------------------|----------------------------------------------------|-----------------------------------------------------------------------------|-----------------------------------------------|------------------|------|----|
| I _{BATT+} ² | Average UMTS supply current (GNSS off) | SLEEP ³ @ DRX=9 | USB disconnected | 1.8 | mA | |
| | | SLEEP ³ @ DRX=8 | USB disconnected | 2.1 | mA | |
| | | SLEEP ³ @ DRX=6 | USB disconnected | 3.3 | mA | |
| | | IDLE @ DRX=6 | USB disconnected | 30 | mA | |
| | | | USB active | 40 | mA | |
| | | Voice call Band II | @50Ω | 580 | mA | |
| | | | @total mismatch | 700 | | |
| | | Voice call Band IV | | 490 | mA | |
| | | Voice call Band V | | 470 | mA | |
| | | UMTS Data transfer Band II | | 580 | mA | |
| | | UMTS Data transfer Band IV | | 520 | mA | |
| | | UMTS Data transfer Band V | | 490 | mA | |
| | | HSPA Data transfer Band II | | 590 | mA | |
| | | HSPA Data transfer Band IV | | 540 | mA | |
| | HSPA Data transfer Band V | | 510 | mA | | |
| | Average UMTS / GNSS supply current (GNSS on) | WCDMA active (UART / USB active); @DRX=6 & GNSS NMEA output off | | 65 | mA | |
| | | WCDMA active (UART / USB active); @DRX=6 & GNSS NMEA output on ⁴ | | 85 | mA | |
| | Average LTE supply current ⁵ (GNSS off) | Data transfers measured @maximum Pout | SLEEP ³ @ "Paging Occasions" = 256 | USB disconnected | 2.3 | mA |
| | | | SLEEP ³ @ "Paging Occasions" = 128 | USB disconnected | 2.7 | mA |
| | | | SLEEP ³ @ "Paging Occasions" = 64 | USB disconnected | 3.5 | mA |
| | | | SLEEP ³ @ "Paging Occasions" = 32 | USB disconnected | 5.4 | mA |
| | | | IDLE | USB disconnected | 35 | mA |
| | | | | USB active | 45 | mA |
| | | | LTE Data transfer Band 2 | @ 50Ω | 620 | mA |
| | | | | @ total mismatch | 740 | mA |
| | | | LTE Data transfer Band 4 | | 540 | mA |
| | | | LTE Data transfer Band 5 | | 550 | mA |
| LTE Data transfer Band 13 | | | 570 | mA | | |
| LTE Data transfer Band 17 | | | 550 | mA | | |

6.6 Power Supply Ratings

Table 24: Current consumption ratings¹

| | Description | Conditions | Typical rating | Unit |
|---------------------------------|--------------------------------------------------------------------------------------|---------------------------------------------------------------------------|----------------|------|
| I _{BATT+} ² | Average LTE / GNSS supply current (GNSS on) | LTE active (UART / USB active); @DRX=6 & GNSS NMEA output off | 65 | mA |
| | | LTE active (UART / USB active); @DRX=6 & GNSS NMEA output on ⁴ | 85 | mA |
| I _{VUSB_IN} | USB typical and maximum ratings are mentioned in Table 22 : VUSB_IN. | | | |

1. Please note that the listed frequency bands apply as follows:
 PLS8-X: LTE: Bd 2, 4, 5, 13 and 17; UMTS/HSPA+ Bd II, IV and V; GSM 850/900/1800/1900MHz
 PLS8-V: LTE: Bd 2, 4 and 13
2. With an impedance of Z_{LOAD}=50Ω at the antenna pads. Measured at 25°C and 4.2V - except for Power Down ratings that were measured at 3.4V.
3. Measurements start 6 minutes after switching ON the module,
 Averaging times: SLEEP mode - 3 minutes, transfer modes - 1.5 minutes
 Communication tester settings: no neighbour cells, no cell reselection etc,
 RMC (Reference Measurement Channel)
4. One fix per second.
5. Communication tester settings:
 - Channel Bandwidth: 5MHz
 - Number of Resource Blocks: 25 (DL), 1 (UL)
 - Modulation: QPSK

6.7 RF Antenna Interface Characteristics

Table 25: RF Antenna interface GSM / UMTS/LTE (at operating temperature range¹)²

| Parameter | Conditions | Min. | Typical | Max. | Unit |
|-------------------------------------------------------------------------------------------|-------------------------|--------|---------|------|--------|
| LTE connectivity ³ | Band 2, 4, 5, 13 and 17 | | | | |
| Receiver Input Sensitivity @ ARP (ch. bandwidth 5MHz) | LTE 700 Band 17 | -97 | -102 | | dBm |
| | LTE 700 Band 13 | TBD. | TBD. | | dBm |
| | LTE 850 Band 5 | -98 | -104 | | dBm |
| | LTE AWS Band 4 | -100 | -103 | | dBm |
| | LTE 1900 Band 2 | -98 | -103 | | dBm |
| RF Power @ ARP with 50Ω Load | LTE 700 Band 17 | +21 | +23 | +25 | dBm |
| | LTE 700 Band 13 | +21 | +23 | +25 | dBm |
| | LTE 850 Band 5 | +21 | +23 | +25 | dBm |
| | LTE AWS Band 4 | +21 | +23 | +25 | dBm |
| | LTE 1900 Band 2 | +21 | +23 | +25 | dBm |
| UMTS/HSPA connectivity ³ | Band II, IV, V | | | | |
| Receiver Input Sensitivity @ ARP | UMTS 850 Band V | -104.7 | -110 | | dBm |
| | UMTS AWS Band IV | -106.7 | -110 | | dBm |
| | UMTS 1900 Band II | -104.7 | -109 | | dBm |
| RF Power @ ARP with 50Ω Load | UMTS 850 Band V | +21 | +24 | +25 | dBm |
| | UMTS AWS Band IV | +21 | +24 | +25 | dBm |
| | UMTS 1900 Band II | +21 | +24 | +25 | dBm |
| Tx noise @ ARP with max. RF power for UMTS: Band 1 channel 9777 Band 2 channel 9477 | GNSS band | | -170 | | dBm/Hz |
| GPRS coding schemes | Class 12, CS1 to CS4 | | | | |
| EGPRS | Class 12, MCS1 to MCS9 | | | | |
| GSM Class | Small MS | | | | |
| Static Receiver input Sensitivity @ ARP | GSM 850 / E-GSM 900 | -102 | -111 | | dBm |
| | GSM 1800 / GSM 1900 | -102 | -110 | | dBm |
| RF Power @ ARP with 50Ω Load GSM | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | GSM 1800 / GSM 1900 | | 30 | | dBm |

6.7 RF Antenna Interface Characteristics

Table 25: RF Antenna interface GSM / UMTS/LTE (at operating temperature range¹)²

| Parameter | | Conditions | Min. | Typical | Max. | Unit |
|-----------------------------------------------------------|------------|---------------------|------|---------|------|------|
| RF Power @ ARP with 50Ω Load (ROPR=4, i.e., no reduction) | GPRS, 1 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 1 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 2 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 2 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 3 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 3 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 4 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| RF Power @ ARP with 50Ω Load (ROPR=5) | GPRS, 1 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 1 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 2 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 2 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 3 TX | GSM 850 / E-GSM 900 | | 32.2 | | dBm |
| | | GSM 1800 / GSM 1900 | | 29.2 | | dBm |
| | EDGE, 3 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 4 TX | GSM 850 / E-GSM 900 | | 31 | | dBm |
| | | GSM 1800 / GSM 1900 | | 28 | | dBm |
| | EDGE, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |

6.7 RF Antenna Interface Characteristics

Table 25: RF Antenna interface GSM / UMTS/LTE (at operating temperature range¹)²

| Parameter | | Conditions | Min. | Typical | Max. | Unit |
|---------------------------------------|------------|---------------------|------|---------|------|------|
| RF Power @ ARP with 50Ω Load (ROPR=6) | GPRS, 1 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 1 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 2 TX | GSM 850 / E-GSM 900 | | 31 | | dBm |
| | | GSM 1800 / GSM 1900 | | 28 | | dBm |
| | EDGE, 2 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 3 TX | GSM 850 / E-GSM 900 | | 30.2 | | dBm |
| | | GSM 1800 / GSM 1900 | | 27.2 | | dBm |
| | EDGE, 3 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 4 TX | GSM 850 / E-GSM 900 | | 29 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | EDGE, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| RF Power @ ARP with 50Ω Load (ROPR=7) | GPRS, 1 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 1 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 2 TX | GSM 850 / E-GSM 900 | | 30 | | dBm |
| | | GSM 1800 / GSM 1900 | | 27 | | dBm |
| | EDGE, 2 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 3 TX | GSM 850 / E-GSM 900 | | 28.2 | | dBm |
| | | GSM 1800 / GSM 1900 | | 25.2 | | dBm |
| | EDGE, 3 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 24 | | dBm |
| | EDGE, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |

6.7 RF Antenna Interface Characteristics

Table 25: RF Antenna interface GSM / UMTS/LTE (at operating temperature range¹)²

| Parameter | | Conditions | Min. | Typical | Max. | Unit |
|-------------------------------------------------------------|------------|---------------------|------|---------|------|------|
| RF Power @ ARP with 50Ω Load (ROPR=8, i.e., max. reduction) | GPRS, 1 TX | GSM 850 / E-GSM 900 | | 33 | | dBm |
| | | GSM 1800 / GSM 1900 | | 30 | | dBm |
| | EDGE, 1 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 26 | | dBm |
| | GPRS, 2 TX | GSM 850 / E-GSM 900 | | 30 | | dBm |
| | | GSM 1800 / GSM 1900 | | 27 | | dBm |
| | EDGE, 2 TX | GSM 850 / E-GSM 900 | | 24 | | dBm |
| | | GSM 1800 / GSM 1900 | | 23 | | dBm |
| | GPRS, 3 TX | GSM 850 / E-GSM 900 | | 28.2 | | dBm |
| | | GSM 1800 / GSM 1900 | | 25.2 | | dBm |
| | EDGE, 3 TX | GSM 850 / E-GSM 900 | | 22.2 | | dBm |
| | | GSM 1800 / GSM 1900 | | 21.2 | | dBm |
| | GPRS, 4 TX | GSM 850 / E-GSM 900 | | 27 | | dBm |
| | | GSM 1800 / GSM 1900 | | 24 | | dBm |
| | EDGE, 4 TX | GSM 850 / E-GSM 900 | | 21 | | dBm |
| | | GSM 1800 / GSM 1900 | | 20 | | dBm |

¹. At extended temperature range no active power reduction is implemented - any deviations are hardware related.

². Please note that the listed frequency bands apply as follows:

PLS8-X: LTE: Bd 2, 4, 5, 13 and 17; UMTS/HSPA+ Bd II, IV and V; GSM 850/900/1800/1900MHz

PLS8-V: LTE: Bd 2, 4 and 13

³. Applies also to UMTS/LTE Rx diversity/MIMO antenna.

6.8 GNSS Interface Characteristics

The following tables list general characteristics of the GNSS interface.

Table 26: GNSS properties

| Parameter | Conditions | Min. | Typical | Max. | Unit |
|---------------------------------------|------------------------------------------------------|----------|--------------|----------|------|
| Frequency | GPS GLONASS | 1597.551 | 1575.42 | 1605.886 | MHz |
| Tracking Sensitivity | Open sky Active antenna or LNA Passive antenna | | -159 -156 | | dBm |
| Acquisition Sensitivity | Open sky Active antenna or LNA Passive antenna | | -149 -145 | | dBm |
| Cold Start sensitivity ¹ | | | -145 | | dBm |
| Time-to-First-Fix (TTFF) ² | Cold ³ | | 25 | 32 | s |
| | Warm ⁴ | | 10 | 29 | s |

¹ Test condition: Assumes 300 seconds timeout, QoS=1000m, and 50% yield.

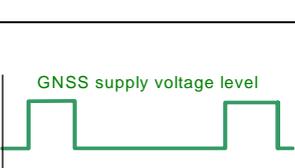
² Test condition: TTFF is defined for an open sky environment, i.e., with a clear view to the sky and a minimum signal level of -130dBm at the antenna for at least 3...4 satellites. This signal level represents C/No=42dB in an NMEA \$GPGSV message.

³ For test purposes a cold start may be triggered by AT command: AT^SBNW="agps",-1 - see also [1].

⁴ To optimize GPS start-up behavior, it is recommended to backup the module's internal real time clock via VDDL P line as described in Section 3.5.

Through the external GNSS antenna DC feeding the module is able to supply an active GNSS antenna. The supply voltage level at the GNSS antenna interface depends on the GNSS configuration done with AT command as shown in Table 27.

Table 27: Power supply for active GNSS antenna

| Function | Setting samples | IO | Signal form and level |
|----------------------------|-----------------------------------------------------------------------------|----|--------------------------------------------------------------------------------------|
| GNSS active antenna supply | Supply voltage with: GNSS receiver off Active antenna off | O |  |
| | Supply voltage with: GNSS receiver on Active antenna on SLEEP mode | O |  |
| | Supply voltage with: GNSS receiver on Active antenna auto | O |  |

6.9 Electrostatic Discharge

The module is not protected against Electrostatic Discharge (ESD) in general. Consequently, it is subject to ESD handling precautions that typically apply to ESD sensitive components. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any application that incorporates a PLS8-X/PLS8-V module.

Special ESD protection provided on PLS8-X/PLS8-V:

BATT+: Inductor/capacitor

An example for an enhanced ESD protection for the SIM interface is shown in [Section 3.8.1](#).

The remaining interfaces of PLS8-X/PLS8-V with the exception of the antenna interface are not accessible to the user of the final product (since they are installed within the device) and are therefore only protected according to the ANSI/ESDA/JEDEC JS-001-2011 requirements.

PLS8-X/PLS8-V has been tested according to the following standards. Electrostatic values can be gathered from the following table.

Table 28: Electrostatic values

| Specification / Requirements | Contact discharge | Air discharge |
|------------------------------------|-----------------------------------|---------------|
| ANSI/ESDA/JEDEC JS-001-2011 | | |
| All SMT interfaces | ± 1kV Human Body Model | n.a. |
| JESD22-C101 | | |
| All SMT interfaces | ± 250V Charged Device Model (CDM) | n.a. |
| ETSI EN 301 489-1/7 | | |
| BATT+ | ± 4kV | ± 8kV |

Note: The values may vary with the individual application design. For example, it matters whether or not the application platform is grounded over external devices like a computer or other equipment, such as the Gemalto M2M reference application described in [Chapter 9](#).

7 Mechanics, Mounting and Packaging

7.1 Mechanical Dimensions of PLS8-X/PLS8-V

Figure 33 shows a 3D view¹ of PLS8-X/PLS8-V and provides an overview of the board's mechanical dimensions. For further details see Figure 34.

Length: 33mm
Width: 29mm
Height: 2.95mm

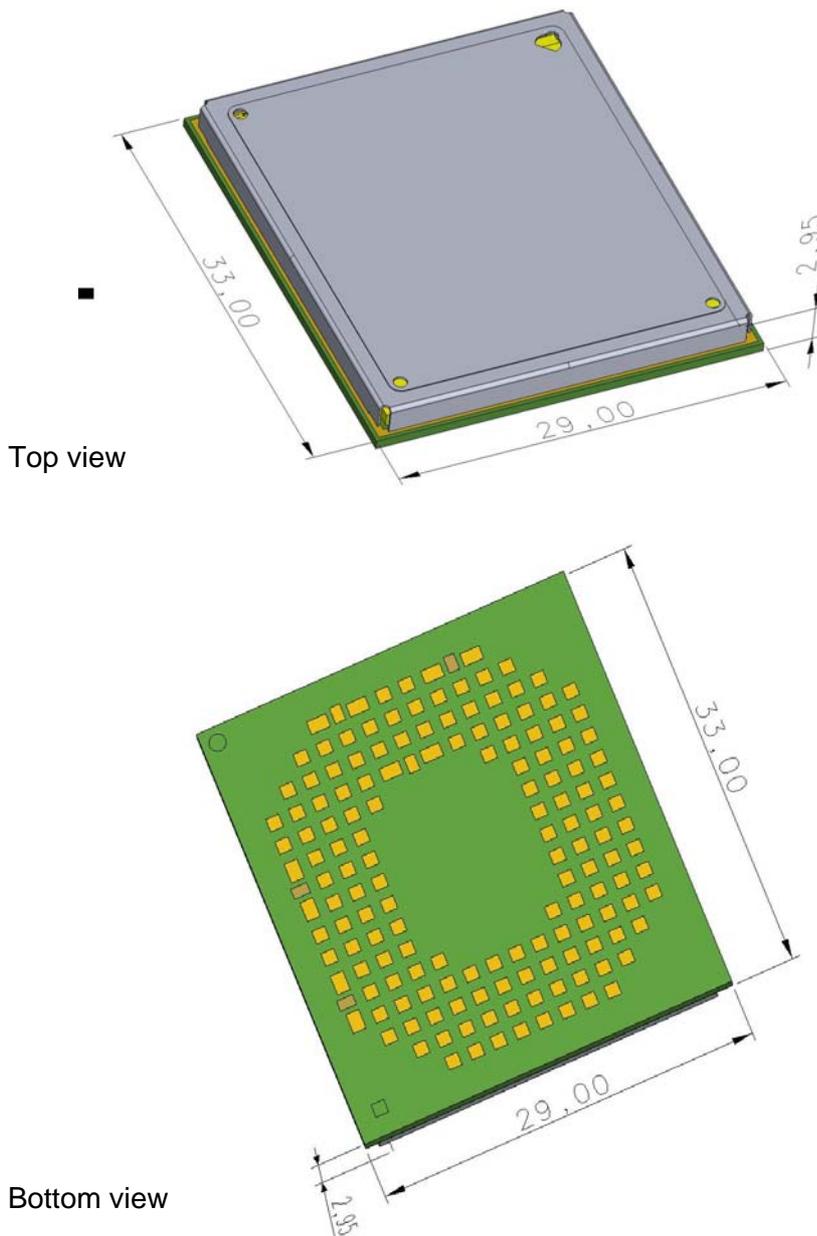


Figure 33: PLS8-X/PLS8-V – top and bottom view

¹ The coloring of the 3D view does not reflect the module's real color.

7.1 Mechanical Dimensions of PLS8-X/PLS8-V

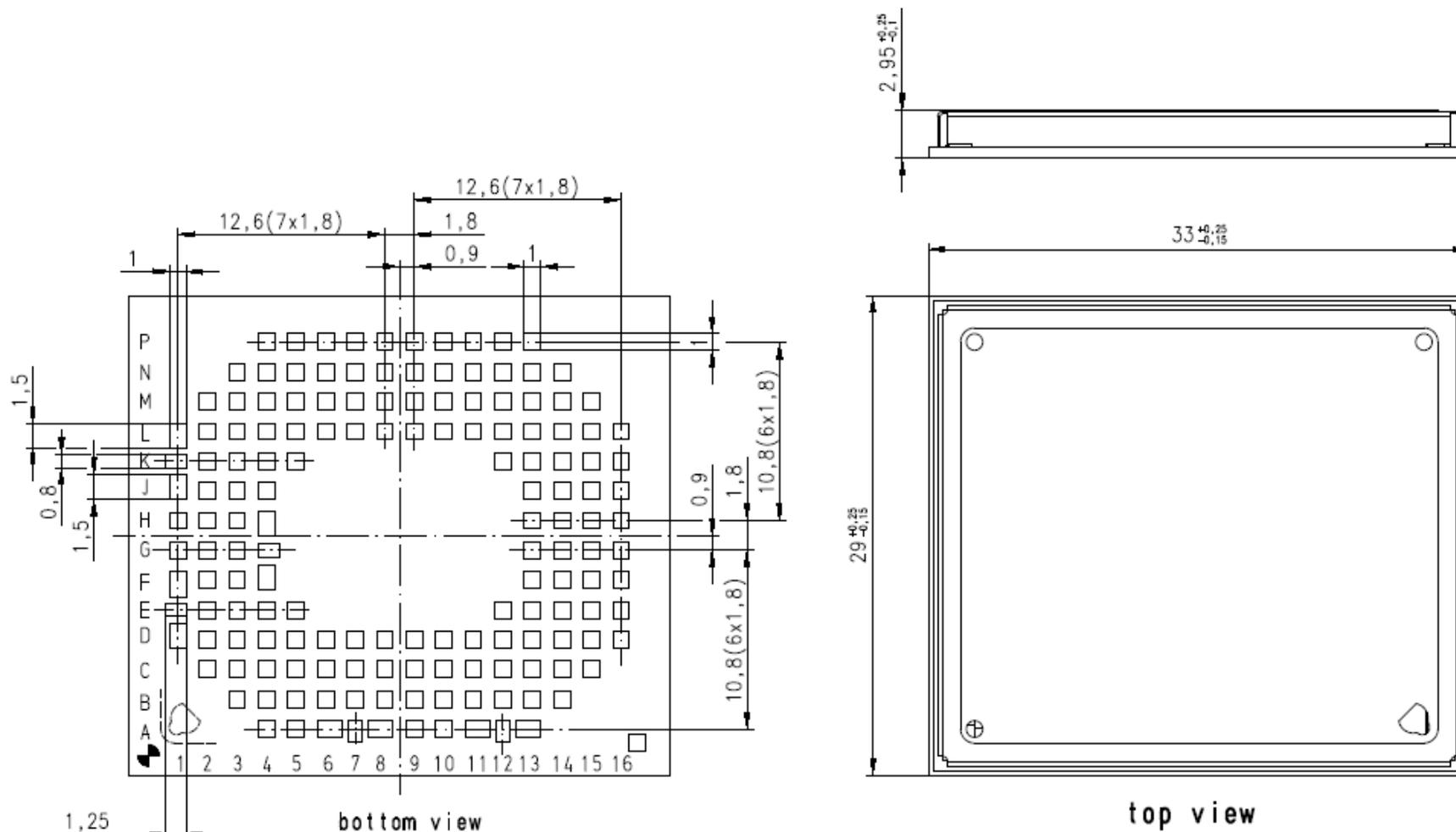


Figure 34: Dimensions of PLS8-X/PLS8-V (all dimensions in mm)

7.2 Mounting PLS8-X/PLS8-V onto the Application Platform

This section describes how to mount PLS8-X/PLS8-V onto the PCBs, including land pattern and stencil design, board-level characterization, soldering conditions, durability and mechanical handling. For more information on issues related to SMT module integration see also [3].

Note: Gemalto strongly recommends to solder all connecting pads for mechanical stability and heat dissipation. Not only must all supply pads and signals be connected appropriately, but all pads denoted as “Do not use” should also be soldered (but not electrically connected). Note also that in order to avoid short circuits between signal tracks on an external application’s PCB and various markings at the bottom side of the module, it is recommended not to route the signal tracks on the top layer of an external PCB directly under the module, or at least to ensure that signal track routes are sufficiently covered with solder resist.

7.2.1 SMT PCB Assembly

7.2.1.1 Land Pattern and Stencil

The land pattern and stencil design as shown below is based on Gemalto M2M characterizations for lead-free solder paste on a four-layer test PCB and a 110 as well as a 150 micron-thick stencil.

The land pattern given in Figure 35 reflects the module’s pad layout, including signal pads and ground pads (for pad assignment see Section 6.5). Besides these pads there are ground areas on the module’s bottom side that must not be soldered, e.g., the position marker. To prevent short circuits, it has to be ensured that there are no wires on the external application side that may connect to these module ground areas.

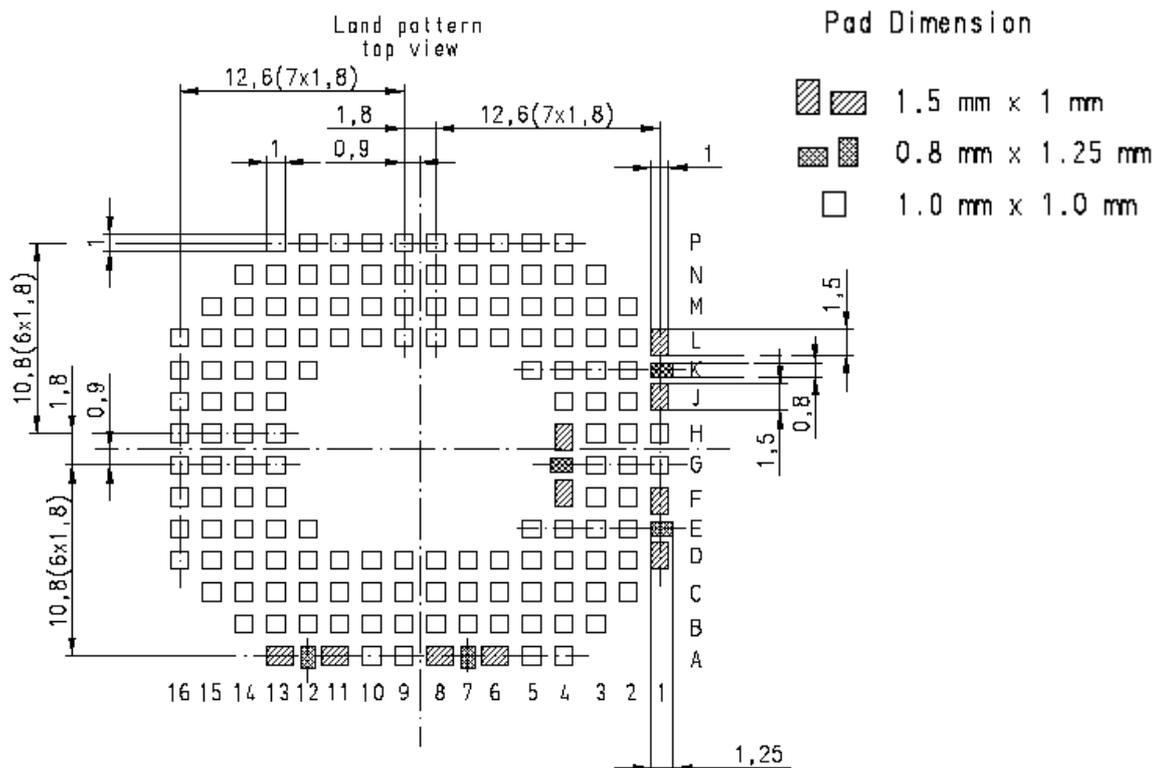


Figure 35: Land pattern (top layer)

7.2 Mounting PLS8-X/PLS8-V onto the Application Platform

The stencil design illustrated in Figure 36 and Figure 37 is recommended by Gemalto M2M as a result of extensive tests with Gemalto M2M Daisy Chain modules.

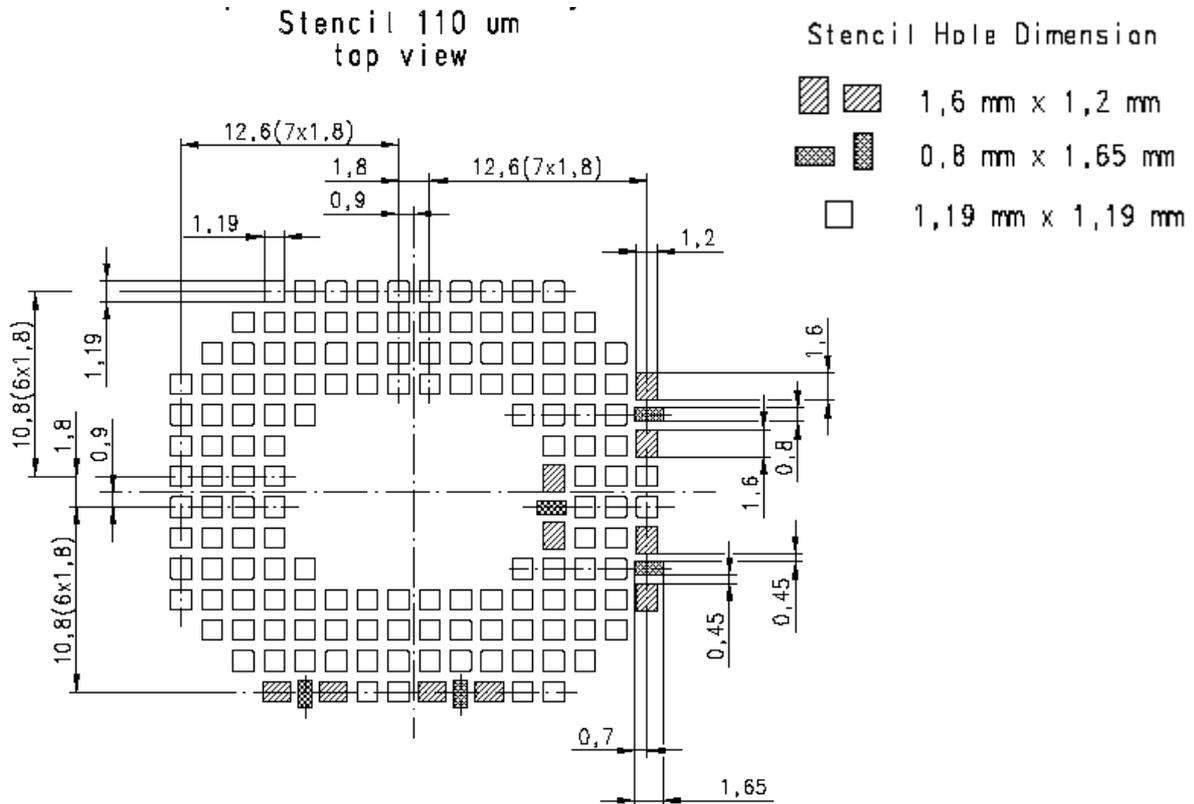


Figure 36: Recommended design for 110 micron thick stencil (top layer)

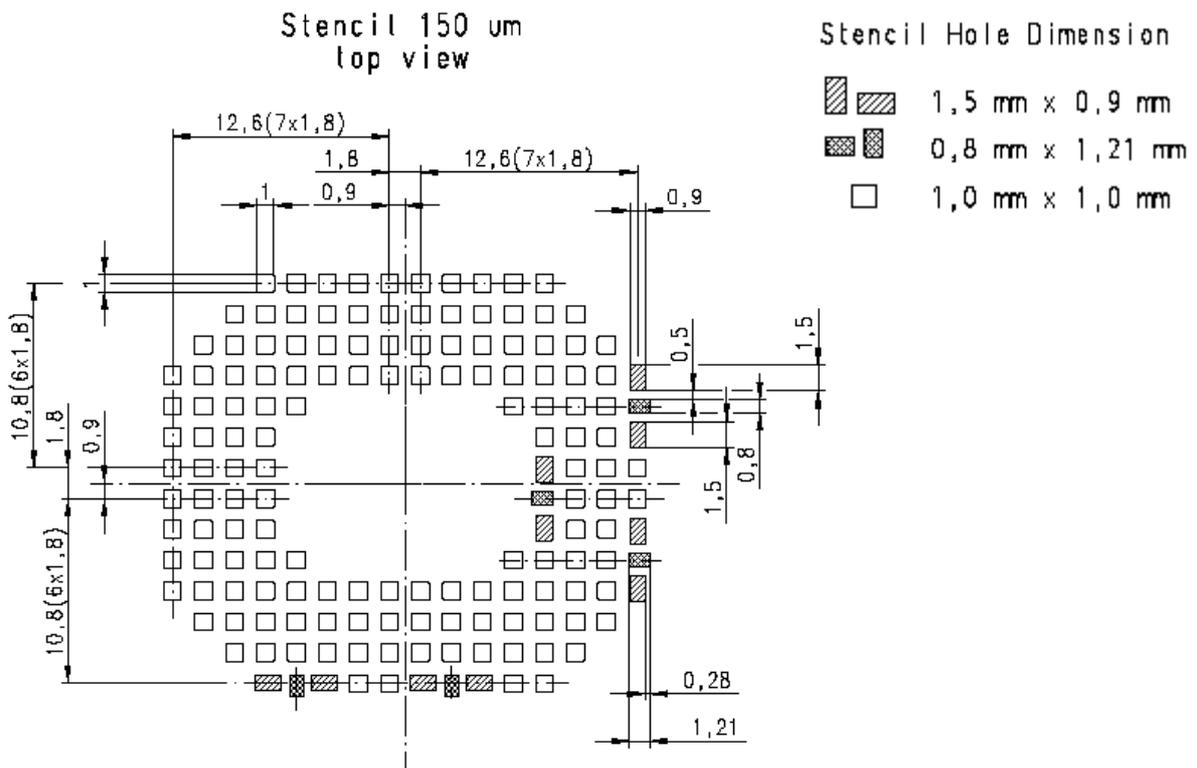


Figure 37: Recommended design for 150 micron thick stencil (top layer)

7.2.1.2 Board Level Characterization

Board level characterization issues should also be taken into account if devising an SMT process.

Characterization tests should attempt to optimize the SMT process with regard to board level reliability. This can be done by performing the following physical tests on sample boards: Peel test, bend test, tensile pull test, drop shock test and temperature cycling. Sample surface mount checks are described in [\[3\]](#).

It is recommended to characterize land patterns before an actual PCB production, taking individual processes, materials, equipment, stencil design, and reflow profile into account. For land and stencil pattern design recommendations see also [Section 7.2.1.1](#). Optimizing the solder stencil pattern design and print process is necessary to ensure print uniformity, to decrease solder voids, and to increase board level reliability.

Daisy chain modules for SMT characterization are available on request. For details refer to [\[3\]](#).

Generally, solder paste manufacturer recommendations for screen printing process parameters and reflow profile conditions should be followed. Maximum ratings are described in [Section 7.2.3](#).

7.2.2 Moisture Sensitivity Level

PLS8-X/PLS8-V comprises components that are susceptible to damage induced by absorbed moisture.

Gemalto M2M's PLS8-X/PLS8-V module complies with the latest revision of the IPC/JEDEC J-STD-020 Standard for moisture sensitive surface mount devices and is classified as MSL 4.

For additional moisture sensitivity level (MSL) related information see [Section 7.2.4](#) and [Section 7.3.2](#).

7.2.3 Soldering Conditions and Temperature

7.2.3.1 Reflow Profile

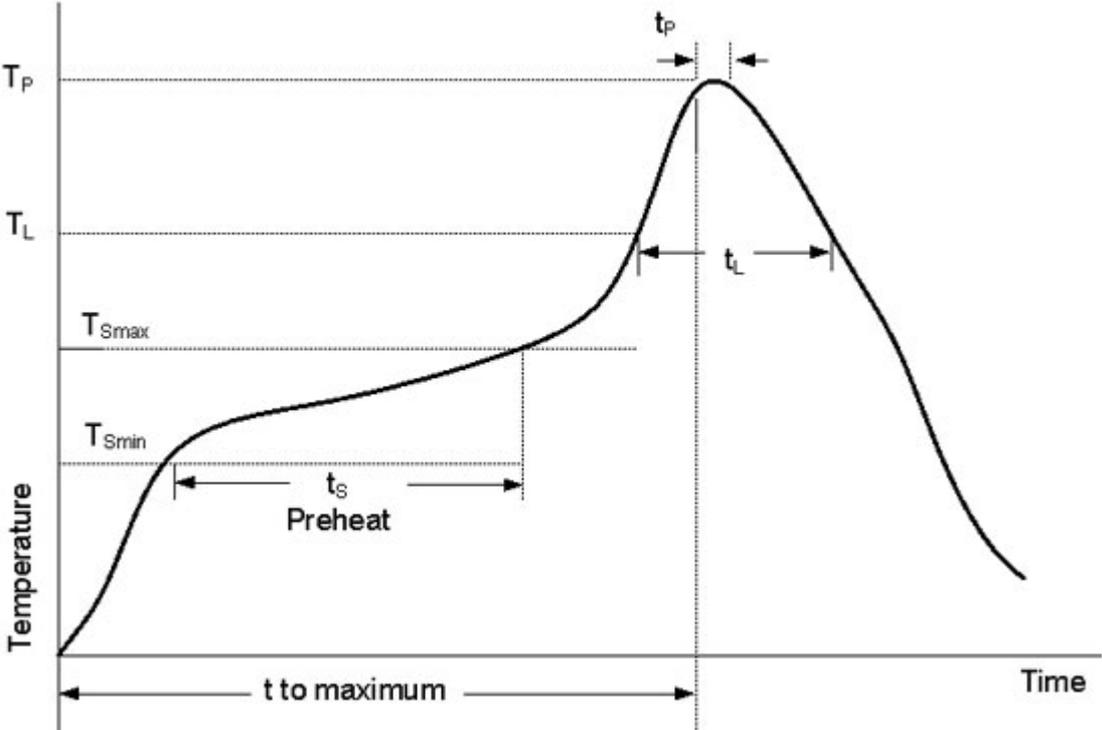


Figure 38: Reflow Profile

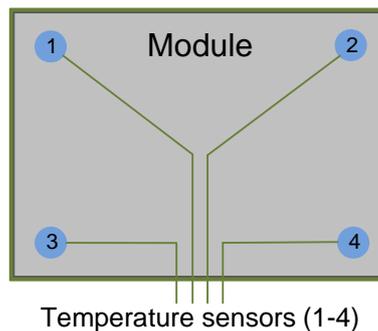
7.2 Mounting PLS8-X/PLS8-V onto the Application Platform

Table 29: Reflow temperature recommendations¹

| Profile Feature | Pb-Free Assembly |
|-------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------|
| Preheat & Soak Temperature Minimum (T_{Smin}) Temperature Maximum (T_{Smax}) Time (t_{Smin} to t_{Smax}) (t_S) | 150°C 200°C 60-120 seconds |
| Average ramp up rate (T_L to T_p) | 3K/second max. ² |
| Liquidous temperature (T_L) Time at liquidous (t_L) | 217°C 60-90 seconds |
| Peak package body temperature (T_p) | 245°C +0/-5°C |
| Time (t_p) within 5 °C of the peak package body temperature (T_p) | 30 seconds max. |
| Average ramp-down rate - Limited ramp-down rate between 225°C and 200°C | 6K/second max. ² 3K/second max. ² |
| Time 25°C to maximum temperature | 8 minutes max. |

¹ Please note that the listed reflow profile features and ratings are based on the joint industry standard IPC/ JEDEC J-STD-020D.1, and are as such meant as a general guideline. For more information on reflow profiles and their optimization please refer to [3].

² Temperatures measured on shielding at each corner. See also [3].



7.2.3.2 Maximum Temperature and Duration

The following limits are recommended for the SMT board-level soldering process to attach the module:

- A maximum module temperature of 245°C. This specifies the temperature as measured at the module's top side.
- A maximum duration of 30 seconds at this temperature.
- Ramp-down rate from T_p to 200°C should be controlled in order to reduce thermally induced stress during the solder solidification phase (see Table 29 - limited ramp-down rate). Therefore, a cool-down step in the oven's temperature program between 200°C and 180°C should be considered. For more information on reflow profiles and their optimization see [3].

Please note that while the solder paste manufacturers' recommendations for best temperature and duration for solder reflow should generally be followed, the limits listed above must not be exceeded.

PLS8-X/PLS8-V is specified for one soldering cycle only. Once PLS8-X/PLS8-V is removed from the application, the module will very likely be destroyed and cannot be soldered onto another application.

7.2.4 Durability and Mechanical Handling

7.2.4.1 Storage Life

PLS8-X/PLS8-V modules, as delivered in tape and reel carriers, must be stored in sealed, moisture barrier anti-static bags. The shelf life in a sealed moisture bag is an estimated 12 months. However, such a life span requires a non-condensing atmospheric environment, ambient temperatures below 40°C and a relative humidity below 90%. Additional storage conditions are listed in [Table 22](#).

7.2.4.2 Processing Life

PLS8-X/PLS8-V must be soldered to an application within 72 hours after opening the moisture barrier bag (MBB) it was stored in.

As specified in the IPC/JEDEC J-STD-033 Standard, the manufacturing site processing the modules should have ambient temperatures below 30°C and a relative humidity below 60%.

7.2.4.3 Baking

Baking conditions are specified on the moisture sensitivity label attached to each MBB (see [Figure 43](#) for details):

- It is *not necessary* to bake PLS8-X/PLS8-V, if the conditions specified in [Section 7.2.4.1](#) and [Section 7.2.4.2](#) were not exceeded.
- It is *necessary* to bake PLS8-X/PLS8-V, if any condition specified in [Section 7.2.4.1](#) and [Section 7.2.4.2](#) was exceeded.

If baking is necessary, the modules must be put into trays that can be baked to at least 125°C. Devices should not be baked in tape and reel carriers at any temperature.

7.2.4.4 Electrostatic Discharge

Electrostatic discharge (ESD) may lead to irreversible damage for the module. It is therefore advisable to develop measures and methods to counter ESD and to use these to control the electrostatic environment at manufacturing sites.

Please refer to [Section 6.9](#) for further information on electrostatic discharge.

7.3 Packaging

7.3 Packaging

7.3.1 Tape and Reel

The single-feed tape carrier for PLS8-X/PLS8-V is illustrated in Figure 39. The figure also shows the proper part orientation. The tape width is 44mm and the PLS8-X/PLS8-V modules are placed on the tape with a 40mm pitch. The reels are 330mm in diameter with 100mm hubs. Each reel contains 500 modules.

7.3.1.1 Orientation

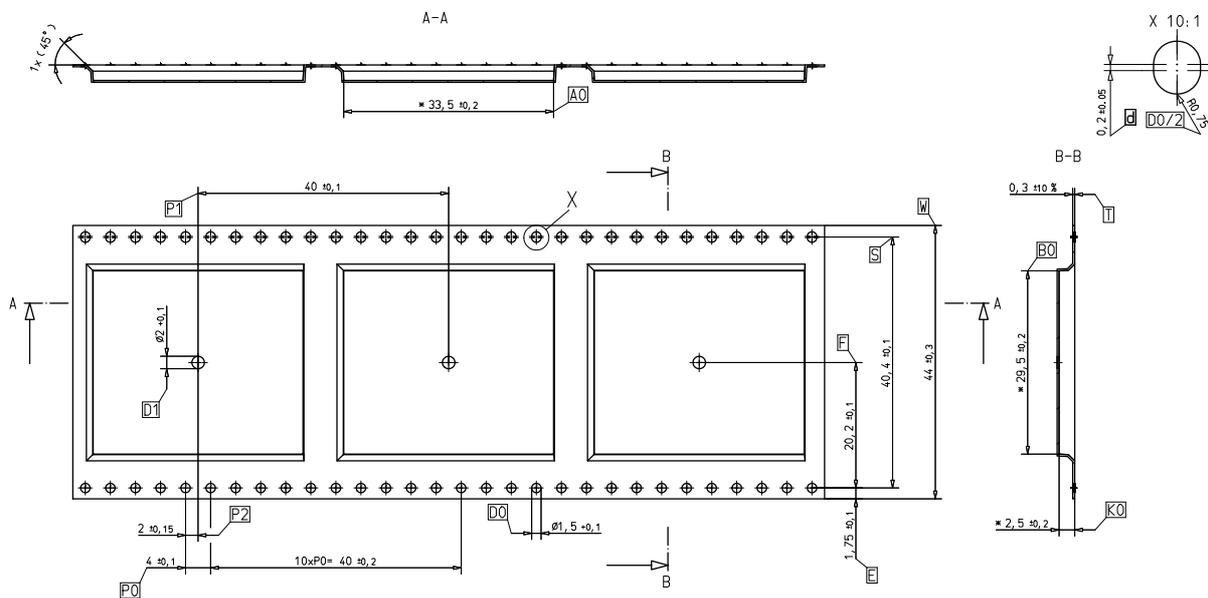


Figure 39: Carrier tape

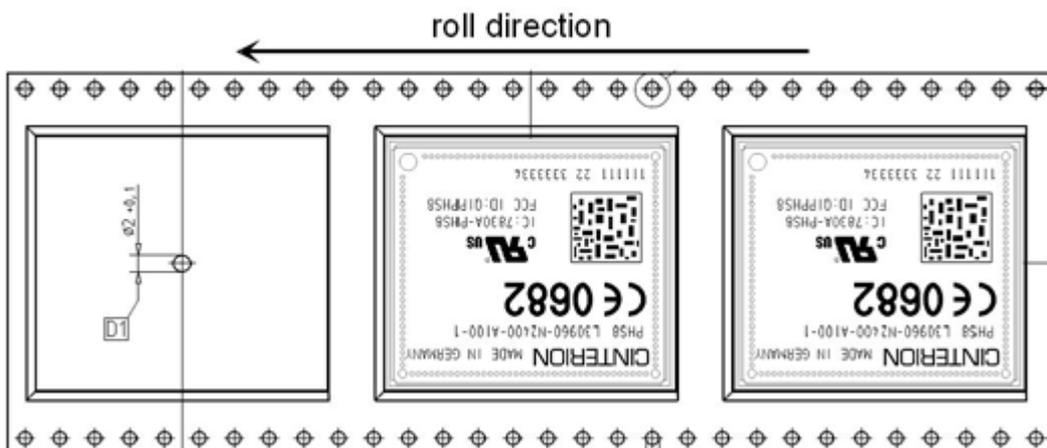


Figure 40: Roll direction

7.3.1.2 Barcode Label

A barcode label provides detailed information on the tape and its contents. It is attached to the reel.

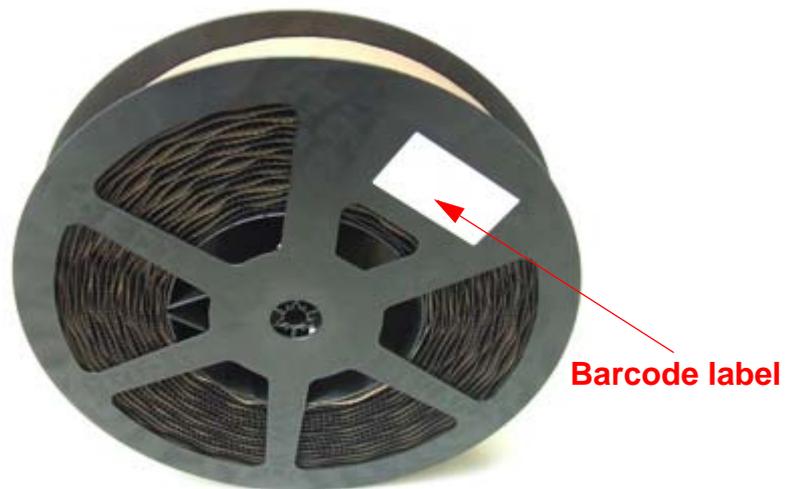


Figure 41: Barcode label on tape reel

7.3.2 Shipping Materials

PLS8-X/PLS8-V is distributed in tape and reel carriers. The tape and reel carriers used to distribute PLS8-X/PLS8-V are packed as described below, including the following required shipping materials:

- Moisture barrier bag, including desiccant and humidity indicator card
- Transportation bag

7.3.2.1 Moisture Barrier Bag

The tape reels are stored inside a moisture barrier bag (MBB), together with a humidity indicator card and desiccant pouches - see [Figure 42](#). The bag is ESD protected and delimits moisture transmission. It is vacuum-sealed and should be handled carefully to avoid puncturing or tearing. The bag protects the PLS8-X/PLS8-V modules from moisture exposure. It should not be opened until the devices are ready to be soldered onto the application.

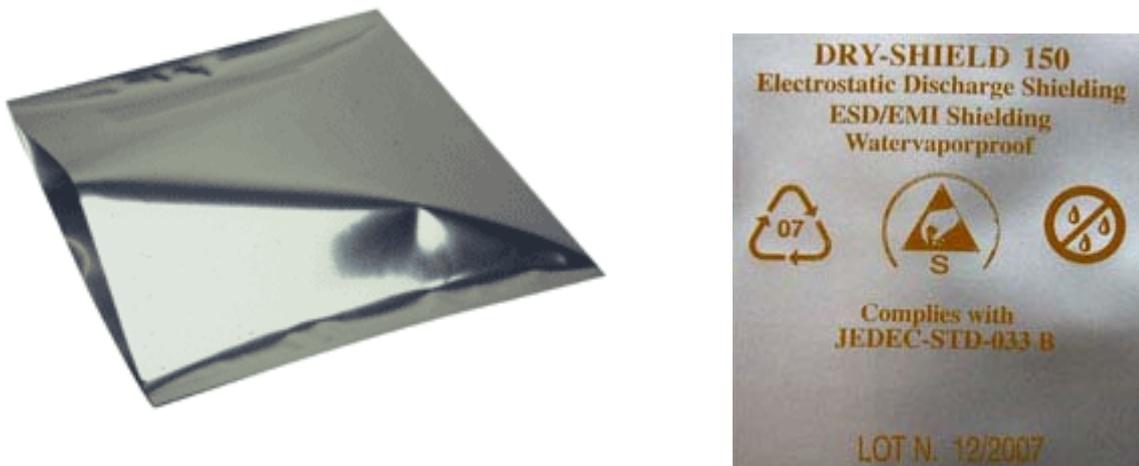


Figure 42: Moisture barrier bag (MBB) with imprint

The label shown in [Figure 43](#) summarizes requirements regarding moisture sensitivity, including shelf life and baking requirements. It is attached to the outside of the moisture barrier bag.

| | | |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------|-------------------|
|  | CAUTION This bag contains MOISTURE-SENSITIVE DEVICES | LEVEL 4 |
| <p>1. Calculated shelf life in sealed bag: 12 months at < 40 °C and < 90% relative humidity (RH)</p> <p>2. Peak package body temperature: <u>245°C</u></p> <p>3. After bag is opened, devices that will be subject to reflow solder or other high temperature process must be</p> <p style="margin-left: 20px;">a) mounted within: <u>72</u> hours of factory conditions < 30 °C / 60% RH</p> <p style="margin-left: 20px;">b) stored at < 10% RH</p> <p>4. Devices require bake, before mounting, if:</p> <p style="margin-left: 20px;">a) Humidity Indicator Card is > 10% when read at 23 +/- 5 °C</p> <p style="margin-left: 20px;">b) 3a or 3b not met</p> <p>5. If baking is required, refer to IPC/Jedec J-STD-033 for bake procedure</p> <p>Note: The devices are shipped in a non heat-resistant carrier and may not be baked in the carriers</p> <p>Bag Seal Date: <u>DD.MM.YYYY</u></p> <p>Note: MSL level and body temperature defined by IPC/JEDEC J-STD-020</p> | | |
| CINTERION | | |
| INFO-2 | DELIVERYPARTNUMBER | |
| Peak package body temperature: <u>245°C</u> | | |
| | | Qty. : <u>000</u> |
| Bag Seal Date (DDMMYYYY) : <u>DDMMYYYY</u> | | |
|  | | |
| Package ID: <u>WM8000123412</u> | | |
|  | | |

Figure 43: Moisture Sensitivity Label

MBBs contain one or more desiccant pouches to absorb moisture that may be in the bag. The humidity indicator card described below should be used to determine whether the enclosed components have absorbed an excessive amount of moisture.

The desiccant pouches should not be baked or reused once removed from the MBB.

The humidity indicator card is a moisture indicator and is included in the MBB to show the approximate relative humidity level within the bag. A sample humidity card is shown in [Figure 44](#). If the components have been exposed to moisture above the recommended limits, the units will have to be rebaked.

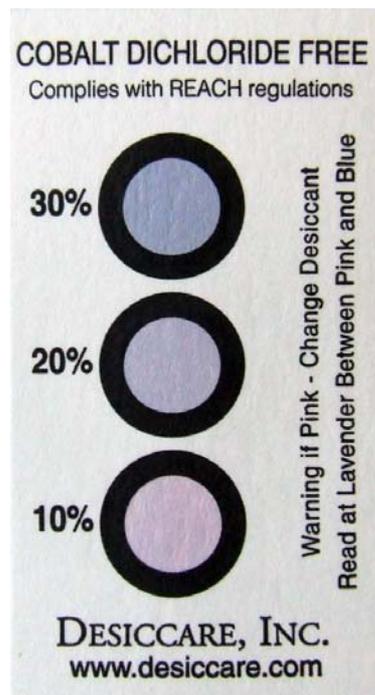


Figure 44: Humidity Indicator Card - HIC

A baking is required if the humidity indicator inside the bag indicates 10% RH or more.

7.3.2.2 Transportation Box

Tape and reel carriers are distributed in a box, marked with a barcode label for identification purposes. A box contains 2 reels with 500 modules each.

8 Sample Application

Figure 45 shows a typical example of how to integrate an PLS8-X/PLS8-V module with an application.

The PWR_IND line is an open collector that needs an external pull-up resistor which connects to the voltage supply VCC μ C of the microcontroller. Low state of the open collector pulls the PWR_IND signal low and indicates that the PLS8-X/PLS8-V module is active, high level notifies the Power Down mode.

If the module is in Power Down mode avoid current flowing from any other source into the module circuit, for example reverse current from high state external control lines. Therefore, the controlling application must be designed to prevent reverse flow.

While developing SMT applications it is strongly recommended to provide test points for certain signals, i.e., lines to and from the module - for debug and/or test purposes. The SMT application should allow for an easy access to these signals. For details on how to implement test points see [3].

The EMC measures are best practice recommendations. In fact, an adequate EMC strategy for an individual application is very much determined by the overall layout and, especially, the position of components.

Some LGA pads are connected to clocks or high speed data streams that might interfere with the module's antenna. The RF receiver would then be blocked at certain frequencies (self interference). The external application's PCB tracks connected to these pads should therefore be well shielded or kept away from the antenna. This applies especially to the USB and UICC/SIM interfaces.

Depending on the micro controller used by an external application PLS8-X/PLS8-V's digital input and output lines may require level conversion. Section 8.1 shows a possible sample level conversion circuit.

Disclaimer:

No warranty, either stated or implied, is provided on the sample schematic diagram shown in Figure 45 and the information detailed in this section. As functionality and compliance with national regulations depend to a great amount on the used electronic components and the individual application layout manufacturers are required to ensure adequate design and operating safeguards for their products using PLS8-X/PLS8-V modules.

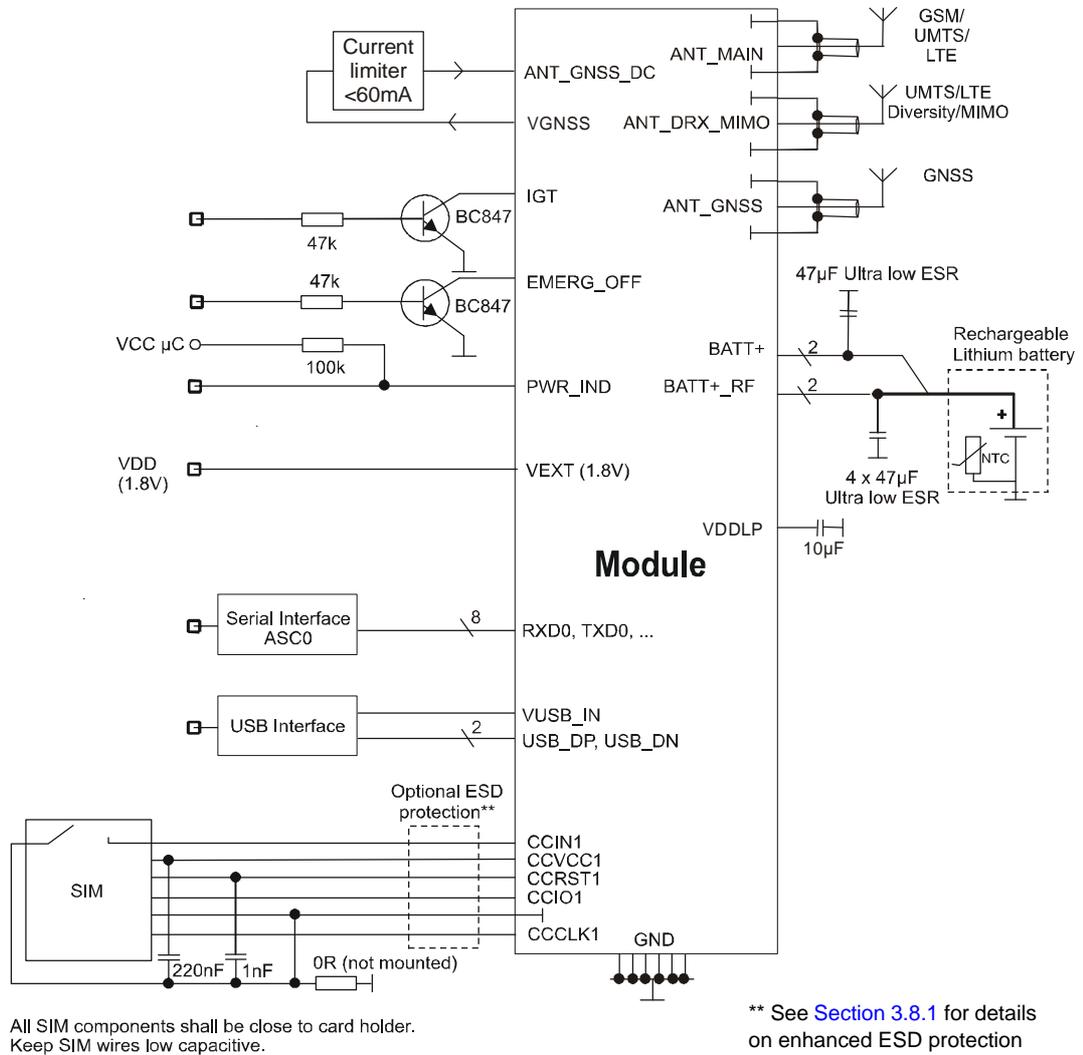


Figure 45: PLS8-X/PLS8-V sample application

8.1 Sample Level Conversion Circuit

Depending on the micro controller used by an external application PLS8-X/PLS8-V's digital input and output lines (i.e., ASC0 lines) may require level conversion. The following [Figure 46](#) shows a sample circuit with recommended level shifters for an external application's micro controller (with VLOGIC between 3.0V...3.6V). The level shifters can be used for digital input and output lines with $V_{OH,max}=1.85V$ or $V_{IH,max}=1.85V$.

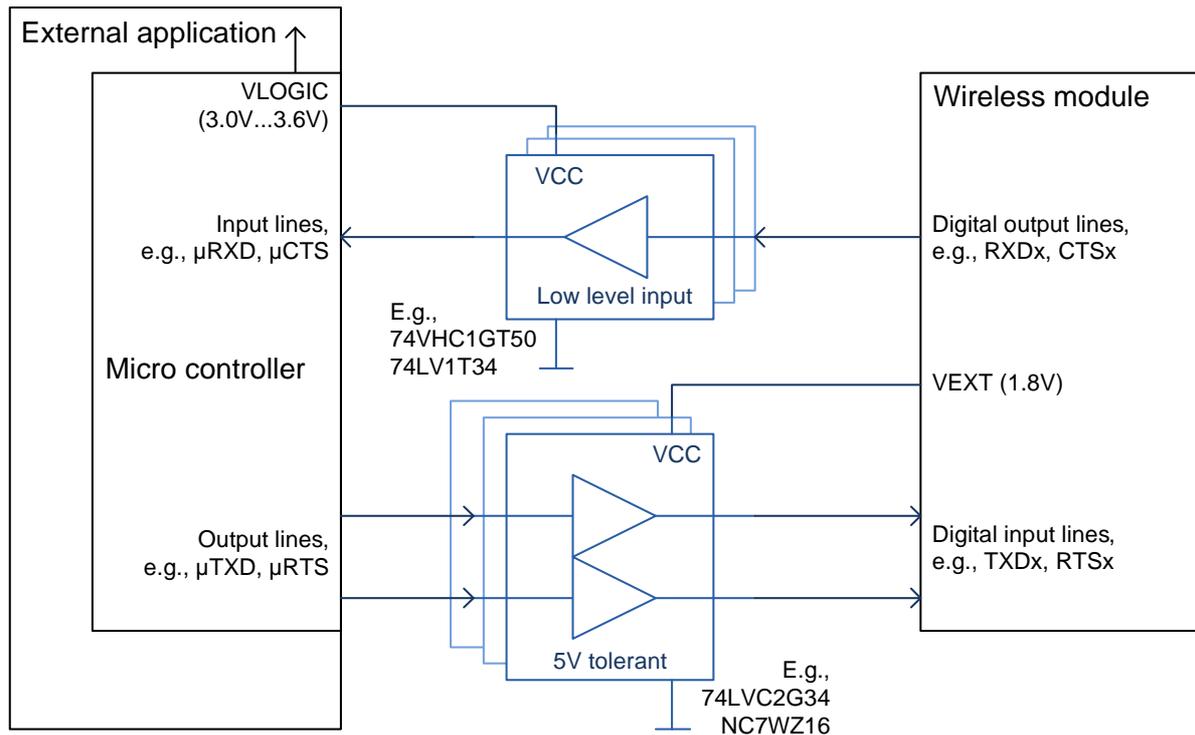


Figure 46: Sample level conversion circuit

9 Reference Approval

9.1 Reference Equipment for Type Approval

The Gemalto M2M reference setup submitted to type approve PLS8-X/PLS8-V is shown in [Figure 47](#). The module (i.e., the evaluation module) is connected to the DSB75 by means of a flex cable and a special DSB75 adapter. The GSM/UMTS/LTE test equipment is connected via edge mount SMA connectors soldered to the module's antenna pads.

For ESD tests and evaluation purposes, it is also possible connect the module to the GSM/UMTS/LTE test equipment through an SMA-to-Hirose-U.FL antenna cable and the SMA antenna connectors of the DSB75 adapter.

A further option is to mount the evaluation module directly onto the DSB75 adapter's 80-pin board-to-board connector and to connect the test equipment as shown below.

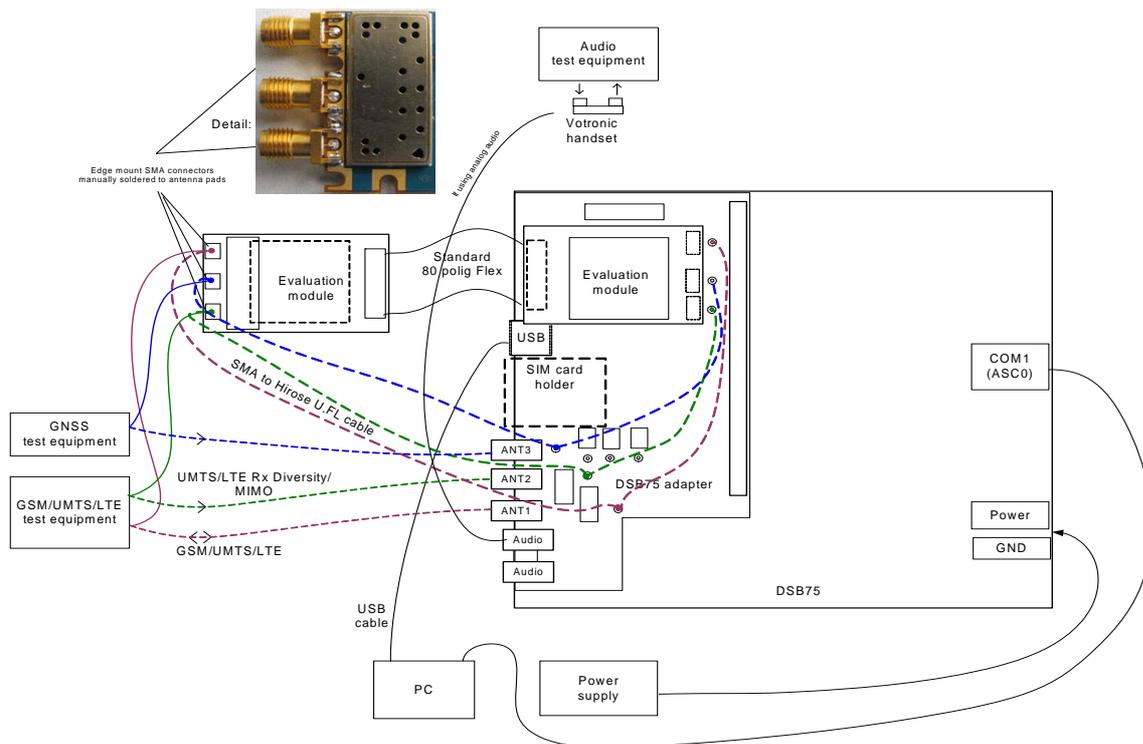


Figure 47: Reference equipment for type approval

9.2 Compliance with FCC and IC Rules and Regulations

The Equipment Authorization Certification for the Gemalto M2M modules reference application described in [Section 9.1](#) will be registered under the following identifiers:

- PLS8-X:
FCC Identifier QIPPLS8-X
Industry Canada Certification Number: 7830A-PLS8X
Granted to Gemalto M2M GmbH
- PLS8-V:
FCC Identifier QIPPLS8-V
Industry Canada Certification Number: 7830A-PLS8V
Granted to Gemalto M2M GmbH

Manufacturers of mobile or fixed devices incorporating PLS8-X/PLS8-V modules are authorized to use the FCC Grants and Industry Canada Certificates of the PLS8-X/PLS8-V modules for their own final products according to the conditions referenced in these documents. In this case, the FCC label of the module shall be visible from the outside, or the host device shall bear a second label stating "Contains FCC ID: QIPPLS8-X" or "Contains FCC ID: QIPPLS8-V" and accordingly "Contains IC: 7830A-PLS8X" or "Contains IC: 7830A-PLS8V". The integration is limited to fixed or mobile categorised host devices, where a separation distance between the antenna and any person of min. 20cm can be assured during normal operating conditions.

For mobile and fixed operation configurations the antenna gain, including cable loss, must not exceed the limits listed in the following [Table 30](#) for FCC and IC.

Table 30: Antenna gain limits for FCC and IC

| Operational band ¹ | FCC limit | IC limit | Unit |
|-----------------------------------------------------------------------------------------------------|-----------|----------|------|
| Maximum gain in lower operational bands with f < 1GHz (GSM850, WCDMA BdV, LTE Bd5 / Bd13 / Bd17) | 3.25 | 0.16 | dBi |
| Maximum gain in higher operational bands with f=1700MHz (WCDMA BdIV, LTE Bd4) | 5.5 | 5.5 | dBi |
| Maximum gain in higher operational bands with f=1900MHz (GSM1900, WCDMA BdII, LTE Band 2) | 2.51 | 2.51 | dBi |

¹. Please note that the listed frequency bands apply as follows:
 PLS8-X: LTE: Bd 2, 4, 5, 13 and 17; WCDMA Bd II, IV and V; GSM 850/1900MHz
 PLS8-V: LTE: Bd 2, 4 and 13

IMPORTANT:

Manufacturers of portable applications incorporating PLS8-X/PLS8-V modules are required to have their final product certified and apply for their own FCC Grant and Industry Canada Certificate related to the specific portable mobile. This is mandatory to meet the SAR requirements for portable mobiles (see [Section 1.4](#) for detail).

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules and with Industry Canada licence-exempt RSS standard(s). These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This Class B digital apparatus complies with Canadian ICES-003.

If Canadian approval is requested for devices incorporating PLS8-X/PLS8-V modules the above note will have to be provided in the English and French language in the final user documentation. Manufacturers/OEM Integrators must ensure that the final user documentation does not contain any information on how to install or remove the module from the final product.

10 Appendix

10.1 List of Parts and Accessories

Table 31: List of parts and accessories

| Description | Supplier | Ordering information |
|-------------------------------------------------------------|---------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| PLS8-X | Gemalto M2M | Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N3460-A300 Module label number: S30960-S3460-A300-1 ¹ Customer IMEI module Packaging unit (ordering) number: L30960-N3465-A300 Module label number: S30960-S3465-A300-1 ¹ |
| PLS8-X Evaluation Module | Gemalto M2M | Ordering number: L30960-N3461-A300 |
| PLS8-V | Gemalto M2M | Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N3470-A300 Module label number: S30960-S3470-A300-1 ¹ |
| PLS8-V Evaluation Module | Gemalto M2M | Ordering number: L30960-N3471-A300 |
| DSB75 Support Box | Gemalto M2M | Ordering number: L36880-N8811-A100 |
| DSB75 adapter for mounting the evaluation module | Gemalto M2M | Ordering number: L30960-N2301-A100 |
| Votronic handset for approval purposes | Votronic / Gemalto M2M | Gemalto M2M ordering number: L36880-N8301-A107 Votronic ordering number: HH-SI-30.3/V1.1/0 Votronic Entwicklungs- und Produktionsgesellschaft für elektronische Geräte mbH Saarbrücker Str. 8 66386 St. Ingbert Germany Phone: +49-(0)6 89 4 / 92 55-0 Fax: +49-(0)6 89 4 / 92 55-88 Email: contact@votronic.com |
| SIM card holder incl. push button ejector and slide-in tray | Molex | Ordering numbers: 91228 91236 Sales contacts are listed in Table 32 . |
| U.FL antenna connector | Hirose or Molex | Sales contacts are listed in Table 32 and Table 33 . |

¹. Note: At the discretion of Gemalto M2M, module label information can either be laser engraved on the module's shielding or be printed on a label adhered to the module's shielding.

10.1 List of Parts and Accessories

Table 32: Molex sales contacts (subject to change)

| | | |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------|
| Molex For further information please click: http://www.molex.com | Molex Deutschland GmbH Otto-Hahn-Str. 1b 69190 Walldorf Germany Phone: +49-6227-3091-0 Fax: +49-6227-3091-8100 Email: mxgermany@molex.com | American Headquarters Lisle, Illinois 60532 U.S.A. Phone: +1-800-78MOLEX Fax: +1-630-969-1352 |
| Molex China Distributors Beijing, Room 1311, Tower B, COFCO Plaza No. 8, Jian Guo Men Nei Street, 100005 Beijing P.R. China Phone: +86-10-6526-9628 Fax: +86-10-6526-9730 | Molex Singapore Pte. Ltd. 110, International Road Jurong Town, Singapore 629174 Phone: +65-6-268-6868 Fax: +65-6-265-6044 | Molex Japan Co. Ltd. 1-5-4 Fukami-Higashi, Yamato-City, Kanagawa, 242-8585 Japan Phone: +81-46-265-2325 Fax: +81-46-265-2365 |

Table 33: Hirose sales contacts (subject to change)

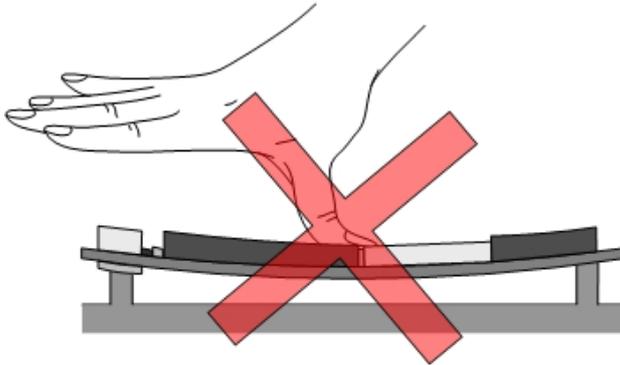
| | | |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Hirose Ltd. For further information please click: http://www.hirose.com | Hirose Electric (U.S.A.) Inc 2688 Westhills Court Simi Valley, CA 93065 U.S.A. Phone: +1-805-522-7958 Fax: +1-805-522-3217 | Hirose Electric Europe B.V. German Branch: Herzog-Carl-Strasse 4 73760 Ostfildern Germany Phone: +49-711-456002-1 Fax: +49-711-456002-299 Email: info@hirose.de |
| Hirose Electric Europe B.V. UK Branch: First Floor, St. Andrews House, Caldecotte Lake Business Park, Milton Keynes MK7 8LE Great Britain Phone: +44-1908-369060 Fax: +44-1908-369078 | Hirose Electric Co., Ltd. 5-23, Osaki 5 Chome, Shinagawa-Ku Tokyo 141 Japan Phone: +81-03-3491-9741 Fax: +81-03-3493-2933 | Hirose Electric Europe B.V. Hogehillweg 8 1101 CC Amsterdam Z-O Netherlands Phone: +31-20-6557-460 Fax: +31-20-6557-469 |

10.2 Mounting Advice Sheet

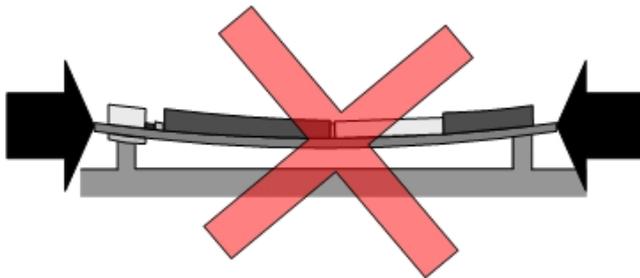
To prevent mechanical damage, be careful not to force, bend or twist the module. Be sure it is soldered flat against the host device (see also [Section 7.2](#)). The advice sheet on the next page shows a number of examples for the kind of bending that may lead to mechanical damage of the module (the module as part of an external application is integrated into a housing).

Mounting Advice

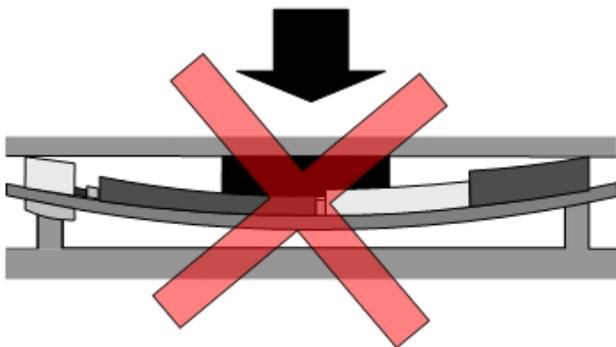
Do **NOT BEND** the Module



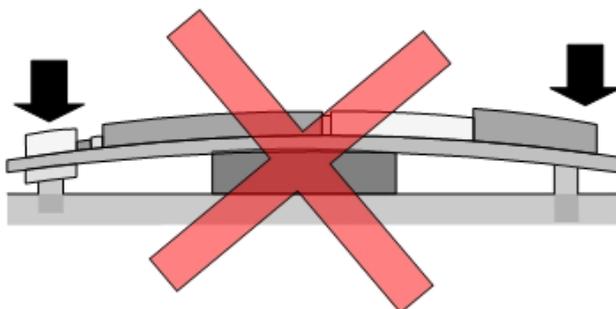
- By pressing from above



- By mounting under pressure



- By putting objects on top



- By putting objects below

About Gemalto

Gemalto (Euronext NL0000400653 GTO) is the world leader in digital security with 2014 annual revenues of €2.5 billion and blue-chip customers in over 180 countries. Our 14,000 employees operate out of 99 offices, 34 personalization and data centers, and 24 research and software development centers located in 46 countries.

We are at the heart of the rapidly evolving digital society. Billions of people worldwide increasingly want the freedom to communicate, travel, shop, bank, entertain and work - anytime, everywhere - in ways that are enjoyable and safe. Gemalto delivers on their expanding needs for personal mobile services, payment security, authenticated cloud access, identity and privacy protection, eHealthcare and eGovernment efficiency, convenient ticketing and dependable machine-to-machine (M2M) applications.

Gemalto develops secure embedded software and secure products which we design and personalize. Our platforms and services manage these secure products, the confidential data they contain and the trusted end-user services they enable. Our innovations enable our clients to offer trusted and convenient digital services to billions of individuals.

Gemalto thrives with the growing number of people using its solutions to interact with the digital and wireless world.

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Germany

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